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# HT32F49365/HT32F49395 Datasheet

**32-Bit Arm® Cortex®-M4 Microcontroller,  
up to 1024 KB Flash and 96+128 KB SRAM with ADC, DAC,  
USART, UART, SPI, I<sup>2</sup>S, I<sup>2</sup>C, GPTMR, PWM, Basic TMR,  
CRC, RTC, WDT, WWDT, DMA, SDIO, CAN, XMC, SPIM and USBFS**



Singel 3 | B-2550 Kontich | Belgium | Tel. +32 (0)3 458 30 33  
info@alcom.be | www.alcom.be  
Rivium 1e straat 52 | 2909 LE Capelle aan den IJssel | The Netherlands  
Tel. +31 (0)10 288 25 00 | info@alcom.nl | www.alcom.nl

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[www.holtek.com](http://www.holtek.com)

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# 1 General Descriptions

The HT32F49365/HT32F49395 devices are based on the high-performance Arm®Cortex®-M4 32-bit RISC core, operating at a frequency of up to 240 MHz. The Cortex®-M4 core features a Floating Point Unit (FPU) single precision which supports all Arm® single-precision data processing instructions and data types. It also implements a full set of DSP instructions and a Memory Protection Unit (MPU) which enhances application security.

The devices incorporate high-speed embedded memories (up to 1024 KBytes of internal Flash memory, 96 + 128 KBytes of SRAM), external SPI Flash (up to 16 MBytes addressing capability), and a wide range of enhanced GPIOs and peripherals connected to two APB buses. Any block of the embedded Flash memory can be protected by the “sLib” (security library), functioning as a security area with code-executable only.

The devices offer three 12-bit ADCs, two 12-bit DACs, eight general-purpose 16-bit timers plus two general-purpose 32-bit timers, and up to two PWM timers for motor control. They support standard and advanced communication interfaces including up to three I<sup>2</sup>Cs, four SPIs (all multiplexed as I<sup>2</sup>Ss), two SDIOs, eight USARTs/UARTs, an USBFS, and two CANs.

The HT32F49365/HT32F49395 devices operate in the -40 to +105 °C temperature range, from a 2.6 to 3.6 V power supply. A comprehensive set of power-saving mode allows the design of low-power application.

The HT32F49365/HT32F49395 are supplied in different package types. The entire HT32F49365/HT32F49395 series of devices are fully pin-to-pin, software and functionally compatible with each other, except that the configurations of peripherals are not completely identical, depending on the package types.

**arm** CORTEX

## 2 Feature

### Arm® Cortex®-M4 with FPU

The Arm® Cortex®-M4 processor is the latest generation of Arm® processors for embedded systems. It is a 32-bit RISC processor features exceptional code efficiency, outstanding computational performance and advanced response to interrupts. The processor supports a set of DSP instructions which enable efficient signal processing and complex algorithm execution. Its single precision FPU (Floating Point Unit) speeds up floating point calculation while avoiding saturation.

### Memory

#### Internal Flash Memory

Up to 1024 KBytes of embedded Flash is available for storing programs and data. Any part of the embedded Flash memory can be protected by the sLib (security library), a security area that is code-executable only but non-readable. “sLib” is a mechanism designed to protect the intelligence of solution vendors and facilitate the second-level development by customers.

The devices provide additional interface called SPIM (SPI Memory), which interfaces the external SPI Flash memory storing programs and data. With up to 16 MBytes addressing capability, SPIM can be used as an extensive Flash memory Bank 3. Besides, SPIM can be encrypted through the User System Data block to ensure data security, and the encryption range can be configured through the corresponding control register.

There is another 18-KByte boot code area in which the bootloader is stored.

An User System Data block is included, which is used to configure the hardware behaviors such as read/erase/write protection and watchdog self-enable. User System Data allows to set erase/write and read protection individually.

#### Memory Protection Unit (MPU)

The Memory Protection Unit (MPU) is used to manage the CPU accesses to memory to prevent one task to accidentally corrupt the memory or resources used by any other active task. This memory area consists of up to 8 protected areas that can in turn be divided up into 8 subareas. The protection area sizes are between 32 bytes and the entire 4 gigabytes of addressable memory.

The MPU is especially suited to the applications where some critical or certified code has to be protected against the misbehavior of other tasks. It is usually managed by an RTOS (real-time operating system).

#### Embedded SRAM

The devices offer up to 224 KBytes of embedded SRAM that is accessible (read/write) at CPU clock speed with zero wait states.

#### External Memory Controller (XMC)

An XMC is embedded in this series of devices. It has two Chip Select outputs supporting the following modes: multiplexed PSRAM/NOR and 16-bit/8-bit NAND memory.



Main features:

- Write buffer area
- Code execution from external memory of the multiplexed PSRAM/NOR

The XMC can be configured to interface with most graphic LCD controllers. It supports the Intel 8080 and Motorola 6800 modes.

## Interrupts

### Nested Vectored Interrupt Controller (NVIC)

This series of devices have embedded a nested vectored interrupt controller able to manage 16 priority levels and handle maskable interrupt channels plus the 16 interrupt lines of the Cortex®-M4 core. This hardware block provides flexible interrupt management features with minimal interrupt latency.

### External Interrupts (EXINT)

The external interrupt (EXINT), which is connected directly with NVIC, consists of 19 edge detector lines used to generate interrupt requests. Each line can be independently configured to select the trigger event (rising edge, falling edge, both) and can be masked independently. A pending register maintains the status of the interrupt requests. The external interrupt lines connects up to 16 GPIOs.

## Power Control (PWC)

### Power Supply Schemes

- $V_{DD} = 2.6 \sim 3.6$  V: an external power supply for GPIOs and the internal block such as regulator (LDO), provided externally through  $V_{DD}$  pins.
- $V_{DDA} = 2.6 \sim 3.6$  V: an external analog power supplies for ADCs and DACs.  $V_{DDA}$  and  $V_{SSA}$  must be the same voltage potential as  $V_{DD}$  and  $V_{SS}$ , respectively.
- $V_{BAT} = 1.8 \sim 3.6$  V: power supply for  $V_{BAT}$  domain through the external battery or super capacitor, or from  $V_{DD}$  when the external battery or super capacitor is not present.  $V_{BAT}$  (through power switch) supplies for RTC, external crystal 32.768 kHz (LEXT), and battery powered registers (BPR) when  $V_{DD}$  is not present.

### Reset and Power Voltage Monitoring (POR / LVR / PVM)

The devices have an integrated Power-On Reset (POR) / Low Voltage Reset (LVR) circuitry. It is always active, and allows proper operation starting from / down to 2.6 V. The devices remain in reset mode when  $V_{DD}$  is below a specified threshold ( $V_{LVR}$ ) without the need for an external reset circuit.

The devices feature an embedded Power Voltage Monitor (PVM) that monitors the  $V_{DD}$  power supply and compares it to the  $V_{PVM}$  threshold. An interrupt can be generated when  $V_{DD}$  drops below the  $V_{PVM}$  threshold and/or when  $V_{DD}$  rises above the  $V_{PVM}$  threshold. The PVM is enabled by software.

### Voltage Regulator (LDO)

The LDO has three operation modes: normal, low-power, and power-down.

- Normal mode: It is used in Run / Sleep mode and in the Deepsleep mode;
- Low-power mode: It can be used in the Deepsleep mode;
- Power-down mode: It is used in Standby mode where the LDO output is in high impedance and the kernel circuitry is powered down but the contents of the registers and SRAM are lost.

This LDO always operates in its normal mode after reset.

## Low-power Modes

The devices support three low-power modes:

### Sleep Mode

In Sleep mode, only the CPU is stopped. All peripherals continue to operate and can wake up the CPU when an interrupt/event occurs.

### Deepsleep Mode

Deepsleep mode achieves the lowest power consumption while retaining the contents of SRAM and registers. All clocks in the LDO domain are stopped, disabling the PLL, the HICK clock, and the HEXT crystal oscillator. The voltage regulator can also be put in normal or low-power mode.

The device can be woken up from Deepsleep mode by any of the EXINT line. The EXINT line source can be one of the 16 external lines, the PVM output, the RTC alarm, or the USBFS wakeup.

### Standby Mode

The Standby mode is used to achieve the lowest power consumption. The internal voltage regulator is switched off so that the entire LDO domain is powered off. The PLL, the HICK clock and the HEXT crystal oscillator are also switched off. After entering the Standby mode, SRAM and register contents are lost except for registers in the BPR domain and Standby circuitry.

The device leaves Standby mode when an external reset (NRST pin), a WDT reset, a rising edge on the WKUP pin, or an RTC alarm occurs.

Note: The RTC and the corresponding clock sources are not stopped by entering Deepsleep or Standby mode. The WDT depends on User System Data setting.

## Boot Modes

At startup, boot pins are used to select one of three boot options:

- Boot from the internal Flash memory. For this series of devices, user has an option to boot from any of two memory banks. By default, boot from Flash memory Bank 1 is selected. User can also choose to boot from Flash memory Bank 2 using the User System Data;
- Boot from boot code area;
- Boot from embedded SRAM.

The bootloader is stored in the boot code area. It is used to reprogram the Flash memory through USART1, USART2, or USBFS1. If SPIM\_IO0/1 pins are mapped on USBFS1 pins, the Flash memory Bank 3 cannot be reprogrammed through USBFS1. The following table presents the device pin configurations relative to Bootloader.

**Table 1. The Bootloader Supported Part Numbers and Pin Configurations**

| Interface | Part Number                              | Pin  |
|-----------|--|--|
| USART1    | All part numbers                         | PA9: USART1_TX<br>PA10: USART1_RX                      |
| USART2    | HT32F49395 (100LQFP)                     | PD5: USART2_TX (remapped)<br>PD6: USART2_RX (remapped) |
|           | Part numbers except HT32F49395 (100LQFP) | PA2: USART2_TX<br>PA3: USART2_RX                       |
| USBFS1    | All part numbers                         | PA11: USBFS1_D-<br>PA12: USBFS1_D+                     |

## Clocks

On reset, the internal 48 MHz clock (HICK), after being divided by 6 (that is 8 MHz), is selected as default CPU clock after any reset. The application can select an external 4 to 25 MHz clock (HEXT) as a system clock. This clock can be monitored for failure. If failure is detected, HEXT will be switched off and the system automatically switches back to the internal HICK. A software interrupt is generated. Similarly, the system takes the same action once HEXT fails when it is used as the source of PLL.

Several prescalers are available to allow the configuration of the AHB and the APB (APB1 and APB2) frequency. The maximum frequency of the AHB domain is 240 MHz. The maximum allowed frequency of the APB domains are 120 MHz.

The devices have embedded an automatic clock calibration (ACC) block, which calibrates the internal 48 MHz HICK clock, assuring the most precise accuracy of the HICK in the full range of the operating temperatures.

## General-Purpose Inputs / Outputs (GPIOs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down), or as multiple function. Most of the GPIO pins are shared with digital or analog multiple functions. All GPIOs are high current-capable.

The GPIO's configuration can be locked, if needed, in order to avoid spurious writing to the GPIO's registers by following a specific sequence.

## Remap Capability

This feature allows the use of a maximum number of peripherals in a given application. Indeed, multiple functions are available not only on the default pins but also on other specific pins onto which they are remappable. This has the advantage of making board design and port usage much more flexible.

For details refer to Table 6, which shows the list of remappable multiple functions and the pins onto which they can be remapped. See the user manual of this series of devices for software considerations.

## Direct Memory Access Controller (DMA)

The devices feature two 14-channel general-purpose DMAs (7 channels for DMA1 and 7 channels for DMA2), which are able to manage memory-to-memory, peripheral-to-memory, and memory-to-peripheral transfers. The two DMA controllers support circular buffer management, removing the need for user code intervention when the controller reaches the end of the buffer.

Each channel is connected to dedicated hardware DMA requests, with support software trigger on each channel. Configuration is made by software and transfer sizes between source and destination are independent.

The DMA can be used with the main peripherals: SPI, I<sup>2</sup>C, USART, advanced, general-purpose and basic timers TMRx, DAC, I<sup>2</sup>S, SDIO, and ADC.

## Timers (TMR)

The devices include two advanced timers, ten general-purpose timers, two basic timers and a SysTick timer.

The table below compares the features of the advanced, general-purpose and basic timers.

**Table 2. Timer Feature Comparison**

| Timer                      | Counter Resolution | Counter Type      | Prescaler Factor                | DMA Request Generation | Capture/ Compare Channels | Complementary Outputs |
|----------------------------|--------------------|-------------------|---------------------------------|------------------------|---------------------------|-----------------------|
| TMR1, TMR8                 | 16-bit             | Up, down, up/down | Any integer between 1 and 65536 | Yes                    | 4                         | Yes                   |
| TMR2, TMR5                 | 32-bit             | Up, down, up/down | Any integer between 1 and 65536 | Yes                    | 4                         | No                    |
| TMR3, TMR4                 | 16-bit             | Up, down, up/down | Any integer between 1 and 65536 | Yes                    | 4                         | No                    |
| TMR9, TMR12                | 16-bit             | Up                | Any integer between 1 and 65536 | No                     | 2                         | No                    |
| TMR10, TMR11, TMR13, TMR14 | 16-bit             | Up                | Any integer between 1 and 65536 | No                     | 1                         | No                    |
| TMR6, TMR7                 | 16-bit             | Up                | Any integer between 1 and 65536 | Yes                    | 0                         | No                    |

### Advanced Timers (TMR1 and TMR8)

The two advanced timers (TMR1 and TMR8) can each be seen as three-phase PWM generators multiplexed on 6 channels. They have complementary PWM outputs with programmable dead-time insertion. They can also be seen as a complete general-purpose timer. Their four independent channels can be used for:

- Input capture
- Output compare
- PWM generation (edge or center-aligned modes)
- One-cycle mode output

If configured as a standard 16-bit timer, it has the same features as the TMRx timer. If configured as the 16-bit PWM generator, it has full modulation capability (0 - 100 %).

In debug mode, the advanced timer counter can be frozen and the PWM outputs disabled to turn off any power switch driven by these outputs.

Many features are shared with those of the general-purpose TMR which have the same architecture. The advanced timer can therefore work together with the general-purpose timers via the timer link feature for synchronization or event chaining.

## General-Purpose Timers (TMRx)

There are 10 synchronizable general-purpose timers embedded in this series of devices.

### TMR2, TMR3, TMR4, and TMR5

There are 4 full-featured general-purpose timers: TMR2, TMR3, TMR4, and TMR5. The TMR2 and TMR5 timers are based on a 32-bit auto-reload up/down counter and a 16-bit prescaler. The TMR3 and TMR4 timers are based on a 16-bit auto-reload up/down counter and a 16-bit prescaler. They can offer four independent channels on the largest package. Each channel can be used for input capture/output compare, PWM or one-cycle mode output.

These general-purpose timers can work together with advanced timers via the timer link feature for synchronization or event chaining. In debug mode, their counter can be frozen. Any of these general-purpose timers can be used to generate PWM outputs. Each timer has individual DMA request.

These timers are capable of handling incremental quadrature encoder signals and the digital outputs coming from 1 to 3 hall-effect sensors.

### TMR9 and TMR12

TMR9 and TMR12 are based on a 16-bit auto-reload upcounter, a 16-bit prescaler, and two independent channels for input capture/output compare, PWM, or one-cycle mode output. They can be synchronized with the TMR2, TMR3, TMR4, and TMR5 full-featured general-purpose timers. They can also be used as simple time bases.

### TMR10, TMR11, TMR13, and TMR14

These timers are based on a 16-bit auto-reload upcounter, a 16-bit prescaler, and one independent channel for input capture/output compare, PWM, or one-cycle mode output. They can be synchronized with the TMR2, TMR3, TMR4, and TMR5 full-featured general-purpose timers. They can also be used as simple time bases.

## Basic Timers (TMR6 and TMR7)

These two timers are mainly used for DAC trigger generation. Each of them can also be used as a generic 16-bit time base.

## SysTick Timer

This timer is dedicated to real-time operating systems, but could also be used as a standard down counter. Its features include:

- A 24-bit down counter
- Auto-reload capability
- Maskable system interrupt generation when the counter reaches 0
- Programmable clock source

## Watchdog (WDT)

The watchdog consists of a 12-bit down counter and an 8-bit prescaler. It is clocked by an independent internal LICK clock. As it operates independently from the main clock, it can operate in DeepSleep and Standby modes. It can be used either as a watchdog to reset the device when an error occurs, or as a free running timer for application timeout management. It is self-enabled through the User System Data configuration. The counter can be frozen in debug mode.

## Window Watchdog (WWDT)

The window watchdog embeds a 7-bit down counter that can be set as free running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

## Real-Time Clock (RTC) and Battery Powered Registers (BPR)

The RTC and the battery powered registers (BPR) are supplied with a power switch that is powered either from  $V_{DD}$  when present or from the  $V_{BAT}$  pin. The battery powered registers are forty-two 16-bit registers used to store 84 bytes of user application data. RTC and BPR are not reset by a system or power reset, and they are not reset when the device wakes up from the Standby mode.

The real-time clock provides a continuous-running counter. The RTC provides clock calendar, and alarm interrupt and periodic interrupt functions. It is clocked by a 32.768 kHz external crystal (LEXT), the internal low-power clock (LICK), or the high-speed external clock (HEXT) divided by 128. The RTC can be calibrated using a divided-by-64 output of TAMPER pin to compensate for any natural quartz deviation. The RTC features a 32-bit programmable counter that allows long time measurement with the help of the Compare register. A 20-bit prescaler is used for the time base clock and is by default configured to generate a time base of 1 second from a clock at 32.768 kHz.

## Communication Interfaces

### Serial Peripheral Interfaces (SPI) / Inter-Integrated Sound Interfaces (I<sup>2</sup>S)

There are up to four SPI interfaces which are able to communicate at speeds of up to 50 Mbits/s in slave and master modes in full-duplex and half-duplex communication modes. The 3-bit prescaler generates eight master mode frequencies and the frame is configurable to 8 bits or 16 bits. The hardware CRC generation/verification supports basic SD Card/MMC/SDHC modes. All SPIs can be served by the DMA controller.

Four standard I<sup>2</sup>S interfaces (multiplexed with SPI) can be operated in master or slave mode in half-duplex mode, and I<sup>2</sup>S2 and I<sup>2</sup>S3 can also be operated in full-duplex mode. These interfaces can be configured as a 16/24/32-bit resolution, input or output channels. Audio sampling frequencies from 8 kHz up to 192 kHz are supported. When the I<sup>2</sup>S is configured in master mode, the master clock can be output to the external DAC/CODEC at 256 times the sampling frequency. All I<sup>2</sup>Ss can be served by the DMA controller.

### Universal Synchronous / Asynchronous Receiver Transmitters (USART)

The devices have embedded four universal synchronous/asynchronous receiver transmitters (USART1, USART2, USART3, and USART6) and four universal asynchronous receiver transmitters (UART4, UART5, UART7, and UART8).

These eight interfaces provide asynchronous communication, IrDA SIR ENDEC support, multiprocessor communication mode, single-wire half-duplex communication mode, and have LIN Master/Slave capability.

These eight interfaces are able to communicate at speeds of up to 7.5 Mbit/s.

USART1, USART2, and USART3 provide hardware management of the CTS and RTS signals. USART1, USART2, USART3, and USART6 provide Smart Card mode (ISO 7816 compliant) and SPI-like communication capability. All interfaces can be served by the DMA controller.

**Table 3. USART / UART Feature Comparison**

| USART / UART Function                 | USART1 | USART2 | USART3 | UART4 | UART5 | USART6 | UART7 | UART8 |
|---------------------------------------|--------|--------|--------|-------|-------|--------|-------|-------|
| Hardware flow control for modem       | Yes    | Yes    | Yes    | —     | —     | —      | —     | —     |
| Continuous communication using DMA    | Yes    | Yes    | Yes    | Yes   | Yes   | Yes    | Yes   | Yes   |
| Multiprocessor communication          | Yes    | Yes    | Yes    | Yes   | Yes   | Yes    | Yes   | Yes   |
| Synchronous mode                      | Yes    | Yes    | Yes    | —     | —     | Yes    | —     | —     |
| Smart card mode                       | Yes    | Yes    | Yes    | —     | —     | Yes    | —     | —     |
| Single-wire half-duplex communication | Yes    | Yes    | Yes    | Yes   | Yes   | Yes    | Yes   | Yes   |
| IrDA SIR ENDEC block                  | Yes    | Yes    | Yes    | Yes   | Yes   | Yes    | Yes   | Yes   |
| LIN mode                              | Yes    | Yes    | Yes    | Yes   | Yes   | Yes    | Yes   | Yes   |

### Inter-Integrated-Circuit Interfaces (I<sup>2</sup>C)

Up to three I<sup>2</sup>C bus interfaces can operate in multi-master and slave modes. They support standard mode (max. 100 kHz) and fast mode (max. 400 kHz). The I<sup>2</sup>C bus frequency can be increased up to 1 MHz.

They support 7/10-bit addressing mode and 7-bit dual addressing mode (as slave). A hardware CRC generation/verification is included.

They can be served by DMA and they support SMBus 2.0 / PMBus.

### Secure Digital Input / Output Interface (SDIO)

Two SD/SDIO/MMC host interfaces are available that supports MultiMediaCard System Specification Version 4.2 in three different data bus modes: 1-bit (default), 4-bit and 8-bit. The interface allows data transfer at up to 48 MHz in 8-bit mode, and is compliant with SD Memory Card Specifications Version 2.0.

Two different data bus modes supported in the SDIO Card Specification Version 2.0 are: 1-bit (default) and 4-bit.

The current version supports only one SD/SDIO/MMC4.2 card at any one time and a stack of MMC4.1 or previous.

In addition to SD/SDIO/MMC/eMMC, this interface is also fully compliant with the CE-ATA digital protocol Rev1.1.

### Controller Area Network (CAN)

Two CANs are compliant with specifications 2.0A and 2.0B (active) with a bit rate of up to 1 Mbit/s. It can receive and transmit standard frames with 11-bit identifiers as well as extended frames with 29-bit identifiers. Each CAN has three transmit mailboxes, two receive buffers with 3-level depth, and 14 scalable filter banks.

### Universal Serial Bus Full-Speed (USBFS)

The devices have embedded a USB device peripheral compatible with the USB full-speed 12 Mbit/s. It has software-configurable endpoint setting and suspend/resume support. The dedicated 48 MHz clock is generated from the internal main PLL or directly from the 48 MHz HICK.

## Cyclic Redundancy Check (CRC) Calculation Unit

The CRC (cyclic redundancy check) calculation unit is used to get a CRC code from a 32-bit data word and a fixed generator polynomial. Among other applications, CRC-based techniques are used to verify data transmission or storage integrity.

## Analog-to-Digital Converters (ADC)

Three 12-bit analog-to-digital converters are embedded into the devices and they share up to 16 external channels, performing conversions in single-shot or sequential modes. In sequence mode, automatic conversion is performed on a selected group of analog inputs.

Additional logic functions embedded in the ADC interface allow:

- Simultaneous sample and hold
- Interleaved sample and hold
- Single sample

The ADC can be served by the DMA controller.

The voltage monitoring feature allows very precise monitoring of the converted voltage of one, some or all selected channels. An interrupt is generated when the converted voltage is outside the programmed thresholds.

The events generated by the general-purpose timers (TMRx) and the advanced timers (TMR1 and TMR8) can be internally connected to the ADC regular trigger and injection trigger, respectively, to allow the application to synchronize A/D conversion and timers.

## Temperature Sensor ( $V_{TS}$ )

The temperature sensor has to generate a voltage  $V_{TS}$  that varies linearly with temperature. The temperature sensor is internally connected to the ADC1\_IN16 input channel which is used to convert the sensor output voltage into a digital value.

The offset of this line varies from chip to chip due to process variation. The internal temperature sensor is more suited to applications that detect temperature variations instead of absolute temperatures. If accurate temperature readings are needed, an external temperature sensor part should be used.

## Internal Reference Voltage ( $V_{INTRV}$ )

The internal reference voltage ( $V_{INTRV}$ ) provides a stable voltage source for ADC. The  $V_{INTRV}$  is internally connected to the ADC1\_IN17 input channel.

## Digital-to-Analog Converters (DAC)

The two 12-bit buffered DACs can be used to convert two-channel digital signals into two-channel analog voltage signal outputs.

The DAC has the following features:

- Two DAC converters with an output channel each
- 8-bit or 12-bit monotonic output
- Left- or right-alignment data in 12-bit mode
- Synchronized update capability
- Noise-wave generation



- Triangular-wave generation
- Dual DAC channel independent or simultaneous conversions
- DMA capability for each DAC
- External triggers for conversion
- Input voltage reference  $V_{REF+}$

Several DAC trigger inputs are available in the devices. DAC outputs can be triggered through the timer update outputs. The update output can also be connected to different DMA channels.

## Debug

### Serial Wire (SWD) / JTAG Port

The Arm® SWJ-DP Interface is embedded, consisting of a serial wire debug port and JTAG. It enables either a serial wire debug or a JTAG probe to be connected to the target for programming and debug operation. The JTAG TMS and TCK pins are shared respectively with SWDIO and SWCLK.

### Embedded Trace Macrocell (ETM™)

The Arm® Embedded Trace Macrocell (ETM™) provides a greater visibility of the instruction and data flow inside the CPU core by streaming compressed data at a very high rate from the devices through a small number of ETM pins to an external hardware trace port analyzer (TPA) device. The TPA is connected to a host computer using USB or any other high-speed channel. Real-time instruction and data flow activity can be recorded and then formatted for display on the host computer that runs the debugger software. TPA hardware is commercially available from common development tool vendors. It operates with third party debugger software tools.

# 3 Overview

## Device Information

**Table 4. Features and Peripheral List**

| Part Number                  | HT32F49365                           |                        | HT32F49395             |                        |                        |
|------------------------------|--------------------------------------|------------------------|------------------------|------------------------|------------------------|
| CPU frequency (MHz)          | 240                                  |                        |                        |                        |                        |
| Int. Flash <sup>(1)(2)</sup> | ZW (KBytes)                          | 128                    |                        | 128                    |                        |
|                              | NZW (KBytes)                         | 0                      |                        | 768                    |                        |
|                              | Configurable (KBytes)<br>(ZW or NZW) | 128                    |                        | 128                    |                        |
|                              | Total (KBytes)                       | 256                    |                        | 1024                   |                        |
| SRAM <sup>(2)</sup> (KBytes) | 96 + 128                             |                        |                        |                        |                        |
| Timers                       | Advanced                             | 2                      | 2                      | 2                      | 2                      |
|                              | 32-bit general-purpose               | 2                      | 2                      | 2                      | 2                      |
|                              | 16-bit general-purpose               | 8                      | 8                      | 8                      | 8                      |
|                              | Basic                                | 2                      | 2                      | 2                      | 2                      |
|                              | SysTick                              | 1                      | 1                      | 1                      | 1                      |
|                              | WDT                                  | 1                      | 1                      | 1                      | 1                      |
|                              | WWDT                                 | 1                      | 1                      | 1                      | 1                      |
|                              | RTC                                  | 1                      | 1                      | 1                      | 1                      |
| Communication                | I <sup>2</sup> C                     | 3                      | 3                      | 3                      | 3                      |
|                              | SPI/I <sup>2</sup> S                 | 4/4<br>(2 full-duplex) | 4/4<br>(2 full-duplex) | 4/4<br>(2 full-duplex) | 4/4<br>(2 full-duplex) |
|                              | USART + UART                         | 3 + 4 <sup>(3)</sup>   | 4 + 4                  | 3 + 4 <sup>(3)</sup>   | 4 + 4                  |
|                              | SDIO                                 | 1 <sup>(4)</sup>       | 2                      | 1 <sup>(4)</sup>       | 2                      |
|                              | USBFS device                         | 1                      | 1                      | 1                      | 1                      |
|                              | CAN                                  | 2                      | 2                      | 2                      | 2                      |
| Analog                       | Number of 12-bit ADC                 | 3                      |                        |                        |                        |
|                              | Number of channels                   | 10                     | 16                     | 10                     | 16                     |
|                              | Number of 12-bit DAC                 | 2                      |                        |                        |                        |
| XMC                          | —                                    | 1 <sup>(5)</sup>       | —                      | 1                      |                        |
| SPIM <sup>(6)</sup>          | 1 channel / up to 16 MBytes          |                        |                        |                        |                        |
| DMA                          | 14 channels                          |                        |                        |                        |                        |
| CRC                          | 1                                    |                        |                        |                        |                        |
| GPIO                         | 37                                   | 51/80                  | 37                     | 51/80                  |                        |
| EXINT                        | 16                                   |                        |                        |                        |                        |
| Operating voltage            | 2.6 to 3.6 V                         |                        |                        |                        |                        |

| Part Number           | HT32F49365                 |                              | HT32F49395                 |                              |
|-----------------------|----------------------------|------------------------------|----------------------------|------------------------------|
| Operating temperature | -40 to +105 °C             |                              |                            |                              |
| Package               | 48-pin QFN,<br>48-pin LQFP | 64-pin LQFP,<br>100-pin LQFP | 48-pin QFN,<br>48-pin LQFP | 64-pin LQFP,<br>100-pin LQFP |

Note: 1. ZW = zero wait-state, up to SYSCLK 240 MHz  
 NZW = non-zero wait-state

2. The internal Flash and SRAM sizes are configurable with User System Data. Take the HT32F49395 as an example, on which the Flash/SRAM can be configured into two options below:
  - ZW: 256 KBytes, NZW: 768 KBytes, SRAM: 96 KBytes;
  - ZW: 128 KBytes, NZW: 896 KBytes, SRAM: 224 KBytes.
3. For the 48-pin LQFP and 48-pin QFN packages, UART8 is not available and USART6 is used as UART for no CK pin.
4. For the 48-pin LQFP and 48-pin QFN packages, only SDIO2 exists and supports maximum 4-bit (D0~D3) mode.
5. For the 64-pin LQFP package, XMC only supports the LCD panel with 8-bit mode.
6. SPIM = External SPI Flash memory extension, for both program execution and data storage with encryption capability.

## Block Diagram

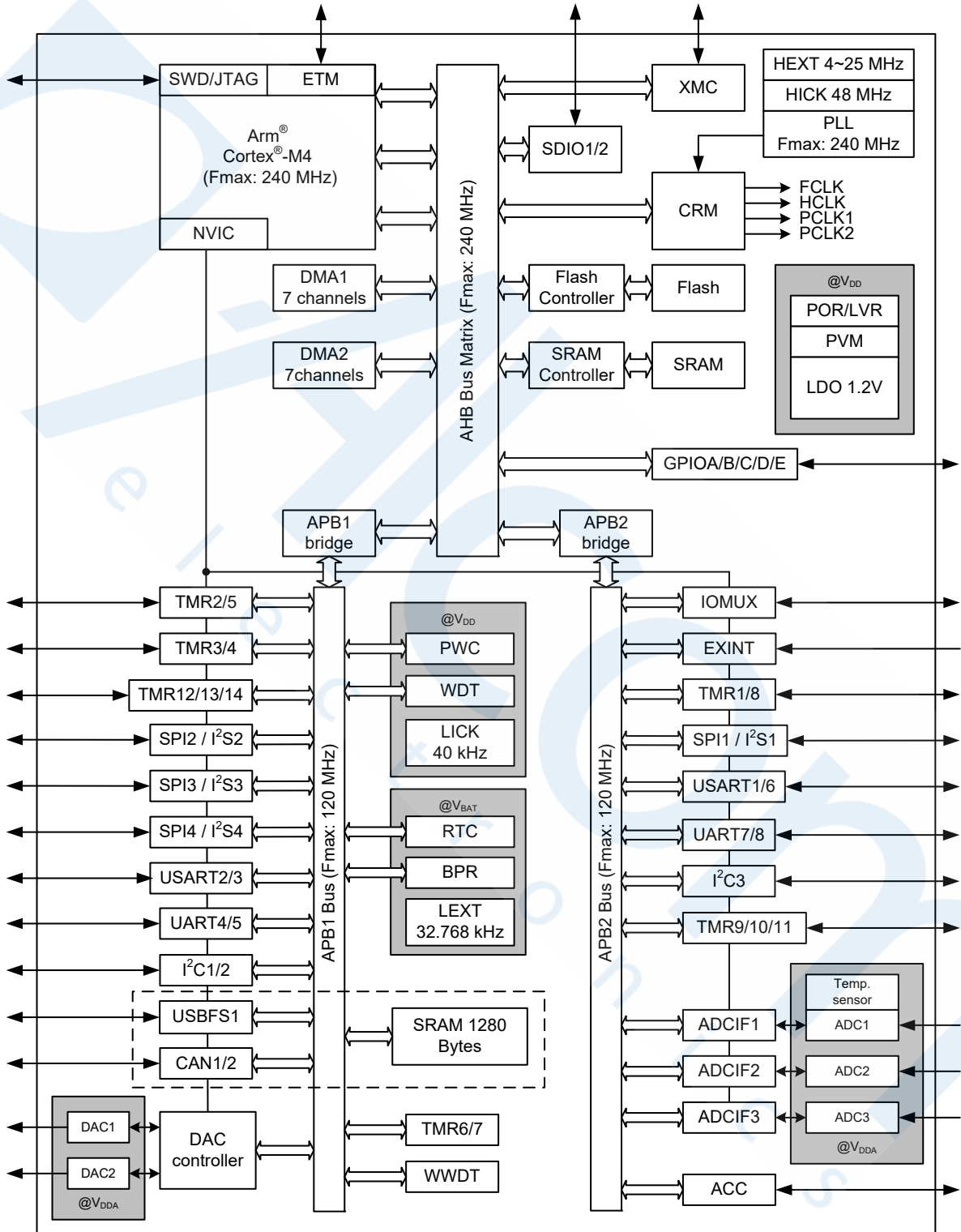


Figure 1. Block Diagram

## Memory Map

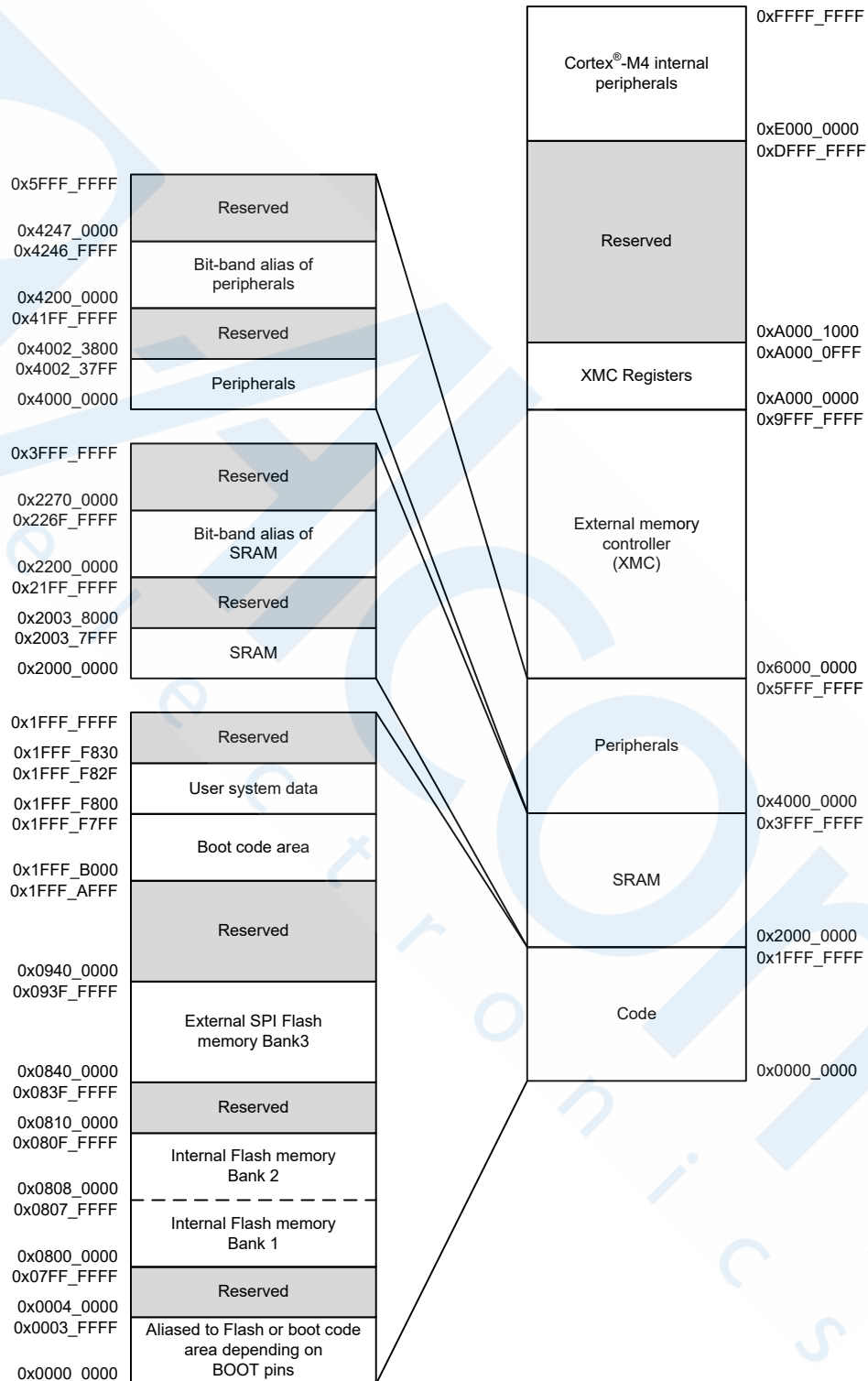


Figure 2. Memory Map

**Table 5. Peripheral Boundary Address**

| Bus                       | Boundary Address          | Peripherals                    |
|---------------------------|---------------------------|--------------------------------|
| AHB                       | 0xA000 1000 - 0xFFFF FFFF | Reserved                       |
|                           | 0xA000 0000 - 0xA000 0FFF | XMC_REG                        |
|                           | 0x6000 0000 - 0x9FFF FFFF | XMC_MEM                        |
|                           | 0x4002 8000 - 0x5FFF FFFF | Reserved                       |
|                           | 0x4002 3400 - 0x4002 7FFF | SDIO2                          |
|                           | 0x4002 3000 - 0x4002 33FF | CRC                            |
|                           | 0x4002 2000 - 0x4002 23FF | Flash memory interface (FLASH) |
|                           | 0x4002 1400 - 0x4002 1FFF | Reserved                       |
|                           | 0x4002 1000 - 0x4002 13FF | Clock reset manage (CRM)       |
|                           | 0x4002 0800 - 0x4002 0FFF | Reserved                       |
|                           | 0x4002 0400 - 0x4002 07FF | DMA2                           |
|                           | 0x4002 0000 - 0x4002 03FF | DMA1                           |
|                           | 0x4001 8400 - 0x4001 FFFF | Reserved                       |
|                           | 0x4001 8000 - 0x4001 83FF | SDIO                           |
| APB2                      | 0x4001 7400 - 0x4001 7FFF | Reserved                       |
|                           | 0x4001 7000 - 0x4001 73FF | I <sup>2</sup> S3EXT           |
|                           | 0x4001 6C00 - 0x4001 6FFF | I <sup>2</sup> S2EXT           |
|                           | 0x4001 6800 - 0x4001 6BFF | UART8                          |
|                           | 0x4001 6400 - 0x4001 67FF | UART7                          |
|                           | 0x4001 6000 - 0x4001 63FF | USART6                         |
|                           | 0x4001 5C00 - 0x4001 5FFF | I <sup>2</sup> C3              |
|                           | 0x4001 5800 - 0x4001 5BFF | ACC                            |
|                           | 0x4001 5400 - 0x4001 57FF | TMR11 timer                    |
|                           | 0x4001 5000 - 0x4001 53FF | TMR10 timer                    |
|                           | 0x4001 4C00 - 0x4001 4FFF | TMR9 timer                     |
|                           | 0x4001 4400 - 0x4001 4BFF | Reserved                       |
|                           | 0x4001 4000 - 0x4001 43FF | Reserved                       |
|                           | 0x4001 3C00 - 0x4001 3FFF | ADC3                           |
|                           | 0x4001 3800 - 0x4001 3BFF | USART1                         |
|                           | 0x4001 3400 - 0x4001 37FF | TMR8 timer                     |
|                           | 0x4001 3000 - 0x4001 33FF | SPI1/I <sup>2</sup> S1         |
|                           | 0x4001 2C00 - 0x4001 2FFF | TMR1 timer                     |
|                           | 0x4001 2800 - 0x4001 2BFF | ADC2                           |
|                           | 0x4001 2400 - 0x4001 27FF | ADC1                           |
|                           | 0x4001 2000 - 0x4001 23FF | Reserved                       |
|                           | 0x4001 1C00 - 0x4001 1FFF | Reserved                       |
|                           | 0x4001 1800 - 0x4001 1BFF | GPIO port E                    |
|                           | 0x4001 1400 - 0x4001 17FF | GPIO port D                    |
| 0x4001 1000 - 0x4001 13FF | GPIO port C               |                                |

| Bus  | Boundary Address          | Peripherals                            |
|------|---------------------------|--|
| APB2 | 0X4001 0C00 - 0x4001 0FFF | GPIO port B                            |
|      | 0x4001 0800 - 0x4001 0BFF | GPIO port A                            |
|      | 0x4001 0400 - 0x4001 07FF | EXINT                                  |
|      | 0x4001 0000 - 0x4001 03FF | IOMUX                                  |
| APB1 | 0x4000 8400 - 0x4000 FFFF | Reserved                               |
|      | 0x4000 7800 - 0x4000 83FF | USBFS 1280 bytes buffer <sup>(1)</sup> |
|      | 0x4000 7400 - 0x4000 77FF | DAC                                    |
|      | 0x4000 7000 - 0x4000 73FF | Power control (PWC)                    |
|      | 0x4000 6C00 - 0x4000 6FFF | Backup registers (BPR)                 |
|      | 0x4000 6800 - 0x4000 6BFF | CAN2                                   |
|      | 0x4000 6400 - 0x4000 67FF | CAN1                                   |
|      | 0x4000 6000 - 0x4000 63FF | USBFS 512 bytes buffer <sup>(1)</sup>  |
|      | 0x4000 5C00 - 0x4000 5FFF | USBFS                                  |
|      | 0x4000 5800 - 0x4000 5BFF | I <sup>2</sup> C2                      |
|      | 0x4000 5400 - 0x4000 57FF | I <sup>2</sup> C1                      |
|      | 0x4000 5000 - 0x4000 53FF | UART5                                  |
|      | 0x4000 4C00 - 0x4000 4FFF | UART4                                  |
|      | 0x4000 4800 - 0x4000 4BFF | USART3                                 |
|      | 0x4000 4400 - 0x4000 47FF | USART2                                 |
|      | 0x4000 4000 - 0x4000 43FF | SPI4/I <sup>2</sup> S4                 |
|      | 0x4000 3C00 - 0x4000 3FFF | SPI3/I <sup>2</sup> S3                 |
|      | 0x4000 3800 - 0x4000 3BFF | SPI2/I <sup>2</sup> S2                 |
|      | 0x4000 3400 - 0x4000 37FF | Reserved                               |
|      | 0x4000 3000 - 0x4000 33FF | Watchdog timer (WDT)                   |
|      | 0x4000 2C00 - 0x4000 2FFF | Window watchdog timer (WWDT)           |
|      | 0x4000 2800 - 0x4000 2BFF | RTC                                    |
|      | 0x4000 2400 - 0x4000 27FF | Reserved                               |
|      | 0x4000 2000 - 0x4000 23FF | TMR14 timer                            |
|      | 0x4000 1C00 - 0x4000 1FFF | TMR13 timer                            |
|      | 0x4000 1800 - 0x4000 1BFF | TMR12 timer                            |
|      | 0x4000 1400 - 0x4000 17FF | TMR7 timer                             |
|      | 0x4000 1000 - 0x4000 13FF | TMR6 timer                             |
|      | 0x4000 0C00 - 0x4000 0FFF | TMR5 timer                             |
|      | 0x4000 0800 - 0x4000 0BFF | TMR4 timer                             |
|      | 0x4000 0400 - 0x4000 07FF | TMR3 timer                             |
|      | 0x4000 0000 - 0x4000 03FF | TMR2 timer                             |

Note: When USBBUFS = 0, USBFS buffer size is 512 bytes, its address is 0x4000 6000 ~ 0x4000 63FF. When USBBUFS = 1, USBFS buffer size is 768 ~ 1280 bytes, its address is 0x4000 7800 ~ 0x4000 83FF. If both CAN1 and CAN2 are not enabled, the maximum USBFS buffer can be set to 1280 bytes; If any one of them is enabled, the maximum USBFS buffer can be up to 1024 bytes; If both are enabled, the maximum USB buffer can be set to 768 bytes.

## Clock Structure

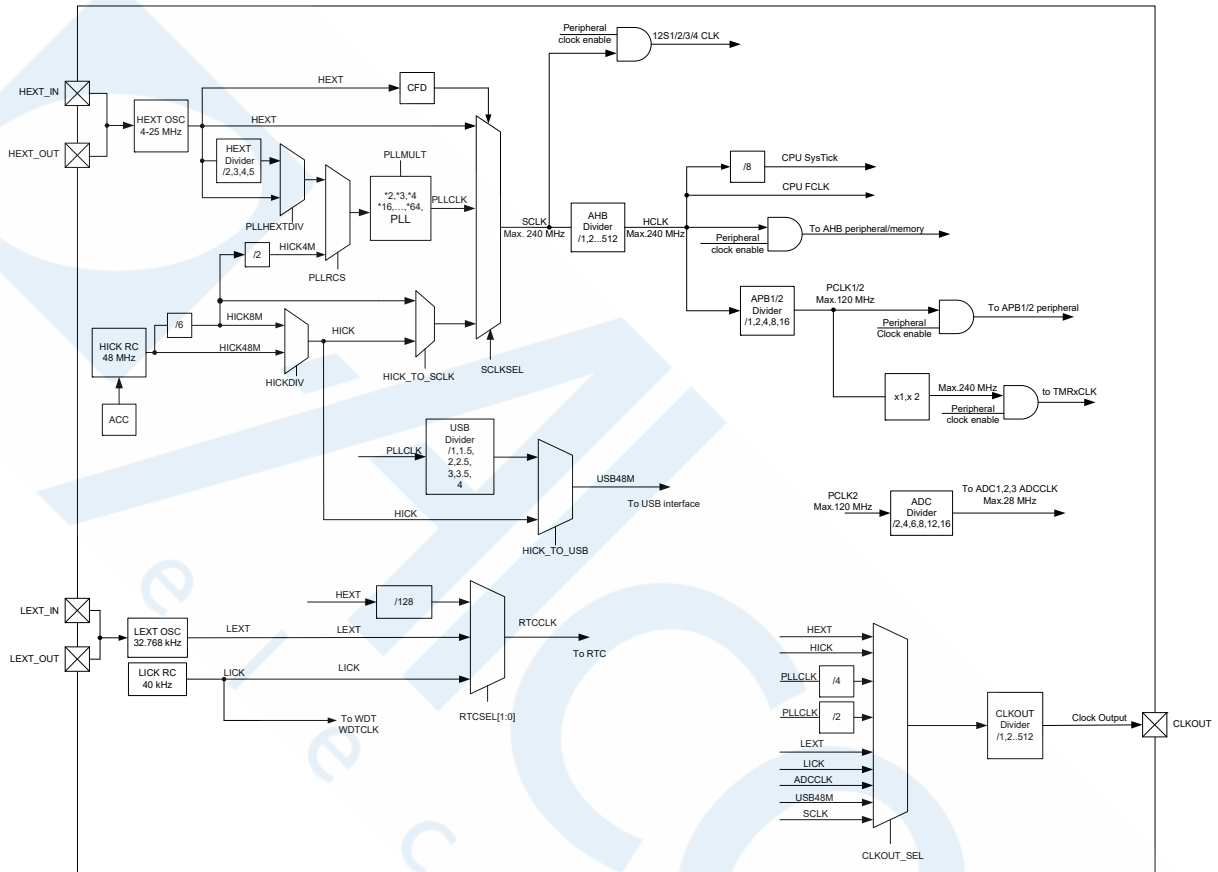


Figure 3. Clock Structure



# 4 Pin Assignment

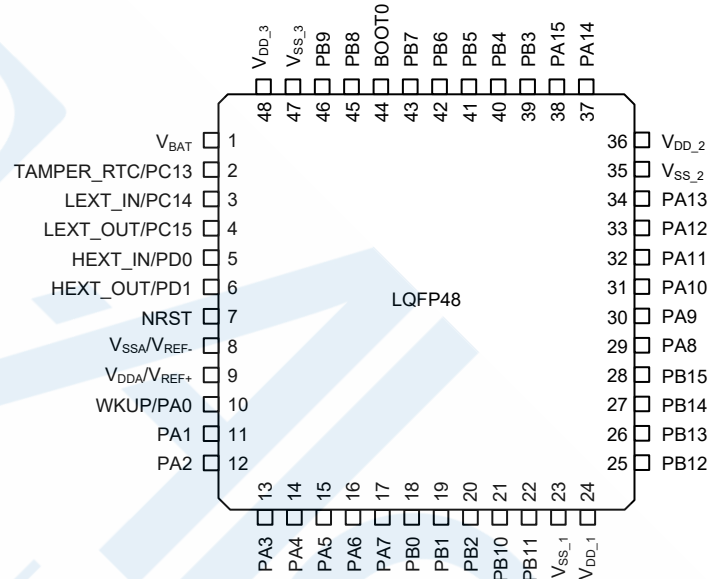


Figure 4. 48-pin LQFP Pin Assignment

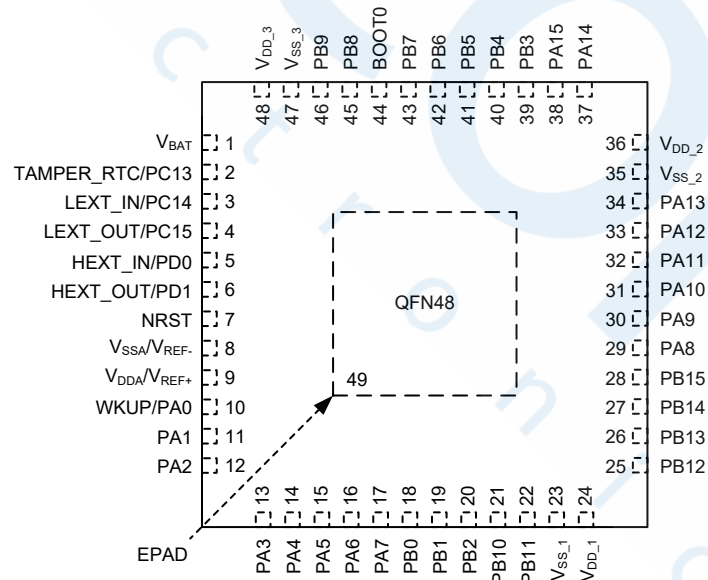


Figure 5. 48-pin QFN Pin Assignment

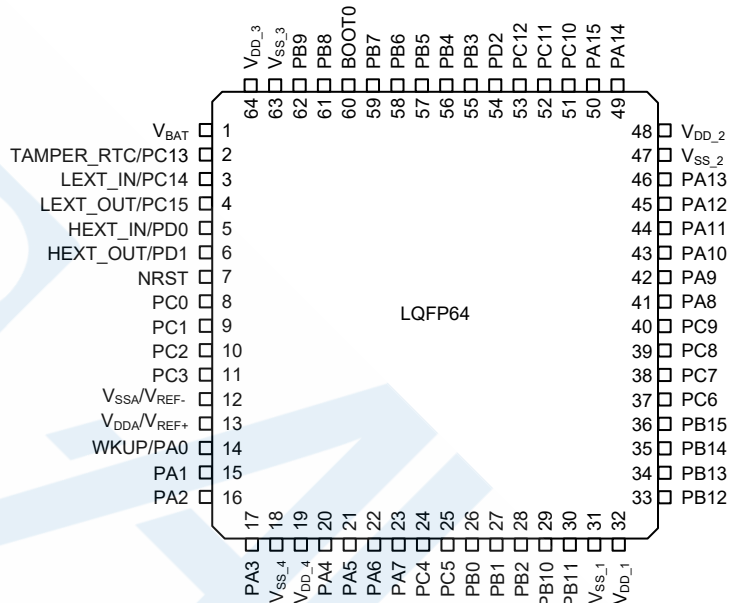


Figure 6. 64-pin LQFP Pin Assignment

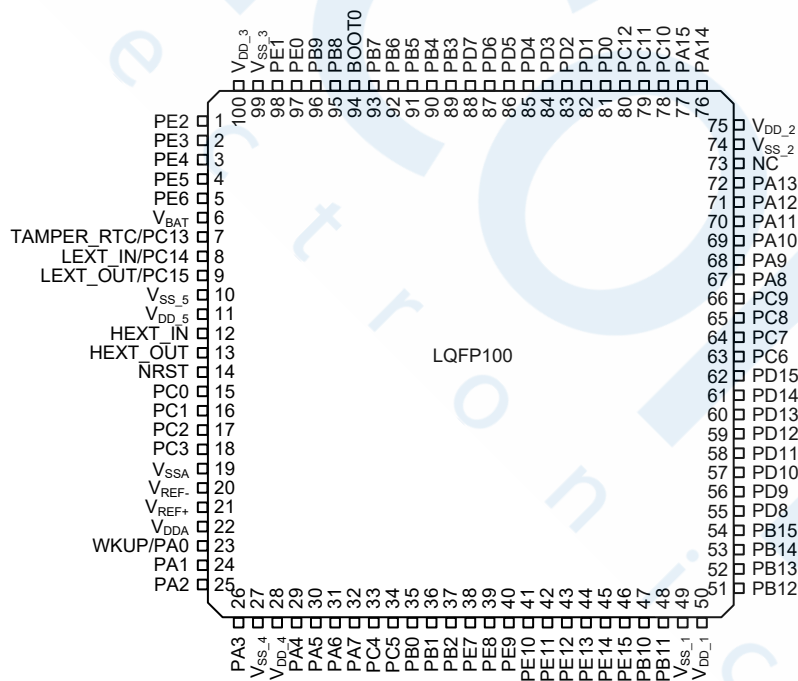


Figure 7. 100-pin LQFP Pin Assignment

The table below is the pin definition of the HT32F49365/HT32F49395. “—” presents there is no such pinout on the related package. The multi-functions list follows priority from high to low. In principle, the analog signals have priority over the digital signals, and the digital output signals have priority over the digital input signals.

**Table 6. Pin Definitions**

| Pin Number      |            |             | Pin Name                             | Type <sup>(1)</sup> | IO Level <sup>(2)</sup> | Main Function <sup>(3)</sup>         | Multi-Functions <sup>(4)</sup>  |                    |
|-----------------|------------|-------------|--------------------------------------|---------------------|-------------------------|--------------------------------------|---|--------------------|
| 48LQFP<br>48QFN | 64<br>LQFP | 100<br>LQFP |                                      |                     |                         |                                      | Default   | Remap              |
| —               | —          | 1           | PE2                                  | I/O                 | FT                      | PE2                                  | SPI4_SCK <sup>(7)</sup> / I2S4_CK <sup>(7)</sup> / XMC_A23 / TRACECK  | —                  |
| —               | —          | 2           | PE3                                  | I/O                 | FT                      | PE3                                  | XMC_A19 / TRACED0   | —                  |
| —               | —          | 3           | PE4                                  | I/O                 | FT                      | PE4                                  | SPI4_CS <sup>(7)</sup> / I2S4_WS <sup>(7)</sup> / XMC_A20 / TRACED1   | —                  |
| —               | —          | 4           | PE5                                  | I/O                 | FT                      | PE5                                  | SPI4_MISO <sup>(7)</sup> / XMC_A21 / TRACED2  | TMR9_CH1           |
| —               | —          | 5           | PE6                                  | I/O                 | FT                      | PE6                                  | SPI4_MOSI <sup>(7)</sup> / I2S4_SD <sup>(7)</sup> / XMC_A22 / TRACED3   | TMR9_CH2           |
| 1               | 1          | 6           | V <sub>BAT</sub>                     | S                   | —                       | V <sub>BAT</sub>                     | —   | —                  |
| 2               | 2          | 7           | TAMPER_RTC / PC13 <sup>(5)</sup>     | I/O                 | TC                      | PC13 <sup>(6)</sup>                  | TAMPER_RTC  | —                  |
| 3               | 3          | 8           | LEXT_IN / PC14 <sup>(5)</sup>        | I/O                 | TC                      | PC14 <sup>(6)</sup>                  | LEXT_IN   | —                  |
| 4               | 4          | 9           | LEXT_OUT / PC15 <sup>(5)</sup>       | I/O                 | TC                      | PC15 <sup>(6)</sup>                  | LEXT_OUT  | —                  |
| —               | —          | 10          | V <sub>SS,5</sub>                    | S                   | —                       | V <sub>SS,5</sub>                    | —   | —                  |
| —               | —          | 11          | V <sub>DD,5</sub>                    | S                   | —                       | V <sub>DD,5</sub>                    | —   | —                  |
| —               | —          | 12          | HEXT_IN                              | I                   | —                       | HEXT_IN                              | —   | —                  |
| —               | —          | 13          | HEXT_OUT                             | O                   | —                       | HEXT_OUT                             | —   | —                  |
| 5               | 5          | —           | HEXT_IN / PD0 <sup>(8)</sup>         | I/O                 | TC                      | HEXT_IN                              | —   | PD0 <sup>(8)</sup> |
| 6               | 6          | —           | HEXT_OUT / PD1 <sup>(8)</sup>        | I/O                 | TC                      | HEXT_OUT                             | —   | PD1 <sup>(8)</sup> |
| 7               | 7          | 14          | NRST                                 | I/O                 | —                       | NRST                                 | —   | —                  |
| —               | 8          | 15          | PC0                                  | I/O                 | FTa                     | PC0                                  | ADC123_IN10 / SDIO2_D0 <sup>(7)</sup>   | —                  |
| —               | 9          | 16          | PC1                                  | I/O                 | FTa                     | PC1                                  | ADC123_IN11 / SDIO2_D1 <sup>(7)</sup>   | —                  |
| —               | 10         | 17          | PC2                                  | I/O                 | FTa                     | PC2                                  | ADC123_IN12 / SDIO2_D2 <sup>(7)</sup>   | UART8_TX / XMC_NWE |
| —               | 11         | 18          | PC3                                  | I/O                 | FTa                     | PC3                                  | ADC123_IN13 / SDIO2_D3 <sup>(7)</sup> / XMC_A0  | UART8_RX           |
| —               | —          | 19          | V <sub>SSA</sub>                     | S                   | —                       | V <sub>SSA</sub>                     | —   | —                  |
| —               | —          | 20          | V <sub>REF-</sub>                    | S                   | —                       | V <sub>REF-</sub>                    | —   | —                  |
| 8               | 12         | —           | V <sub>SSA</sub> / V <sub>REF-</sub> | S                   | —                       | V <sub>SSA</sub> / V <sub>REF-</sub> | —   | —                  |
| —               | —          | 21          | V <sub>REF+</sub>                    | S                   | —                       | V <sub>REF+</sub>                    | —   | —                  |
| —               | —          | 22          | V <sub>DDA</sub>                     | S                   | —                       | V <sub>DDA</sub>                     | —   | —                  |
| 9               | 13         | —           | V <sub>DDA</sub> / V <sub>REF+</sub> | S                   | —                       | V <sub>DDA</sub> / V <sub>REF+</sub> | —   | —                  |
| 10              | 14         | 23          | WKUP / PA0                           | I/O                 | TC                      | PA0                                  | ADC123_IN0 / WKUP / USART2_CTS <sup>(7)</sup> / TMR2_CH1 <sup>(7)</sup> / TMR2_EXT <sup>(7)</sup> / TMR5_CH1 / TMR8_EXT | UART4_TX           |
| 11              | 15         | 24          | PA1                                  | I/O                 | FTa                     | PA1                                  | ADC123_IN1 / USART2_RTS <sup>(7)</sup> / TMR2_CH2 <sup>(7)</sup> / TMR5_CH2   | UART4_RX           |
| 12              | 16         | 25          | PA2                                  | I/O                 | FTa                     | PA2                                  | ADC123_IN2 / USART2_TX <sup>(7)</sup> / TMR2_CH3 <sup>(7)</sup> / TMR5_CH3 / TMR9_CH1 <sup>(7)</sup>                    | SDIO2_CK / XMC_D4  |

| Pin Number      |            |             | Pin Name          | Type <sup>(1)</sup> | IO Level <sup>(2)</sup> | Main Function <sup>(3)</sup> | Multi-Functions <sup>(4)</sup>   |   |
|-----------------|------------|-------------|-------------------|---------------------|-------------------------|------------------------------|--|---|
| 48LQFP<br>48QFN | 64<br>LQFP | 100<br>LQFP |                   |                     |                         |                              | Default  | Remap   |
| 13              | 17         | 26          | PA3               | I/O                 | FTa                     | PA3                          | ADC123_IN3 / USART2_RX <sup>(7)</sup> / TMR2_CH4 <sup>(7)</sup> / TMR5_CH4 / TMR9_CH2 <sup>(7)</sup>                       | I2S2_MCK / SDIO2_CMD / XMC_D5                     |
| —               | 18         | 27          | V <sub>SS,4</sub> | S                   | —                       | V <sub>SS,4</sub>            | —  | —   |
| —               | 19         | 28          | V <sub>DD,4</sub> | S                   | —                       | V <sub>DD,4</sub>            | —  | —   |
| 14              | 20         | 29          | PA4               | I/O                 | FTa                     | PA4                          | DAC1_OUT / ADC12_IN4 / USART2_CK <sup>(7)</sup> / SPI1_CS <sup>(7)</sup> / I2S1_WS <sup>(7)</sup> / SDIO2_D4               | USART6_TX / SPI3_CS / I2S3_WS / SDIO2_D0 / XMC_D6 |
| 15              | 21         | 30          | PA5               | I/O                 | FTa                     | PA5                          | DAC2_OUT / ADC12_IN5 / SPI1_SCK <sup>(7)</sup> / I2S1_CK <sup>(7)</sup> / SDIO2_D5   | USART6_RX / SDIO2_D1 / XMC_D7                     |
| 16              | 22         | 31          | PA6               | I/O                 | FTa                     | PA6                          | ADC12_IN6 / SPI1_MISO <sup>(7)</sup> / SDIO2_D6 / TMR3_CH1 <sup>(7)</sup> / TMR8_BRK / TMR13_CH1                           | I2S2_MCK / SDIO2_D2 / TMR1_BRK                    |
| 17              | 23         | 32          | PA7               | I/O                 | FTa                     | PA7                          | ADC12_IN7 / SPI1_MOSI <sup>(7)</sup> / I2S1_SD <sup>(7)</sup> / SDIO2_D7 / TMR3_CH2 <sup>(7)</sup> / TMR8_CH1C / TMR14_CH1 | SDIO2_D3 / TMR1_CH1C                              |
| —               | 24         | 33          | PC4               | I/O                 | FTa                     | PC4                          | ADC12_IN14 / SDIO2_CK <sup>(7)</sup> / XMC_NE4   | —   |
| —               | 25         | 34          | PC5               | I/O                 | FTa                     | PC5                          | ADC12_IN15 / SDIO2_CMD <sup>(7)</sup>  | XMC_NOE   |
| 18              | 26         | 35          | PB0               | I/O                 | FTa                     | PB0                          | ADC12_IN8 / I2S1_MCK <sup>(7)</sup> / TMR3_CH3 <sup>(7)</sup> / TMR8_CH2C  | TMR1_CH2C   |
| 19              | 27         | 36          | PB1               | I/O                 | FTa                     | PB1                          | ADC12_IN9 / SPIM_SCK / TMR3_CH4 <sup>(7)</sup> / TMR8_CH3C   | TMR1_CH3C   |
| 20              | 28         | 37          | PB2               | I/O                 | FT                      | PB2 / BOOT1 <sup>(9)</sup>   | —  | —   |
| —               | —          | 38          | PE7               | I/O                 | FT                      | PE7                          | UART7_RX <sup>(7)</sup> / XMC_D4 <sup>(7)</sup>  | TMR1_EXT  |
| —               | —          | 39          | PE8               | I/O                 | FT                      | PE8                          | UART7_TX <sup>(7)</sup> / XMC_D5 <sup>(7)</sup>  | TMR1_CH1C   |
| —               | —          | 40          | PE9               | I/O                 | FT                      | PE9                          | XMC_D6 <sup>(7)</sup>  | TMR1_CH1  |
| —               | —          | 41          | PE10              | I/O                 | FT                      | PE10                         | XMC_D7 <sup>(7)</sup>  | TMR1_CH2C   |
| —               | —          | 42          | PE11              | I/O                 | FT                      | PE11                         | XMC_D8   | SPI4_SCK / I2S4_CK / TMR1_CH2                     |
| —               | —          | 43          | PE12              | I/O                 | FT                      | PE12                         | XMC_D9   | SPI4_CS / I2S4_WS / TMR1_CH3C                     |
| —               | —          | 44          | PE13              | I/O                 | FT                      | PE13                         | XMC_D10  | SPI4_MISO / TMR1_CH3                              |
| —               | —          | 45          | PE14              | I/O                 | FT                      | PE14                         | XMC_D11  | SPI4_MOSI / I2S4_SD / TMR1_CH4                    |
| —               | —          | 46          | PE15              | I/O                 | FT                      | PE15                         | XMC_D12  | TMR1_BRK  |
| 21              | 29         | 47          | PB10              | I/O                 | FT                      | PB10                         | USART3_TX <sup>(7)</sup> / I2C2_SCL  | I2S3_MCK / SPIM_IO0 / TMR2_CH3                    |
| 22              | 30         | 48          | PB11              | I/O                 | FT                      | PB11                         | USART3_RX <sup>(7)</sup> / I2C2_SDA  | SPIM_IO1 / TMR2_CH4                               |
| 23              | 31         | 49          | V <sub>SS,1</sub> | S                   | —                       | V <sub>SS,1</sub>            | —  | —   |
| 24              | 32         | 50          | V <sub>DD,1</sub> | S                   | —                       | V <sub>DD,1</sub>            | —  | —   |
| 25              | 33         | 51          | PB12              | I/O                 | FT                      | PB12                         | USART3_CK <sup>(7)</sup> / CAN2_RX <sup>(7)</sup> / I2C2_SMBA / SPI2_CS / I2S2_WS / TMR1_BRK <sup>(7)</sup>                | XMC_D13   |
| 26              | 34         | 52          | PB13              | I/O                 | FT                      | PB13                         | USART3_CTS <sup>(7)</sup> / CAN2_TX <sup>(7)</sup> / SPI2_SCK / I2S2_CK / TMR1_CH1C <sup>(7)</sup>                         | —   |
| 27              | 35         | 53          | PB14              | I/O                 | FT                      | PB14                         | USART3_RTS <sup>(7)</sup> / SPI2_MISO / I2S2_SDEXT / TMR1_CH2C <sup>(7)</sup> / TMR12_CH1                                  | XMC_D0  |
| 28              | 36         | 54          | PB15              | I/O                 | FT                      | PB15                         | SPI2_MOSI / I2S2_SD / TMR1_CH3C <sup>(7)</sup> / TMR12_CH2   | —   |

| Pin Number      |            |             | Pin Name          | Type <sup>(1)</sup> | IO Level <sup>(2)</sup> | Main Function <sup>(3)</sup> | Multi-Functions <sup>(4)</sup>  |   |
|-----------------|------------|-------------|-------------------|---------------------|-------------------------|------------------------------|---|---|
| 48LQFP<br>48QFN | 64<br>LQFP | 100<br>LQFP |                   |                     |                         |                              | Default   | Remap   |
| —               | —          | 55          | PD8               | I/O                 | FT                      | PD8                          | XMC_D13 <sup>(7)</sup>  | USART3_TX   |
| —               | —          | 56          | PD9               | I/O                 | FT                      | PD9                          | XMC_D14   | USART3_RX   |
| —               | —          | 57          | PD10              | I/O                 | FT                      | PD10                         | XMC_D15   | USART3_CK   |
| —               | —          | 58          | PD11              | I/O                 | FT                      | PD11                         | XMC_A16   | USART3_CTS  |
| —               | —          | 59          | PD12              | I/O                 | FT                      | PD12                         | XMC_A17   | USART3_RTS /<br>TMR4_CH1                          |
| —               | —          | 60          | PD13              | I/O                 | FT                      | PD13                         | XMC_A18   | TMR4_CH2  |
| —               | —          | 61          | PD14              | I/O                 | FT                      | PD14                         | XMC_D0 <sup>(7)</sup>   | TMR4_CH3  |
| —               | —          | 62          | PD15              | I/O                 | FT                      | PD15                         | XMC_D1 <sup>(7)</sup>   | TMR4_CH4  |
| —               | 37         | 63          | PC6               | I/O                 | FT                      | PC6                          | USART6_TX <sup>(7)</sup> / I2S2_MCK <sup>(7)</sup> /<br>SDIO1_D6 / TMR8_CH1                               | XMC_D1 / TMR3_CH1                                 |
| —               | 38         | 64          | PC7               | I/O                 | FT                      | PC7                          | USART6_RX <sup>(7)</sup> / I2S3_MCK <sup>(7)</sup> /<br>SDIO1_D7 / TMR8_CH2                               | TMR3_CH2  |
| —               | 39         | 65          | PC8               | I/O                 | FT                      | PC8                          | USART6_CK / I2S4_MCK <sup>(7)</sup> /<br>SDIO1_D0 / TMR8_CH3  | TMR3_CH3  |
| —               | 40         | 66          | PC9               | I/O                 | FT                      | PC9                          | I2C3_SDA <sup>(7)</sup> / SDIO1_D1 /<br>TMR8_CH4  | TMR3_CH4  |
| 29              | 41         | 67          | PA8               | I/O                 | FT                      | PA8                          | CLKOUT / USART1_CK /<br>I2C3_SCL / USBFS_SOF /<br>SPIM_CS / TMR1_CH1 <sup>(7)</sup>                       | —   |
| 30              | 42         | 68          | PA9               | I/O                 | FT                      | PA9                          | USART1_TX <sup>(7)</sup> / I2C3_SMBA /<br>TMR1_CH2 <sup>(7)</sup>   | —   |
| 31              | 43         | 69          | PA10              | I/O                 | FT                      | PA10                         | USART1_RX <sup>(7)</sup> / TMR1_CH3 <sup>(7)</sup>  | I2S4_MCK  |
| 32              | 44         | 70          | PA11              | I/O                 | TC                      | PA11                         | USBFS1_D- / USART1_CTS /<br>CAN1_RX <sup>(7)</sup> / SPIM_IO0 <sup>(7)</sup> /<br>TMR1_CH4 <sup>(7)</sup> | —   |
| 33              | 45         | 71          | PA12              | I/O                 | TC                      | PA12                         | USBFS1_D+ / USART1_RTS /<br>CAN1_TX <sup>(7)</sup> / SPIM_IO1 <sup>(7)</sup> /<br>TMR1_EXT <sup>(7)</sup> | —   |
| 34              | 46         | 72          | PA13              | I/O                 | FT                      | JTMS-<br>SWDIO               | —   | PA13  |
| —               | —          | 73          |                   |                     |                         |                              | Not connected   |   |
| 35              | 47         | 74          | V <sub>SS_2</sub> | S                   | —                       | V <sub>SS_2</sub>            | —   | —   |
| 36              | 48         | 75          | V <sub>DD_2</sub> | S                   | —                       | V <sub>DD_2</sub>            | —   | —   |
| 37              | 49         | 76          | PA14              | I/O                 | FT                      | JTCK-<br>SWCLK               | —   | PA14  |
| 38              | 50         | 77          | PA15              | I/O                 | FT                      | JTDI                         | SPI3_CS <sup>(7)</sup> / I2S3_WS <sup>(7)</sup>   | PA15 / SPI1_CS / I2S1_WS /<br>TMR2_CH1 / TMR2_EXT |
| —               | 51         | 78          | PC10              | I/O                 | FT                      | PC10                         | UART4_TX <sup>(7)</sup> / SDIO1_D2  | USART3_TX / SPI3_SCK /<br>I2S3_CK                 |
| —               | 52         | 79          | PC11              | I/O                 | FT                      | PC11                         | UART4_RX <sup>(7)</sup> / SDIO1_D3  | USART3_RX / SPI3_MISO /<br>I2S3_SDEXT / XMC_D2    |
| —               | 53         | 80          | PC12              | I/O                 | FT                      | PC12                         | UART5_TX <sup>(7)</sup> / SDIO1_CK  | USART3_CK / SPI3_MOSI /<br>I2S3_SD / XMC_D3       |
| —               | —          | 81          | PD0               | I/O                 | FT                      | PD0                          | XMC_D2 <sup>(7)</sup>   | CAN1_RX   |
| —               | —          | 82          | PD1               | I/O                 | FT                      | PD1                          | XMC_D3 <sup>(7)</sup>   | CAN1_TX   |
| —               | 54         | 83          | PD2               | I/O                 | FT                      | PD2                          | UART5_RX <sup>(7)</sup> / SDIO1_CMD /<br>TMR3_EXT   | XMC_NWE   |
| —               | —          | 84          | PD3               | I/O                 | FT                      | PD3                          | XMC_CLK   | USART2_CTS  |
| —               | —          | 85          | PD4               | I/O                 | FT                      | PD4                          | XMC_NOE <sup>(7)</sup>  | USART2_RTS  |
| —               | —          | 86          | PD5               | I/O                 | FT                      | PD5                          | XMC_NWE <sup>(7)</sup>  | USART2_TX   |
| —               | —          | 87          | PD6               | I/O                 | FT                      | PD6                          | XMC_NWAIT   | USART2_RX   |
| —               | —          | 88          | PD7               | I/O                 | FT                      | PD7                          | XMC_NE1 / XMC_NCE2  | USART2_CK   |

| Pin Number      |            |             | Pin Name          | Type <sup>(1)</sup> | IO Level <sup>(2)</sup> | Main Function <sup>(3)</sup> | Multi-Functions <sup>(4)</sup>   |  |
|-----------------|------------|-------------|-------------------|---------------------|-------------------------|------------------------------|--|--|
| 48LQFP<br>48QFN | 64<br>LQFP | 100<br>LQFP |                   |                     |                         |                              | Default  | Remap  |
| 39              | 55         | 89          | PB3               | I/O                 | FT                      | JTDO                         | SPI3_SCK <sup>(7)</sup> / I2S3_CK <sup>(7)</sup>                             | PB3 / UART7_RX / SPI1_SCK / I2S1_CK / SWO / TMR2_CH2 |
| 40              | 56         | 90          | PB4               | I/O                 | FT                      | NJTRST                       | SPI3_MISO <sup>(7)</sup> / I2S3_SDEXT <sup>(7)</sup>                         | PB4 / SPI1_MISO / I2C3_SDA / UART7_TX / TMR3_CH1     |
| 41              | 57         | 91          | PB5               | I/O                 | FT                      | PB5                          | SPI3_MOSI <sup>(7)</sup> / I2S3_SD <sup>(7)</sup> / I2C1_SMBA <sup>(7)</sup> | SPI1_MOSI / I2S1_SD / CAN2_RX / TMR3_CH2             |
| 42              | 58         | 92          | PB6               | I/O                 | FT                      | PB6                          | I2C1_SCL <sup>(7)</sup> / SPIM_IO3 / TMR4_CH1 <sup>(7)</sup>                 | USART1_TX / I2S1_MCK / SPI4_CS / I2S4_WS / CAN2_TX   |
| 43              | 59         | 93          | PB7               | I/O                 | FT                      | PB7                          | I2C1_SDA <sup>(7)</sup> / XMC_NADV / SPIM_IO2 / TMR4_CH2 <sup>(7)</sup>      | USART1_RX / SPI4_SCK / I2S4_CK                       |
| 44              | 60         | 94          | BOOT0             | I                   | —                       | BOOT0                        | —  | —  |
| 45              | 61         | 95          | PB8               | I/O                 | FT                      | PB8                          | SDIO1_D4 / TMR4_CH3 <sup>(7)</sup> / TMR10_CH1                               | UART5_RX / SPI4_MISO / I2C1_SCL / CAN1_RX            |
| 46              | 62         | 96          | PB9               | I/O                 | FT                      | PB9                          | SDIO1_D5 / TMR4_CH4 <sup>(7)</sup> / TMR11_CH1                               | UART5_TX / SPI4_MOSI / I2S4_SD / I2C1_SDA / CAN1_TX  |
| —               | —          | 97          | PE0               | I/O                 | FT                      | PE0                          | UART8_RX <sup>(7)</sup> / XMC_LB / TMR4_EXT                                  | —  |
| —               | —          | 98          | PE1               | I/O                 | FT                      | PE1                          | UART8_TX <sup>(7)</sup> / XMC_UB   | —  |
| 47              | 63         | 99          | V <sub>SS,3</sub> | S                   | —                       | V <sub>SS,3</sub>            | —  | —  |
| 48              | 64         | 100         | V <sub>DD,3</sub> | S                   | —                       | V <sub>DD,3</sub>            | —  | —  |
| -/49            | —          | —           | EPAD              | S                   | —                       | V <sub>SS</sub>              | —  | —  |

Note: 1. I = input, O = output, S = supply.

- TC = standard 3.3 V GPIO, FT = general 5 V-tolerant GPIO, FTa = 5 V-tolerant GPIO with analog functionalities. FTa pin is 5 V-tolerant when configured as input floating, input pull-up, or input pull-down mode. However, it cannot be 5 V-tolerant when configured as analog mode. Meanwhile, its input level should not higher than  $V_{DD} + 0.3 V$ .
- Function availability depends on the chosen device.
- If several peripherals share the same GPIO pin, to avoid conflict between these multiple functions only one peripheral should be enabled at a time through the peripheral clock enable bit (in the corresponding RCC peripheral clock enable register).
- PC13, PC14, and PC15 are supplied through the power switch. Since the switch only drives a limited amount of current (3 mA), the use of GPIOs PC13 to PC15 in output mode is limited not to be used as a current source (e.g. to drive an LED).
- Main function after the first battery powered domain power-up. Later on, it depends on the contents of the battery powered registers even after reset (because these registers are not reset by the main reset). For details on how to manage these GPIOs, refer to the battery powered domain and register description sections in the HT32F49365/HT32F49395 user manual.
- This multiple function can be remapped by software to some other port pins (if available on the used package). For more details, refer to the multi-function GPIO and debug configuration section in the HT32F49365/HT32F49395 user manual.
- For the 64-pin LQFP, 48-pin LQFP and 48-pin QFN package, the pins number 5 and 6 are configured as HEXT\_IN and HEXT\_OUT after reset, the functionality of PD0 and PD1 can be remapped by software on these pins. However, for the 100-pin LQFP package, PD0 and PD1 are available by default, so there is no need for remapping. For more details, refer to multi-function GPIO and debug configuration section in the user manual of this series of devices.
- If the device boots from Flash and leaves PB2 not used, suggest to pull PB2/BOOT1 pin down to  $V_{SS}$ .

**Table 7. XMC Pin Definition**

| Pins | XMC                   |     |      | 64LQFP |
|------|-----------------------|-----|------|--------|
|      | Multiplexed PSRAM/NOR | LCD | NAND |        |
| PE2  | A23                   | A23 | —    | —      |
| PE3  | A19                   | A19 | —    | —      |
| PE4  | A20                   | A20 | —    | —      |
| PE5  | A21                   | A21 | —    | —      |
| PE6  | A22                   | A22 | —    | —      |
| PC2  | NWE                   | NWE | NWE  | Yes    |
| PC3  | —                     | A0  | —    | Yes    |
| PA2  | DA4                   | D4  | D4   | Yes    |
| PA3  | DA5                   | D5  | D5   | Yes    |
| PA4  | DA6                   | D6  | D6   | Yes    |
| PA5  | DA7                   | D7  | D7   | Yes    |
| PC4  | NE4                   | NE4 | —    | Yes    |
| PC5  | NOE                   | NOE | NOE  | Yes    |
| PE7  | DA4                   | D4  | D4   | —      |
| PE8  | DA5                   | D5  | D5   | —      |
| PE9  | DA6                   | D6  | D6   | —      |
| PE10 | DA7                   | D7  | D7   | —      |
| PE11 | DA8                   | D8  | D8   | —      |
| PE12 | DA9                   | D9  | D9   | —      |
| PE13 | DA10                  | D10 | D10  | —      |
| PE14 | DA11                  | D11 | D11  | —      |
| PE15 | DA12                  | D12 | D12  | —      |
| PB12 | DA13                  | D13 | D13  | Yes    |
| PB14 | DA0                   | D0  | D0   | Yes    |
| PD8  | DA13                  | D13 | D13  | —      |
| PD9  | DA14                  | D14 | D14  | —      |
| PD10 | DA15                  | D15 | D15  | —      |
| PD11 | A16                   | A16 | CLE  | —      |
| PD12 | A17                   | A17 | ALE  | —      |
| PD13 | A18                   | A18 | —    | —      |
| PD14 | DA0                   | D0  | D0   | —      |
| PD15 | DA1                   | D1  | D1   | —      |
| PC6  | DA1                   | D1  | D1   | Yes    |
| PC11 | DA2                   | D2  | D2   | Yes    |
| PC12 | DA3                   | D3  | D3   | Yes    |
| PD0  | DA2                   | D2  | D2   | —      |
| PD1  | DA3                   | D3  | D3   | —      |
| PD2  | NWE                   | NWE | NWE  | Yes    |
| PD3  | CLK                   | —   | —    | —      |

| Pins | XMC                   |     |       | 64LQFP |
|------|-----------------------|-----|-------|--------|
|      | Multiplexed PSRAM/NOR | LCD | NAND  |        |
| PD4  | NOE                   | NOE | NOE   | —      |
| PD5  | NWE                   | NWE | NWE   | —      |
| PD6  | NWAIT                 | —   | NWAIT | —      |
| PD7  | NE1                   | NE1 | NCE2  | —      |
| PB7  | NADV                  | —   | —     | Yes    |
| PE0  | LB                    | —   | —     | —      |
| PE1  | UB                    | —   | —     | —      |



# 5 Electrical Characteristics

## Parameter Conditions

### Minimum and Maximum Values

The minimum and maximum values are guaranteed in the worst conditions. Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production.

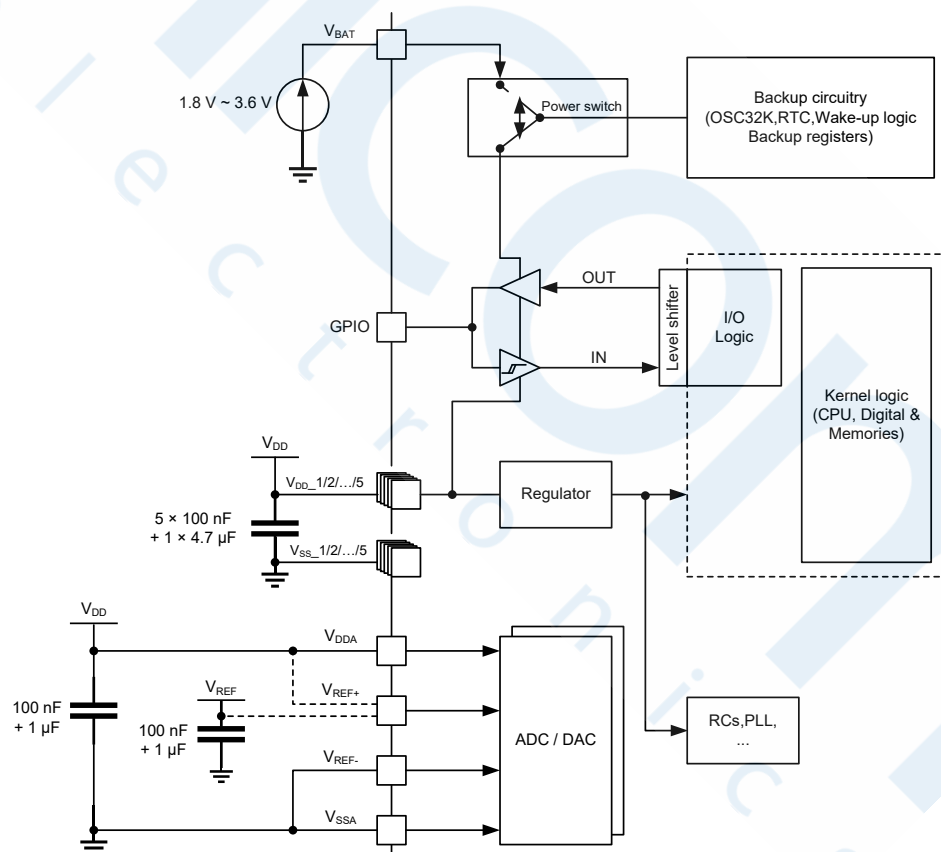
### Typical Values

Typical data are based on  $T_A = 25\text{ }^\circ\text{C}$ ,  $V_{DD} = 3.3\text{ V}$ .

### Typical Curves

All typical curves are given only as design guidelines and are not tested.

### Power Supply Scheme



**Figure 8. Power Supply Scheme**

Note: In this figure, the  $4.7\text{ }\mu\text{F}$  capacitor must be connected to  $V_{DD\_3}$ .

## Absolute Maximum Values

### Ratings

If stresses were out of the absolute maximum ratings listed in the following tables, it may cause permanent damage to the device. These are maximum stress ratings only that the device could bear, but the functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for an extended period of times may affect device reliability.

**Table 8. Voltage Characteristics**

| Symbol                 | Parameter  | Min.         | Max. | Unit |
|------------------------|--|--------------|------|------|
| $V_{DD} - V_{SS}$      | External Main Supply Voltage (including $V_{DDA}$ and $V_{DD}$ )                         | -0.3         | 4.0  | V    |
| $V_{IN}$               | Input Voltage on FT GPIO   | $V_{SS}-0.3$ | 6.0  |      |
|                        | Input Voltage on FTa GPIO (set as Input Floating, Input Pull-up or Input Pull-down Mode) |              |      |      |
|                        | Input Voltage on TC GPIO   | $V_{SS}-0.3$ | 4.0  |      |
|                        | Input Voltage on FTa GPIO (set as Analog Mode)   |              |      |      |
| $ \Delta V_{DD\_x} $   | Variations between Different $V_{DD}$ Power Pins   | —            | 50   | mV   |
| $ V_{SS\_x} - V_{SS} $ | Variations between All the Different Ground Pins   | —            | 50   |      |

**Table 9. Current Characteristics**

| Symbol    | Parameter  | Max. | Unit |
|-----------|--|------|------|
| $I_{VDD}$ | Total Current into $V_{DD}/V_{DDA}$ Power Lines (Source) | 150  | mA   |
| $I_{VSS}$ | Total Current out of $V_{SS}$ Ground Lines (Sink)        | 150  |      |
| $I_{IO}$  | Output Current Sunk by Any GPIO and Control Pin          | 25   |      |
|           | Output Current Source by Any GPIOs and Control Pin       | -25  |      |

**Table 10. Thermal Characteristics**

| Symbol    | Parameter                    | Value      | Unit |
|-----------|------------------------------|------------|------|
| $T_{STG}$ | Storage Temperature Range    | -60 ~ +150 | °C   |
| $T_J$     | Maximum Junction Temperature | 125        |      |

### Electrical Sensitivity

Based on three different tests (HBM, CDM, and LU) using specific measurement methods, the device is stressed in order to determine its performance in terms of electrical sensitivity.

### Electrostatic Discharge (ESD)

Electrostatic discharges are applied to the pins of each sample according to each pin combination. This test conforms to the JS-001-2017 / JS-002-2018 standard.

**Table 11. ESD Values**

| Symbol         | Parameter   | Conditions  | Class | Max. (Note) | Unit |
|----------------|---|---|-------|-------------|------|
| $V_{ESD(HBM)}$ | Electrostatic Discharge Voltage (Human Body Model)    | $T_A = +25\text{ °C}$ , conforming to JS-001-2017 | 3A    | 5000        | V    |
| $V_{ESD(CDM)}$ | Electrostatic Discharge Voltage (Charge Device Model) | $T_A = +25\text{ °C}$ , conforming to JS-002-2018 | III   | 1000        |      |

Note: Data based on characterization results only, not tested in production.

### Static Latch-up

Tests compliant with EIA/JESD78E IC latch-up standard are required to assess the latch-up performance:

- A supply overvoltage is applied to each power supply pin;
- A current injection is applied to each input, output and configurable GPIO pin.

**Table 12. Latch-up Values**

| Symbol | Parameter             | Conditions   | Level/Class         |
|--------|-----------------------|--|---------------------|
| LU     | Static Latch-up Class | T <sub>A</sub> = +105 °C,<br>conforming to EIA/JESD78E | II level A (200 mA) |

## General Operating Conditions

**Table 13. General Operating Conditions**

| Symbol             | Parameter                                     | Conditions                                    | Min.                            | Max. | Unit |     |
|--------------------|---|---|---------------------------------|------|------|-----|
| f <sub>HCLK</sub>  | Internal AHB Clock Frequency                  | Bank 3 not used                               | 3.1 V ≤ V <sub>DD</sub> ≤ 3.6 V | 0    | 240  | MHz |
|                    |   |   | 2.6 V ≤ V <sub>DD</sub> < 3.1 V | 0    | 180  |     |
|                    |   | Bank 3 used                                   | 3.1 V ≤ V <sub>DD</sub> ≤ 3.6 V | 0    | 180  |     |
|                    |   |   | 2.6 V ≤ V <sub>DD</sub> < 3.1 V | 0    | 160  |     |
| f <sub>PCLK1</sub> | Internal APB1 Clock Frequency                 | —   | 0                               | 120  | MHz  |     |
| f <sub>PCLK2</sub> | Internal APB2 Clock Frequency                 | —   | 0                               | 120  | MHz  |     |
| V <sub>DD</sub>    | Standard Operating Voltage                    | —   | 2.6                             | 3.6  | V    |     |
| V <sub>DDA</sub>   | Analog Operating Voltage                      | Must be the same potential as V <sub>DD</sub> | 2.6                             | 3.6  | V    |     |
| V <sub>BAT</sub>   | Backup Operating Voltage                      | —   | 1.8                             | 3.6  | V    |     |
| P <sub>D</sub>     | Power Dissipation:<br>T <sub>A</sub> = 105 °C | 100LQFP                                       | —                               | 326  | mW   |     |
|                    |   | 64LQFP  | —                               | 309  |      |     |
|                    |   | 48LQFP  | —                               | 290  |      |     |
|                    |   | 48QFN   | —                               | 662  |      |     |
| T <sub>A</sub>     | Ambient Temperature                           | —   | -40                             | 105  | °C   |     |

## Operating Conditions at Power-up / Power-down

**Table 14. Operating Conditions at Power-up / Power-down**

| Symbol           | Parameter                         | Conditions | Min. | Max.    | Unit |
|------------------|-----------------------------------|------------|------|---------|------|
| t <sub>VDD</sub> | V <sub>DD</sub> Rising Time Rate  | —          | 0    | ∞(Note) | ms/V |
|                  | V <sub>DD</sub> Falling Time Rate |            | 20   | ∞       | μs/V |

Note: If the V<sub>DD</sub> rising time rate is slower than 120 ms/V, the code should access the backup registers after V<sub>DD</sub> is higher than V<sub>POR</sub> + 0.1 V.

## Embedded Reset and Power Control Block Characteristics

Table 15. Embedded Reset and Power Management Block Characteristics

| Symbol                           | Parameter   | Conditions                                      | Min.                | Typ. | Max. | Unit |
|----------------------------------|---|---|---------------------|------|------|------|
| $V_{PVM}$                        | Power Voltage Monitoring Level  | PVMSEL[2:0] = 001 (rising edge) <sup>(1)</sup>  | 2.19                | 2.28 | 2.37 | V    |
|                                  |   | PVMSEL[2:0] = 001 (falling edge) <sup>(1)</sup> | 2.09                | 2.18 | 2.27 | V    |
|                                  |   | PVMSEL[2:0] = 010 (rising edge) <sup>(2)</sup>  | 2.28                | 2.38 | 2.48 | V    |
|                                  |   | PVMSEL[2:0] = 010 (falling edge) <sup>(2)</sup> | 2.18                | 2.28 | 2.38 | V    |
|                                  |   | PVMSEL[2:0] = 011 (rising edge) <sup>(2)</sup>  | 2.38                | 2.48 | 2.58 | V    |
|                                  |   | PVMSEL[2:0] = 011 (falling edge) <sup>(2)</sup> | 2.28                | 2.38 | 2.48 | V    |
|                                  |   | PVMSEL[2:0] = 100 (rising edge) <sup>(2)</sup>  | 2.47                | 2.58 | 2.69 | V    |
|                                  |   | PVMSEL[2:0] = 100 (falling edge) <sup>(2)</sup> | 2.37                | 2.48 | 2.59 | V    |
|                                  |   | PVMSEL[2:0] = 101 (rising edge) <sup>(2)</sup>  | 2.57                | 2.68 | 2.79 | V    |
|                                  |   | PVMSEL[2:0] = 101 (falling edge) <sup>(2)</sup> | 2.47                | 2.58 | 2.69 | V    |
|                                  |   | PVMSEL[2:0] = 110 (rising edge) <sup>(2)</sup>  | 2.66                | 2.78 | 2.9  | V    |
|                                  |   | PVMSEL[2:0] = 110 (falling edge) <sup>(2)</sup> | 2.56                | 2.68 | 2.8  | V    |
|                                  |   | PVMSEL[2:0] = 111 (rising edge)                 | 2.76                | 2.88 | 3    | V    |
| PVMSEL[2:0] = 111 (falling edge) | 2.66  | 2.78  | 2.9                 | V    |      |      |
| $V_{HYS+P}$ <sup>(2)</sup>       | PVM Hysteresis  | —   | —                   | 100  | —    | mV   |
| $V_{POR}$ <sup>(2)</sup>         | Power On Reset Threshold  | —   | 2.03                | 2.18 | 2.35 | V    |
| $V_{LVR}$ <sup>(2)</sup>         | Low Voltage Reset Threshold   | —   | 1.85 <sup>(3)</sup> | 2.02 | 2.2  | V    |
| $V_{LVRhyst}$ <sup>(2)</sup>     | LVR Hysteresis  | —   | —                   | 160  | —    | mV   |
| $T_{RSTTEMPO}$ <sup>(2)</sup>    | Reset Temporization: CPU starts execution after $V_{DD}$ keeps higher than $V_{POR}$ for $T_{RSTTEMPO}$ | —   | —                   | 13   | —    | ms   |

Note: 1. PVMSEL[2:0] = 001 may be not available as its voltage detector level may be lower than  $V_{POR}$ .  
 2. Data based on characterization results only, not tested in production.  
 3. The product behavior is based on design down to the minimum  $V_{LVR}$  value.

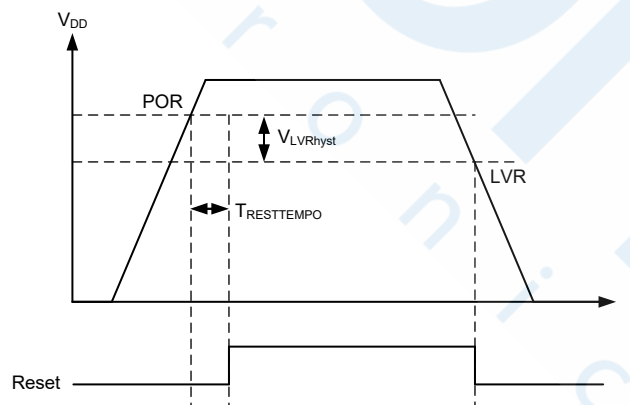


Figure 9. Power On Reset and Low Voltage Reset Waveform

## Memory Characteristics

**Table 16. Internal Flash Memory Characteristics**

| Symbol             | Parameter              | Conditions       | Typ. <sup>(Note)</sup> |      |      |      |      |      | Unit |
|--------------------|------------------------|------------------|------------------------|------|------|------|------|------|------|
|                    |                        |                  | f <sub>HCLK</sub>      |      |      |      |      |      |      |
|                    |                        |                  | 240                    | 200  | 144  | 72   | 48   | 8    | MHz  |
| T <sub>PROG</sub>  | Programming Time       | —                | 50                     |      |      |      |      |      | μs   |
| t <sub>ERASE</sub> | Page (2 KB) Erase Time | —                | 50                     |      |      |      |      |      | ms   |
| t <sub>ME</sub>    | Mass Erase Time        | HT32F49365       | 0.8                    |      |      |      |      |      | s    |
|                    |                        | HT32F49395       | 1.4 (each Bank)        |      |      |      |      |      |      |
| I <sub>DD</sub>    | Supply Current         | Programming Mode | 35.5                   | 29.9 | 22.5 | 13.4 | 9.9  | 3.7  | mA   |
|                    |                        | Erase Mode       | 57.4                   | 49.2 | 38.8 | 25.4 | 20.6 | 11.4 |      |

Note: Data based on characterization results only, not tested in production.

**Table 17. Internal Flash Memory Endurance and Data Retention**

| Symbol           | Parameter      | Conditions                    | Min. <sup>(Note)</sup> | Typ. | Max. | Unit    |
|------------------|----------------|-------------------------------|------------------------|------|------|---------|
| N <sub>END</sub> | Endurance      | T <sub>A</sub> = -40 ~ 105 °C | 100                    | —    | —    | kcycles |
| t <sub>RET</sub> | Data Retention | T <sub>A</sub> = 105 °C       | 10                     | —    | —    | years   |

Note: Data based on characterization results only, not tested in production.

## Supply Current Characteristics

The current consumption is subjected to several parameters and factors such as the operating voltage, ambient temperature, GPIO pin loading, device software configuration, operating frequencies, GPIO pin switching rate, and executed binary code. The current consumption is obtained by characterization results, not tested in production.

### Typical and Maximum Current Consumption

The MCU is placed under the following conditions:

- All GPIO pins are in analog mode.
- Prefetch ON. (Reminder: this bit must be set before clock setting and bus prescaling.)
- When the peripherals are enabled:
  - If f<sub>HCLK</sub> > 120 MHz: f<sub>PCLK1</sub> = f<sub>HCLK</sub>/2, f<sub>PCLK2</sub> = f<sub>HCLK</sub>/2, f<sub>ADCCLK</sub> = f<sub>PCLK2</sub>/4
  - If f<sub>HCLK</sub> ≤ 120 MHz: f<sub>PCLK1</sub> = f<sub>HCLK</sub>, f<sub>PCLK2</sub> = f<sub>HCLK</sub>, f<sub>ADCCLK</sub> = f<sub>PCLK2</sub>/4
- Code executes in ZW area.
- Unless otherwise specified, the typical values are measured with V<sub>DD</sub> = 3.3 V and T<sub>A</sub> = 25 °C condition and the maximum values are measured with V<sub>DD</sub> = 3.6 V.

**Table 18. Typical Current Consumption in Run Mode**

| Symbol          | Parameter                  | Conditions   | f <sub>HCLK</sub> | Typ.                    |                          | Unit |
|-----------------|----------------------------|--|-------------------|-------------------------|--------------------------|------|
|                 |                            |  |                   | All Peripherals Enabled | All Peripherals Disabled |      |
| I <sub>DD</sub> | Supply Current in Run Mode | High Speed External Crystal – HEXT <sup>(1)(2)</sup> | 240 MHz           | 93.8                    | 41.0                     | mA   |
|                 |                            |  | 200 MHz           | 78.9                    | 34.6                     |      |
|                 |                            |  | 144 MHz           | 57.8                    | 25.7                     |      |
|                 |                            |  | 120 MHz           | 59.1                    | 23.3                     |      |
|                 |                            |  | 108 MHz           | 53.5                    | 21.3                     |      |
|                 |                            |  | 72 MHz            | 37.1                    | 15.4                     |      |
|                 |                            |  | 48 MHz            | 25.7                    | 11.1                     |      |
|                 |                            |  | 36 MHz            | 19.9                    | 8.99                     |      |
|                 |                            |  | 24 MHz            | 14.2                    | 6.86                     |      |
|                 |                            |  | 16 MHz            | 10.3                    | 5.44                     |      |
|                 |                            |  | 8 MHz             | 6.01                    | 3.58                     |      |
|                 |                            |  | 4 MHz             | 4.16                    | 2.95                     |      |
|                 |                            |  | 2 MHz             | 3.23                    | 2.63                     |      |
|                 |                            |  | 1 MHz             | 2.77                    | 2.47                     |      |
|                 |                            | 500 kHz  | 2.55              | 2.39                    |                          |      |
|                 |                            | 125 kHz  | 2.37              | 2.34                    |                          |      |
|                 |                            | High Speed Internal Clock – HICK <sup>(2)</sup>      | 240 MHz           | 93.8                    | 41.0                     | mA   |
|                 |                            |  | 200 MHz           | 78.9                    | 34.6                     |      |
|                 |                            |  | 144 MHz           | 57.8                    | 25.6                     |      |
|                 |                            |  | 120 MHz           | 59.0                    | 23.2                     |      |
|                 |                            |  | 108 MHz           | 53.4                    | 21.2                     |      |
|                 |                            |  | 72 MHz            | 37.1                    | 15.4                     |      |
|                 |                            |  | 48 MHz            | 25.6                    | 11.1                     |      |
|                 |                            |  | 36 MHz            | 19.8                    | 8.91                     |      |
|                 |                            |  | 24 MHz            | 14.1                    | 6.78                     |      |
|                 |                            |  | 16 MHz            | 10.2                    | 5.36                     |      |
| 8 MHz           | 5.92                       |  | 3.49              |                         |                          |      |
| 4 MHz           | 4.07                       |  | 2.86              |                         |                          |      |
| 2 MHz           | 3.14                       | 2.54   |                   |                         |                          |      |
| 1 MHz           | 2.69                       | 2.39   |                   |                         |                          |      |
| 500 kHz         | 2.46                       | 2.31   |                   |                         |                          |      |
| 125 kHz         | 2.29                       | 2.25   |                   |                         |                          |      |

Note: 1. External clock is 8 MHz.  
2. PLL is on when f<sub>HCLK</sub> > 8 MHz.

**Table 19. Typical Current Consumption in Sleep Mode**

| Symbol          | Parameter                    | Conditions   | f <sub>HCLK</sub> | Typ.                    |                          | Unit |
|-----------------|------------------------------|--|-------------------|-------------------------|--------------------------|------|
|                 |                              |  |                   | All Peripherals Enabled | All Peripherals Disabled |      |
| I <sub>DD</sub> | Supply Current in Sleep Mode | High Speed External Crystal – HEXT <sup>(1)(2)</sup> | 240 MHz           | 78.3                    | 12.5                     | mA   |
|                 |                              |  | 200 MHz           | 65.9                    | 10.8                     |      |
|                 |                              |  | 144 MHz           | 48.3                    | 8.52                     |      |
|                 |                              |  | 120 MHz           | 50.2                    | 8.07                     |      |
|                 |                              |  | 108 MHz           | 45.5                    | 7.54                     |      |
|                 |                              |  | 72 MHz            | 31.8                    | 6.29                     |      |
|                 |                              |  | 48 MHz            | 22.1                    | 5.07                     |      |
|                 |                              |  | 36 MHz            | 17.2                    | 4.45                     |      |
|                 |                              |  | 24 MHz            | 12.4                    | 3.83                     |      |
|                 |                              |  | 16 MHz            | 9.12                    | 3.42                     |      |
|                 |                              |  | 8 MHz             | 5.42                    | 2.57                     |      |
|                 |                              |  | 4 MHz             | 3.87                    | 2.45                     |      |
|                 |                              |  | 2 MHz             | 3.09                    | 2.39                     |      |
|                 |                              |  | 1 MHz             | 2.71                    | 2.36                     |      |
|                 |                              | 500 kHz  | 2.52              | 2.34                    | mA                       |      |
|                 |                              | 125 kHz  | 2.37              | 2.33                    |                          |      |
|                 |                              | 240 MHz  | 78.3              | 12.4                    |                          |      |
|                 |                              | 200 MHz  | 65.9              | 10.8                    |                          |      |
|                 |                              | 144 MHz  | 48.3              | 8.44                    |                          |      |
|                 |                              | 120 MHz  | 50.2              | 7.99                    |                          |      |
|                 |                              | 108 MHz  | 45.5              | 7.45                    |                          |      |
|                 |                              | 72 MHz   | 31.7              | 6.20                    |                          |      |
|                 |                              | 48 MHz   | 22.0              | 4.97                    |                          |      |
|                 |                              | 36 MHz   | 17.2              | 4.35                    |                          |      |
|                 |                              | 24 MHz   | 12.3              | 3.74                    |                          |      |
|                 |                              | 16 MHz   | 9.04              | 3.33                    |                          |      |
| 8 MHz           | 5.33                         | 2.48   |                   |                         |                          |      |
| 4 MHz           | 3.78                         | 2.36   |                   |                         |                          |      |
| 2 MHz           | 3.01                         | 2.30   |                   |                         |                          |      |
| 1 MHz           | 2.62                         | 2.27   |                   |                         |                          |      |
| 500 kHz         | 2.43                         | 2.25   |                   |                         |                          |      |
| 125 kHz         | 2.28                         | 2.24   |                   |                         |                          |      |

Note: 1. External clock is 8 MHz.  
2. PLL is on when f<sub>HCLK</sub> > 8 MHz.

**Table 20. Maximum Current Consumption in Run Mode**

| Symbol          | Parameter                  | Conditions  | f <sub>HCLK</sub> | Max.                   |                         | Unit |
|-----------------|----------------------------|---|-------------------|------------------------|-------------------------|------|
|                 |                            |   |                   | T <sub>A</sub> = 85 °C | T <sub>A</sub> = 105 °C |      |
| I <sub>DD</sub> | Supply Current in Run Mode | High Speed External Crystal – HEXT <sup>(Note)</sup><br>(All Peripherals Enabled) | 240 MHz           | 108.5                  | 119.6                   | mA   |
|                 |                            |   | 200 MHz           | 93.3                   | 104.2                   |      |
|                 |                            |   | 144 MHz           | 71.6                   | 82.2                    |      |
|                 |                            |   | 120 MHz           | 73.2                   | 83.7                    |      |
|                 |                            |   | 108 MHz           | 67.5                   | 77.9                    |      |
|                 |                            |   | 72 MHz            | 50.4                   | 60.6                    |      |
|                 |                            |   | 48 MHz            | 38.4                   | 48.5                    |      |
|                 |                            |   | 36 MHz            | 32.4                   | 42.3                    |      |
|                 |                            |   | 24 MHz            | 26.3                   | 36.2                    |      |
|                 |                            | 16 MHz  | 22.3              | 32.0                   | mA                      |      |
|                 |                            | 8 MHz   | 17.8              | 27.5                   |                         |      |
|                 |                            | 240 MHz   | 53.4              | 63.5                   |                         |      |
|                 |                            | 200 MHz   | 46.9              | 57.0                   |                         |      |
|                 |                            | 144 MHz   | 37.8              | 47.7                   |                         |      |
|                 |                            | 120 MHz   | 35.4              | 45.3                   |                         |      |
|                 |                            | 108 MHz   | 33.3              | 43.2                   |                         |      |
|                 |                            | 72 MHz  | 27.3              | 37.1                   |                         |      |
|                 |                            | 48 MHz  | 22.9              | 32.6                   |                         |      |
| 36 MHz          | 20.7                       | 30.4  | mA                |                        |                         |      |
| 24 MHz          | 18.5                       | 28.2  |                   |                        |                         |      |
| 16 MHz          | 17.0                       | 26.7  |                   |                        |                         |      |
| 8 MHz           | 15.2                       | 24.8  |                   |                        |                         |      |

Note: External clock is 8 MHz and PLL is on when f<sub>HCLK</sub> > 8 MHz.



**Table 21. Maximum Current Consumption in Sleep Mode**

| Symbol          | Parameter                    | Conditions   | f <sub>HCLK</sub> | Max.                   |                         | Unit |
|-----------------|------------------------------|--|-------------------|------------------------|-------------------------|------|
|                 |                              |  |                   | T <sub>A</sub> = 85 °C | T <sub>A</sub> = 105 °C |      |
| I <sub>DD</sub> | Supply Current in Sleep Mode | High Speed External Crystal – HEXT <sup>(Note)</sup><br>(All Peripherals Enabled)  | 240 MHz           | 92.8                   | 103.2                   | mA   |
|                 |                              |  | 200 MHz           | 80.0                   | 90.4                    |      |
|                 |                              |  | 144 MHz           | 61.9                   | 72.1                    |      |
|                 |                              |  | 120 MHz           | 64.1                   | 74.3                    |      |
|                 |                              |  | 108 MHz           | 59.2                   | 69.3                    |      |
|                 |                              |  | 72 MHz            | 44.8                   | 54.7                    |      |
|                 |                              |  | 48 MHz            | 34.6                   | 44.4                    |      |
|                 |                              |  | 36 MHz            | 29.5                   | 39.2                    |      |
|                 |                              |  | 24 MHz            | 24.4                   | 34.0                    |      |
|                 |                              | High Speed External Crystal – HEXT <sup>(Note)</sup><br>(All Peripherals Disabled) | 16 MHz            | 20.9                   | 30.5                    | mA   |
|                 |                              |  | 8 MHz             | 17.0                   | 26.5                    |      |
|                 |                              |  | 240 MHz           | 23.9                   | 33.5                    |      |
|                 |                              |  | 200 MHz           | 22.3                   | 31.8                    |      |
|                 |                              |  | 144 MHz           | 20.0                   | 29.4                    |      |
|                 |                              |  | 120 MHz           | 19.6                   | 29.0                    |      |
|                 |                              |  | 108 MHz           | 19.0                   | 28.4                    |      |
|                 |                              |  | 72 MHz            | 17.7                   | 27.1                    |      |
|                 |                              |  | 48 MHz            | 16.4                   | 25.8                    |      |
| 36 MHz          | 15.8                         | 25.2   |                   |                        |                         |      |
| 24 MHz          | 15.2                         | 24.6   |                   |                        |                         |      |
| 16 MHz          | 14.8                         | 24.2   |                   |                        |                         |      |
| 8 MHz           | 13.9                         | 23.3   |                   |                        |                         |      |

Note: External clock is 8 MHz and PLL is on when f<sub>HCLK</sub> > 8 MHz.

**Table 22. Typical and Maximum Current Consumptions in Deepsleep and Standby Modes**

| Symbol          | Parameter                        | Conditions  | Typ. <sup>(1)</sup>                       |   | Max. <sup>(2)</sup>          |                        |                         | Unit |
|-----------------|----------------------------------|---|---|---|------------------------------|------------------------|-------------------------|------|
|                 |                                  |   | V <sub>DD</sub> /V <sub>BAT</sub> = 2.6 V | V <sub>DD</sub> /V <sub>BAT</sub> = 3.3 V | T <sub>A</sub> = 25 °C       | T <sub>A</sub> = 85 °C | T <sub>A</sub> = 105 °C |      |
| I <sub>DD</sub> | Supply Current in Deepsleep Mode | LDO in Run Mode, HICK and HEXT OFF (no WDT)       | 1.35                                      | 1.36                                      | Refer to note <sup>(3)</sup> | 13.6                   | 23.7                    | mA   |
|                 |                                  | LDO in Low-power Mode, HICK and HEXT OFF (no WDT) | 1.33                                      | 1.34                                      |                              | 13.1                   | 22.8                    |      |
|                 | Supply Current in Standby Mode   | LEXT and RTC OFF                                  | 3.93                                      | 5.72                                      | 7.49                         | 10.4                   | 14.9                    | μA   |
|                 |                                  | LEXT and RTC ON                                   | 4.55                                      | 6.48                                      | 8.34                         | 11.5                   | 16.5                    |      |

Note: 1. Typical values are measured at T<sub>A</sub> = 25 °C.

2. Data based on characterization results only, not tested in production.

3. The value may be several times the typical values due to process variation.

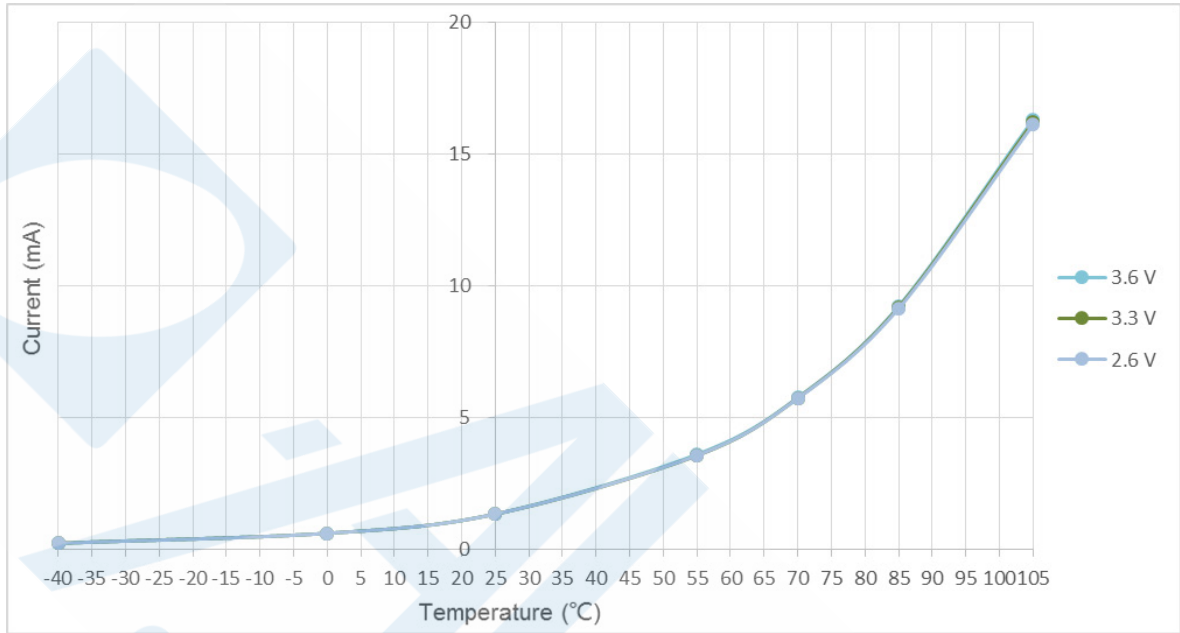


Figure 10. Typical Current Consumption in Deepsleep Mode vs. Temperature at Different V<sub>DD</sub>

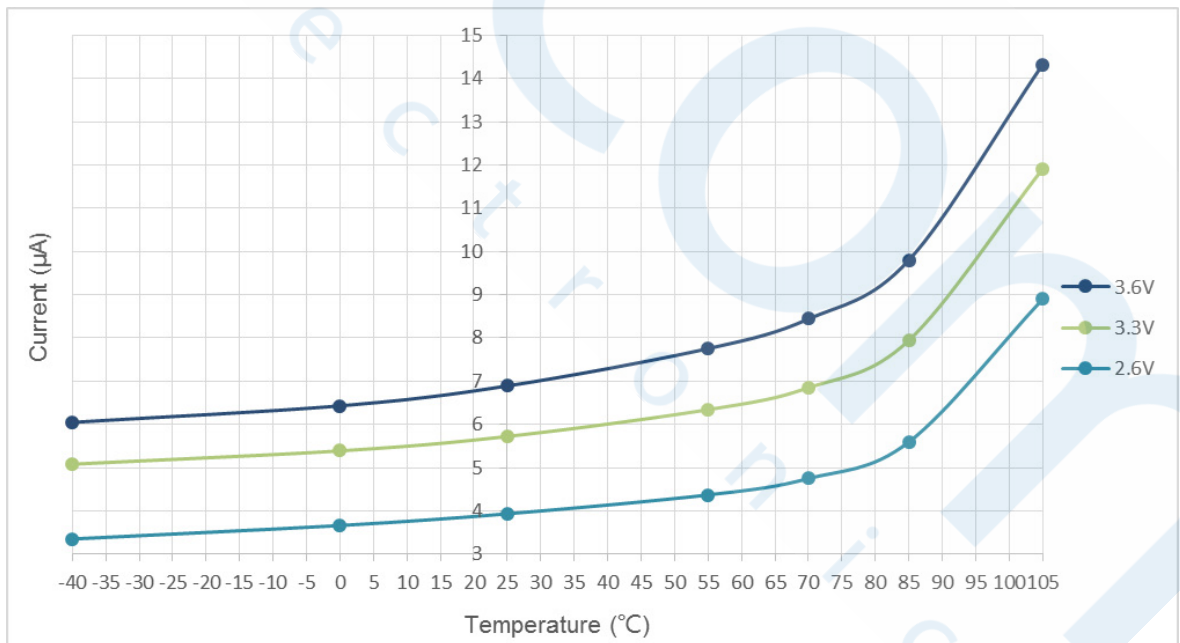
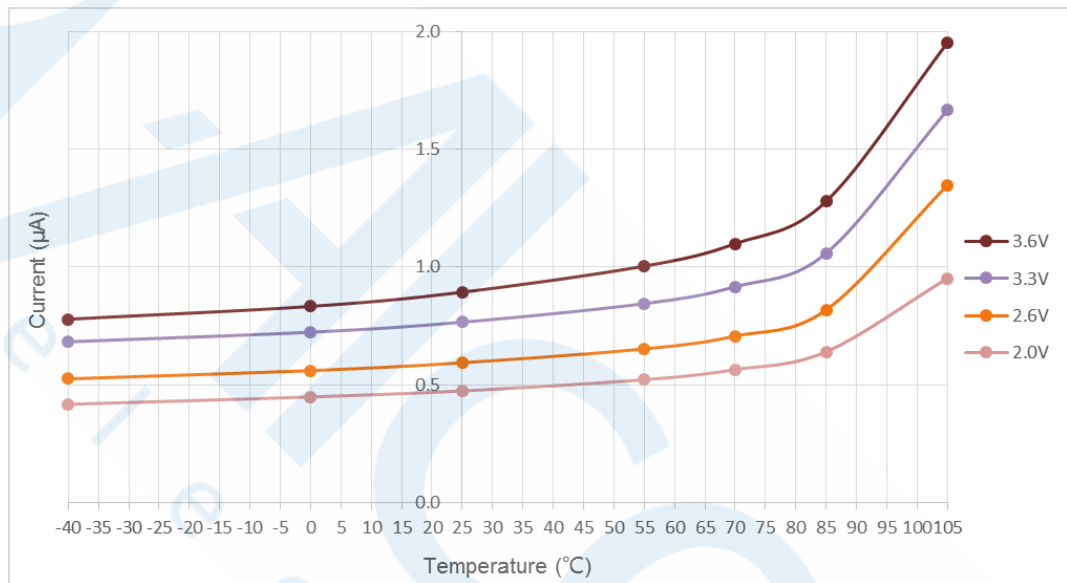


Figure 11. Typical Current Consumption in Standby Mode vs. Temperature at Different V<sub>DD</sub>

**Table 23. Typical and Maximum Current Consumptions on V<sub>BAT</sub>**

| Symbol               | Parameter                       | Conditions   | Typ. <sup>(1)</sup>      |                          |                          | Max. <sup>(2)</sup>    |                        |                         | Unit |
|----------------------|---------------------------------|--|--------------------------|--------------------------|--------------------------|------------------------|------------------------|-------------------------|------|
|                      |                                 |  | V <sub>BAT</sub> = 2.0 V | V <sub>BAT</sub> = 2.6 V | V <sub>BAT</sub> = 3.3 V | T <sub>A</sub> = 25 °C | T <sub>A</sub> = 85 °C | T <sub>A</sub> = 105 °C |      |
| I <sub>DD_VBAT</sub> | V <sub>BAT</sub> Supply Current | LEXT and RTC ON,<br>V <sub>DD</sub> < V <sub>LVR</sub> | 0.47                     | 0.59                     | 0.77                     | 0.92                   | 1.34                   | 2.04                    | μA   |

Note: 1. Typical values are measured at T<sub>A</sub> = 25 °C.  
2. Data based on characterization results only, not tested in production.



**Figure 12. Typical Current Consumption on V<sub>BAT</sub> with LEXT and RTC ON vs. Temperature at Different V<sub>BAT</sub>**

### On-chip Peripheral Current Consumption

The MCU is placed under the following conditions:

- All GPIO pins are in analog mode.
- The given value is calculated by measuring the current consumption difference between “all peripherals clocked OFF” and “only one peripheral clocked ON”.

**Table 24. Peripheral Current Consumption**

| Peripheral | Typ.                   | Unit  |
|------------|------------------------|-------|
| AHB        | DMA1                   | 9.34  |
|            | DMA2                   | 9.39  |
|            | GPIOA                  | 1.41  |
|            | GPIOB                  | 1.41  |
|            | GPIOC                  | 1.47  |
|            | GPIOD                  | 1.43  |
|            | GPIOE                  | 1.44  |
|            | XMC                    | 26.89 |
|            | CRC                    | 1.53  |
|            | SDIO1                  | 19.62 |
| SDIO2      | 20.40                  |       |
| APB1       | TMR2                   | 9.11  |
|            | TMR3                   | 6.52  |
|            | TMR4                   | 6.54  |
|            | TMR5                   | 8.82  |
|            | TMR6                   | 0.77  |
|            | TMR7                   | 0.75  |
|            | TMR12                  | 3.89  |
|            | TMR13                  | 2.45  |
|            | TMR14                  | 2.48  |
|            | SPI2/I <sup>2</sup> S2 | 5.19  |
|            | SPI3/I <sup>2</sup> S3 | 4.95  |
|            | SPI4/I <sup>2</sup> S4 | 2.62  |
|            | USART2                 | 2.60  |
|            | USART3                 | 2.57  |
|            | UART4                  | 2.60  |
|            | UART5                  | 2.63  |
|            | I <sup>2</sup> C1      | 2.47  |
|            | I <sup>2</sup> C2      | 2.54  |
|            | USBFS1                 | 6.40  |
|            | CAN1                   | 3.77  |
|            | CAN2                   | 3.77  |
|            | DAC1/2                 | 2.30  |
|            | WWDT                   | 0.34  |
| PWC        | 0.34                   |       |
| BPR        | 68.36                  |       |

μA/MHz

| Peripheral             | Typ. | Unit   |
|------------------------|------|--------|
| IOMUX                  | 2.32 | μA/MHz |
| SPI1/I <sup>2</sup> S1 | 2.82 |        |
| USART1                 | 2.53 |        |
| USART6                 | 2.64 |        |
| UART7                  | 2.80 |        |
| UART8                  | 2.85 |        |
| I <sup>2</sup> C3      | 2.48 |        |
| TMR1                   | 8.99 |        |
| TMR8                   | 8.72 |        |
| TMR9                   | 3.78 |        |
| TMR10                  | 2.62 |        |
| TMR11                  | 2.56 |        |
| ADC1                   | 5.17 |        |
| ADC2                   | 5.24 |        |
| ADC3                   | 5.18 |        |
| ACC                    | 0.95 |        |

## External Clock Source Characteristics

### High-speed External Clock Generated from a Crystal / Ceramic Resonator

The high-speed external (HEXT) clock can be supplied with a 4 to 25 MHz crystal/ceramic resonator oscillator. All the information given in this paragraph are based on characterization results obtained with typical external components specified in the table below. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time. Refer to the crystal resonator manufacturer for more details on the resonator characteristics (frequency, package, accuracy).

**Table 25. HEXT 4~25 MHz Crystal Characteristics<sup>(1)(2)</sup>**

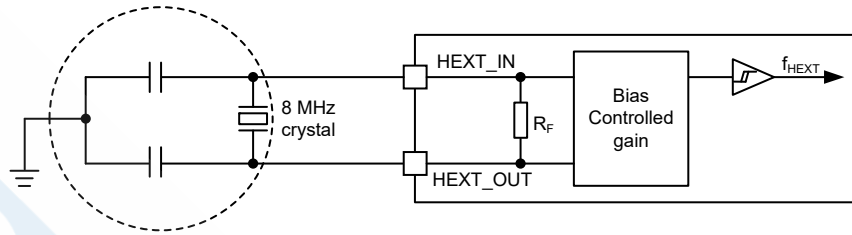
| Symbol                               | Parameter            | Conditions                    | Min. | Typ. | Max. | Unit |
|--------------------------------------|----------------------|-------------------------------|------|------|------|------|
| f <sub>HEXT_IN</sub>                 | Oscillator Frequency | —                             | 4    | 8    | 25   | MHz  |
| t <sub>SU(HEXT)</sub> <sup>(3)</sup> | Startup Time         | V <sub>DD</sub> is stabilized | —    | 2    | —    | ms   |

Note: 1. Oscillator characteristics given by the crystal/ceramic resonator manufacturer.

2. Data based on characterization results only, not tested in production.

3. t<sub>SU(HEXT)</sub> is the startup time measured from the moment HEXT is enabled (by software) to a stabilized 8 MHz oscillation is reached. This value is measured for a standard crystal resonator and it can vary significantly with the crystal manufacturer.

For C<sub>L1</sub> and C<sub>L2</sub>, it is recommended to use high-quality external ceramic capacitors in the 5 pF to 25 pF range (typ.), designed for high-frequency applications, and selected to match the requirements of the crystal or resonator. C<sub>L1</sub> and C<sub>L2</sub> are usually the same size. The crystal manufacturer typically specifies a load capacitance which is the series combination of C<sub>L1</sub> and C<sub>L2</sub>. PCB and MCU pin capacitance must be included (10 pF can be used as a rough estimate of the combined pin and board capacitance) when sizing C<sub>L1</sub> and C<sub>L2</sub>.



**Figure 13. HEXT Typical Application with an 8 MHz Crystal**

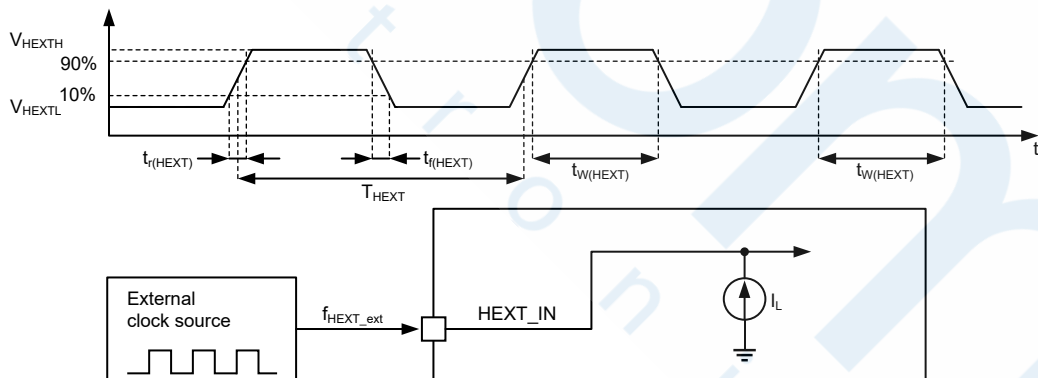
### High-speed External Clock Generated from an External Source

The characteristics given in the table below result from tests performed using a high-speed external clock source.

**Table 26. HEXT External Source Characteristics**

| Symbol                                       | Parameter   | Conditions  | Min.               | Typ. | Max.               | Unit          |
|--|---|---|--------------------|------|--------------------|---------------|
| $f_{\text{HEXT\_ext}}$                       | User External Clock Source Frequency <sup>(1)</sup> | —   | 1                  | 8    | 25                 | MHz           |
| $V_{\text{HEXTH}}$                           | HEXT_IN Input Pin High Level Voltage                |   | $0.7V_{\text{DD}}$ | —    | $V_{\text{DD}}$    | V             |
| $V_{\text{HEXTL}}$                           | HEXT_IN Input Pin Low Level Voltage                 |   | $V_{\text{SS}}$    | —    | $0.3V_{\text{DD}}$ |               |
| $t_{\text{w(HEXT)}}$                         | HEXT_IN High or Low Time <sup>(Note)</sup>          |   | 5                  | —    | —                  | ns            |
| $t_{\text{r(HEXT)}}$<br>$t_{\text{f(HEXT)}}$ | HEXT_IN Rising or Falling Time <sup>(Note)</sup>    | —   | —                  | 20   |                    |               |
| $C_{\text{in(HEXT)}}$                        | HEXT_IN Input Capacitance <sup>(Note)</sup>         | —   | —                  | 5    | —                  | pF            |
| $\text{DuCy}_{\text{(HEXT)}}$                | Duty Cycle  | —   | 45                 | —    | 55                 | %             |
| $I_{\text{L}}$                               | HEXT_IN Input Leakage Current                       | $V_{\text{SS}} \leq V_{\text{IN}} \leq V_{\text{DD}}$ | —                  | —    | $\pm 1$            | $\mu\text{A}$ |

Note: Data based on characterization results only, not tested in production.



**Figure 14. HEXT External Source AC Timing Diagram**

### Low-speed External Clock Generated from a Crystal / Ceramic Resonator

The low-speed external (LEXT) clock can be supplied with a 32.768 kHz crystal/ceramic resonator oscillator. All the information given in this paragraph are based on characterization results obtained with typical external components specified in the table below. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time. Refer to the crystal resonator manufacturer for more details on the resonator characteristics (frequency, package, accuracy).

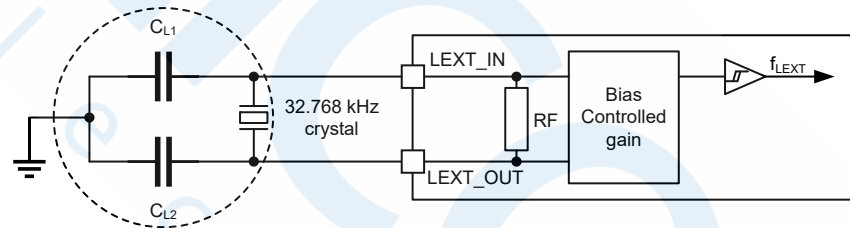
**Table 27. LEXT 32.768 kHz Crystal Characteristics<sup>(1)(2)</sup>**

| Symbol         | Parameter    | Conditions             | Min. | Typ. | Max. | Unit |
|----------------|--------------|------------------------|------|------|------|------|
| $t_{SU(LEXT)}$ | Startup Time | $V_{DD}$ is stabilized | —    | 150  | —    | ms   |

Note: 1. Oscillator characteristics given by the crystal/ceramic resonator manufacturer.  
2. Data based on characterization results only, not tested in production.

For  $C_{L1}$  and  $C_{L2}$ , it is recommended to use high-quality ceramic capacitors in the 5 pF to 15 pF range selected to match the requirements of the crystal or resonator.  $C_{L1}$  and  $C_{L2}$ , are usually the same size. The crystal manufacturer typically specifies a load capacitance which is the series combination of  $C_{L1}$  and  $C_{L2}$ .

Load capacitance  $C_L$  has the following formula:  $C_L = C_{L1} \times C_{L2} / (C_{L1} + C_{L2}) + C_{stray}$  where  $C_{stray}$  is the pin capacitance and board or trace PCB-related capacitance. Typically, it is between 2 pF and 7 pF.



**Figure 15. LEXT Typical Application with a 32.768 kHz Crystal**

Note: No external resistor is required between LEXT\_IN and LEXT\_OUT and it is also prohibited to add it.

### Low-speed External Clock Generated from an External Source

The characteristics given in the table below result from tests performed using a low-speed external clock source.

**Table 28. LEXT External Source Characteristics**

| Symbol                         | Parameter   | Conditions                       | Min.        | Typ.   | Max.        | Unit    |
|--------------------------------|---|----------------------------------|-------------|--------|-------------|---------|
| $f_{LEXT\_ext}$                | User External Clock Source Frequency <sup>(1)</sup> | —                                | —           | 32.768 | 1000        | kHz     |
| $V_{LEXTH}$                    | LEXT_IN Input Pin High Level Voltage                | —                                | $0.7V_{DD}$ | —      | $V_{DD}$    | V       |
| $V_{LEXTL}$                    | LEXT_IN Input Pin Low Level Voltage                 | —                                | $V_{SS}$    | —      | $0.3V_{DD}$ |         |
| $t_{w(LEXT)}$                  | LEXT_IN High or Low Time <sup>(Note)</sup>          | —                                | 450         | —      | —           | ns      |
| $t_{r(LEXT)}$<br>$t_{f(LEXT)}$ | LEXT_IN Rising or Falling Time <sup>(Note)</sup>    | —                                | —           | —      | 50          |         |
| $C_{in(LEXT)}$                 | LEXT_IN Input Capacitance <sup>(Note)</sup>         | —                                | —           | 5      | —           | pF      |
| $DuCy_{(LEXT)}$                | Duty Cycle  | —                                | 30          | —      | 70          | %       |
| $I_L$                          | LEXT_IN Input Leakage Current                       | $V_{SS} \leq V_{IN} \leq V_{DD}$ | —           | —      | $\pm 1$     | $\mu A$ |

Note: Data based on characterization results only, not tested in production.

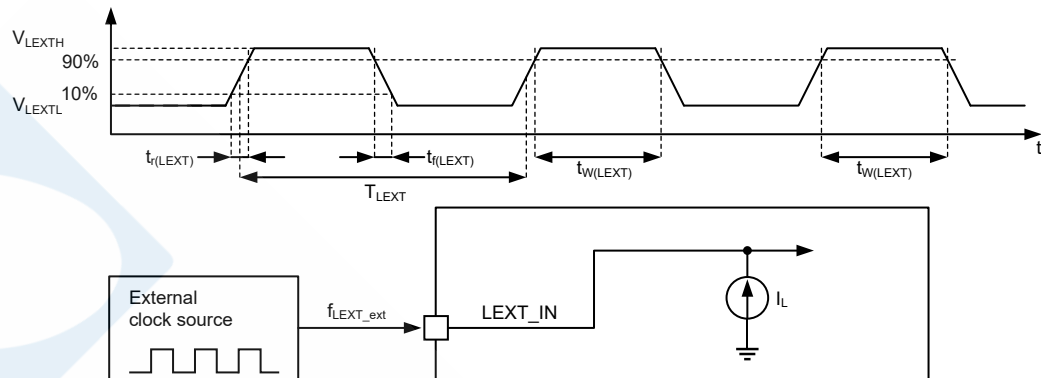


Figure 16. LEXT External Source AC Timing Diagram

## Internal Clock Source Characteristics

### High-speed Internal Clock (HICK)

Table 29. HICK Clock Characteristics

| Symbol               | Parameter                         | Conditions                               | Min.  | Typ. | Max.                | Unit          |   |
|----------------------|-----------------------------------|--|---|------|---------------------|---------------|---|
| $f_{HICK}$           | Frequency                         | —  | —   | 48   | —                   | MHz           |   |
| $DuCy_{(HICK)}$      | Duty Cycle                        | —  | 45  | —    | 55                  | %             |   |
| $ACC_{HICK}$         | Accuracy of the HICK Oscillator   | User-trimmed with the RCC_CTRL register  | —   | —    | 1 <sup>(1)</sup>    | %             |   |
|                      |                                   | ACC-trimmed                              | —   | —    | 0.25 <sup>(1)</sup> |               |   |
|                      |                                   | Factory-calibrated <sup>(2)</sup>        | $T_A = -40 \sim 105 \text{ }^\circ\text{C}$ | -2.5 | —                   | 2             | % |
|                      |                                   |  | $T_A = -40 \sim 85 \text{ }^\circ\text{C}$  | -2.5 | —                   | 2             |   |
|                      |                                   | $T_A = 0 \sim 70 \text{ }^\circ\text{C}$ | -1.5  | —    | 1.5                 |               |   |
|                      |                                   | $T_A = 25 \text{ }^\circ\text{C}$        | -1  | —    | 1                   |               |   |
| $t_{SU(HICK)}^{(2)}$ | HICK Oscillator Startup Time      | —  | —   | —    | 10                  | $\mu\text{s}$ |   |
| $I_{DD(HICK)}^{(2)}$ | HICK Oscillator Power Consumption | —  | —   | 240  | 290                 | $\mu\text{A}$ |   |

Note: 1. Data based on design only, not tested in production.

2. Data based on characterization results only, not tested in production.



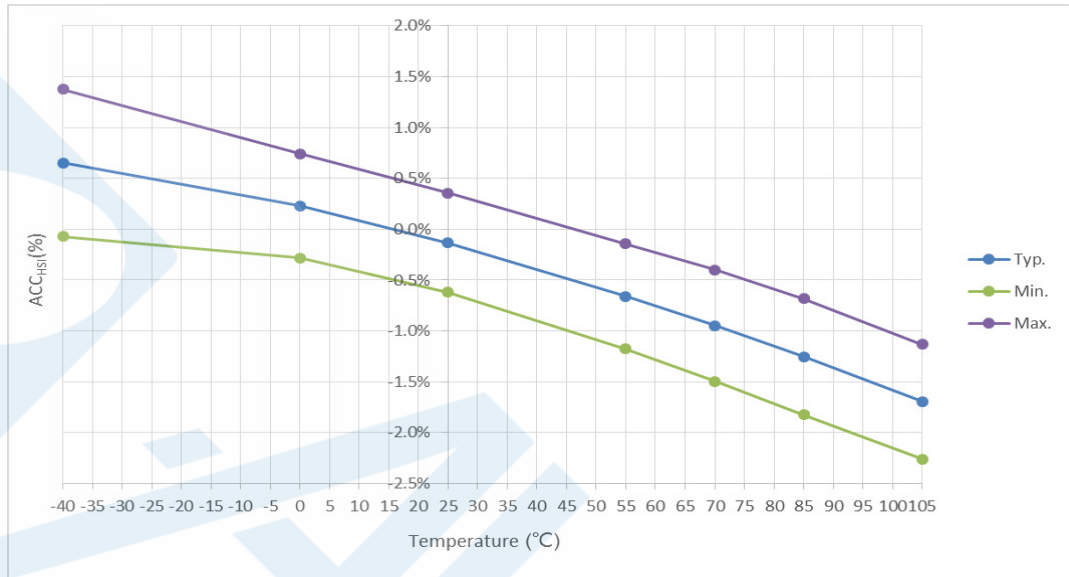


Figure 17. HICK Clock Frequency Accuracy vs. Temperature

### Low-speed Internal Clock (LICK)

Table 30. LICK Clock Characteristics

| Symbol              | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------------|-----------|------------|------|------|------|------|
| $f_{LICK}^{(Note)}$ | Frequency | —          | 30   | 40   | 60   | kHz  |

Note: Data based on characterization results only, not tested in production.

### PLL Characteristics

Table 31. PLL Characteristics

| Symbol         | Parameter                      | Min. | Typ. | Max. <sup>(1)</sup> | Unit    |
|----------------|--------------------------------|------|------|---------------------|---------|
| $f_{PLL\_IN}$  | PLL Input Clock <sup>(2)</sup> | 2    | 8    | 16                  | MHz     |
|                | PLL Input Clock Duty Cycle     | 40   | —    | 60                  | %       |
| $f_{PLL\_OUT}$ | PLL Multiplier Output Clock    | 16   | —    | 240                 | MHz     |
| $t_{LOCK}$     | PLL Lock Time                  | —    | —    | 200                 | $\mu$ s |
| Jitter         | Cycle-to-Cycle Jitter          | —    | —    | 300                 | ps      |

Note: 1. Data based on characterization results only, not tested in production.

2. Take care of using the appropriate multiplier factors so as to have PLL input clock values compatible with the range defined by  $f_{PLL\_OUT}$ .

## Wakeup Time from Low-power Mode

The wakeup time given in the table below are measured on a wakeup phase with the HICK. The clock source used to wake up the device depends from the current operating mode:

- Sleep mode: the clock source is the clock that was set before entering Sleep mode.
- Deepsleep or Standby mode: the clock source is the HICK.

**Table 32. Low-power Mode Wakeup Time**

| Symbol                     | Parameter  | Typ. | Unit    |
|----------------------------|--|------|---------|
| $t_{WUSLEEP}^{(Note)}$     | Wakeup from Sleep Mode                                   | 3.3  | $\mu s$ |
| $t_{WUDEEPSLEEP}^{(Note)}$ | Wakeup from Deepsleep Mode (Regulator in Normal Mode)    | 280  | $\mu s$ |
|                            | Wakeup from Deepsleep Mode (Regulator in Low-power Mode) | 320  |         |
| $t_{WUSTDBY}^{(Note)}$     | Wakeup from Standby Mode                                 | 8    | ms      |

Note: The wakeup time is measured from the wakeup event to the point in which the user application code reads the first instruction.

## EMC Characteristics

Susceptibility tests are performed on a sample basis during device characterization.

### Functional EMS (Electromagnetic Susceptibility)

EFT: A Burst of Fast Transient voltage (positive and negative) is applied to  $V_{DD}$  and  $V_{SS}$  through a coupling/decoupling network, until a functional disturbance occurs. This test is compliant with the IEC 61000-4-4 standard.

**Table 33. EMS Characteristics**

| Symbol    | Parameter  | Conditions  | Level/Class |
|-----------|--|---|-------------|
| $V_{EFT}$ | Fast transient voltage burst limits to be applied through coupling/decoupling network conforms to IEC 61000-4-4 on $V_{DD}$ and $V_{SS}$ pins to induce a functional disturbance, $V_{DD}$ and $V_{SS}$ input has one 47 $\mu F$ capacitor and each $V_{DD}$ and $V_{SS}$ pin pair 0.1 $\mu F$ | $V_{DD} = 3.3 V$ , 100LQFP,<br>$T_A = +25 ^\circ C$ , $f_{HCLK} = 240 MHz$ ,<br>conforms to IEC 61000-4-4 | 4A (4 kV)   |
|           |  | $V_{DD} = 3.3 V$ , 100LQFP,<br>$T_A = +25 ^\circ C$ , $f_{HCLK} = 72 MHz$ ,<br>conforms to IEC 61000-4-4  |             |

EMC characterization and optimization are performed at component level with a typical application environment. It should be noted that good EMC performance is highly dependent on the user application and the software in particular. Therefore it is recommended that the user applies EMC software optimization and prequalification tests in relation with the EMC level requested for his application.

## GPIO Port Characteristics

### General Input / Output Characteristics

All GPIOs are CMOS and TTL compliant.

**Table 34. GPIO Static Characteristics**

| Symbol    | Parameter   | Conditions   | Min.                       | Typ. | Max.                       | Unit       |
|-----------|---|--|----------------------------|------|----------------------------|------------|
| $V_{IL}$  | GPIO Input Low Level Voltage                                      | —  | -0.3                       | —    | $0.28 \times V_{DD} + 0.1$ | V          |
| $V_{IH}$  | TC GPIO Input High Level Voltage                                  | —  | $0.31 \times V_{DD} + 0.8$ | —    | $V_{DD} + 0.3$             | V          |
|           | FTa GPIO Input High Level Voltage                                 | Analog mode  |                            |      |                            |            |
|           | FT GPIO Input High Level Voltage                                  | —  |                            |      |                            |            |
|           | FTa GPIO Input High Level Voltage                                 | Input floating, input pull-up, or input pull-down mode |                            |      |                            |            |
| $V_{hys}$ | TC GPIO Schmitt Trigger Voltage Hysteresis <sup>(1)</sup>         | —  | 200                        | —    | —                          | mV         |
|           | FT and FTa GPIO Schmitt Trigger Voltage Hysteresis <sup>(1)</sup> | —  | $5\% V_{DD}$               | —    | —                          | —          |
| $I_{ikg}$ | Input Leakage Current <sup>(2)</sup>                              | $V_{SS} \leq V_{IN} \leq V_{DD}$<br>TC GPIOs           | —                          | —    | $\pm 1$                    | $\mu A$    |
|           |   | $V_{SS} \leq V_{IN} \leq 5.5V$<br>FT and FTa GPIO      | —                          | —    | $\pm 1$                    |            |
| $R_{PU}$  | Weak Pull-up Equivalent Resistor                                  | $V_{IN} = V_{SS}$                                      | 60                         | 70   | 100                        | k $\Omega$ |
| $R_{PD}$  | Weak Pull-down Equivalent Resistor <sup>(3)</sup>                 | $V_{IN} = V_{DD}$                                      | 60                         | 70   | 100                        | k $\Omega$ |
| $C_{IO}$  | GPIO Pin Capacitance  | —  | —                          | 9    | —                          | pF         |

Note: 1. Hysteresis voltage between Schmitt trigger switching levels. Data based on characterization results only.

2. Leakage could be higher than max if negative current is injected on adjacent pins.

3. The pull-down resistor of BOOT0 exists permanently.

All GPIOs are CMOS and TTL compliant (no software configuration required). Their characteristics cover more than the strict CMOS-technology or TTL parameters.

### Output Driving Current

In the user application, the number of GPIO pins which can drive current must be controlled to respect the absolute maximum rating defined in the “Absolute Maximum Values → Ratings” section:

- The sum of the currents sourced by all GPIOs on  $V_{DD}$ , plus the maximum Run consumption of the MCU sourced on  $V_{DD}$ , cannot exceed the absolute maximum rating  $I_{VDD}$  (see Table 9).
- The sum of the currents sunk by all GPIOs on  $V_{SS}$ , plus the maximum Run consumption of the MCU sunk on  $V_{SS}$ , cannot exceed the absolute maximum rating  $I_{VSS}$  (see Table 9).

### Output Voltage Levels

All GPIOs are CMOS and TTL compliant.

**Table 35. Output Voltage Characteristics**

| Symbol                                   | Parameter                 | Conditions                             | Min.           | Max. | Unit |
|--|---------------------------|--|----------------|------|------|
| <b>Maximum Sourcing/Sinking Strength</b> |                           |  |                |      |      |
| $V_{OL}$                                 | Output Low Level Voltage  | CMOS standard, $I_{IO} = 15\text{ mA}$ | —              | 0.4  | V    |
| $V_{OH}$                                 | Output High Level Voltage |  | $V_{DD} - 0.4$ | —    |      |
| $V_{OL}$                                 | Output Low Level Voltage  | TTL standard, $I_{IO} = 6\text{ mA}$   | —              | 0.4  | V    |
| $V_{OH}$                                 | Output High Level Voltage |  | 2.4            | —    |      |
| <b>Large Sourcing/Sinking Strength</b>   |                           |  |                |      |      |
| $V_{OL}$                                 | Output Low Level Voltage  | CMOS standard, $I_{IO} = 6\text{ mA}$  | —              | 0.4  | V    |
| $V_{OH}$                                 | Output High Level Voltage |  | $V_{DD} - 0.4$ | —    |      |
| $V_{OL}$                                 | Output Low Level Voltage  | TTL standard, $I_{IO} = 3\text{ mA}$   | —              | 0.4  | V    |
| $V_{OH}$                                 | Output High Level Voltage |  | 2.4            | —    |      |
| $V_{OL}^{(Note)}$                        | Output Low Level Voltage  | $I_{IO} = 20\text{ mA}$                | —              | 1.3  | V    |
| $V_{OH}^{(Note)}$                        | Output High Level Voltage |  | $V_{DD} - 1.3$ | —    |      |
| <b>Normal Sourcing/Sinking Strength</b>  |                           |  |                |      |      |
| $V_{OL}$                                 | Output Low Level Voltage  | CMOS standard, $I_{IO} = 4\text{ mA}$  | —              | 0.4  | V    |
| $V_{OH}$                                 | Output High Level Voltage |  | $V_{DD} - 0.4$ | —    |      |
| $V_{OL}$                                 | Output Low Level Voltage  | TTL standard, $I_{IO} = 2\text{ mA}$   | —              | 0.4  | V    |
| $V_{OH}$                                 | Output High Level Voltage |  | 2.4            | —    |      |
| $V_{OL}^{(Note)}$                        | Output Low Level Voltage  | $I_{IO} = 10\text{ mA}$                | —              | 1.3  | V    |
| $V_{OH}^{(Note)}$                        | Output High Level Voltage |  | $V_{DD} - 1.3$ | —    |      |

Note: Data based on characterization results only.

### Input AC Characteristics

The definition and values of input AC characteristics are given as follows.

**Table 36. Input AC Characteristics**

| Symbol        | Parameter  | Min. | Max. | Unit |
|---------------|--|------|------|------|
| $t_{EXINTpw}$ | Pulse Width of External Signals Detected by EXINT Controller | 10   | —    | ns   |

### NRST Pin Characteristics

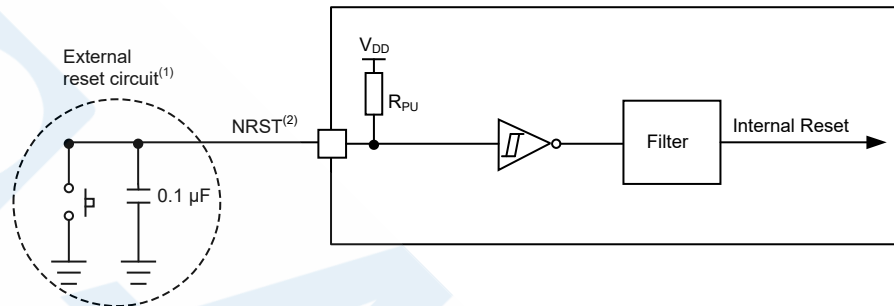
The NRST pin input driver uses CMOS technology. It is connected to a permanent pull-up resistor,  $R_{PU}$  (see the table below).

**Table 37. NRST Pin Characteristics**

| Symbol                  | Parameter                               | Conditions        | Min. | Typ. | Max.           | Unit          |
|-------------------------|---|-------------------|------|------|----------------|---------------|
| $V_{IL(NRST)}^{(Note)}$ | NRST Input Low Level Voltage            | —                 | -0.5 | —    | 0.8            | V             |
| $V_{IH(NRST)}^{(Note)}$ | NRST Input High Level Voltage           | —                 | 2    | —    | $V_{DD} + 0.3$ |               |
| $V_{hys(NRST)}$         | NRST Schmitt Trigger Voltage Hysteresis | —                 | —    | 500  | —              | mV            |
| $R_{PU}$                | Weak Pull-up Equivalent Resistor        | $V_{IN} = V_{SS}$ | 30   | 40   | 50             | k $\Omega$    |
| $V_{F(NRST)}^{(Note)}$  | NRST Input Filtered puLEXT              | —                 | —    | —    | 33.3           | $\mu\text{s}$ |

| Symbol                           | Parameter                      | Conditions | Min. | Typ. | Max. | Unit |
|----------------------------------|--------------------------------|------------|------|------|------|------|
| $V_{NF(NRST)}$ <sup>(Note)</sup> | NRST Input not filtered puLEXT | —          | 66.7 | —    | —    | μs   |

Note: Data based on characterization results only.



**Figure 18. Recommended NRST Pin Protection**

Note: 1. The reset network protects the device against parasitic resets.

2. The user must ensure that the level on the NRST pin can go below the  $V_{IL(NRST)}$  max. level specified in Table 37. Otherwise the reset will not be taken into account by the device.

## XMC Characteristics

### Asynchronous Waveforms and Timings of PSRAM / NOR

The results shown in these tables are obtained with the following XMC configuration:

- AddressSetupTime = 0
- AddressHoldTime = 1
- DataSetupTime = 1

**Table 38. Asynchronous Multiplexed PSRAM / NOR Read Timings**

| Symbol                | Parameter  | Min.              | Max.              | Unit |
|-----------------------|--|-------------------|-------------------|------|
| $t_{w(NE)}$           | XMC_NE Low Time                                      | $7t_{HCLK} - 2$   | $7t_{HCLK} + 2$   | ns   |
| $t_{v(NOENOE)}$       | XMC_NE Low to XMC_NOE Low                            | $3t_{HCLK} - 0.5$ | $3t_{HCLK} + 1.5$ | ns   |
| $t_{w(NOENOE)}$       | XMC_NOE Low Time                                     | $4t_{HCLK} - 1$   | $4t_{HCLK} + 2$   | ns   |
| $t_{h(NE_NOENOE)}$    | XMC_NOE High to XMC_NE High Hold Time                | -1                | —                 | ns   |
| $t_{v(A_NE)}$         | XMC_NE Low to XMC_A Valid                            | —                 | 0                 | ns   |
| $t_{v(NADV_NE)}$      | XMC_NE Low to XMC_NADV Low                           | 3                 | 5                 | ns   |
| $t_{w(NADV)}$         | XMC_NADV Low Time                                    | $t_{HCLK} - 1.5$  | $t_{HCLK} + 1.5$  | ns   |
| $t_{h(AD_NADV)}$      | XMC_AD (address) Valid Hold Time after XMC_NADV High | $t_{HCLK} + 3$    | —                 | ns   |
| $t_{h(A_NOENOE)}$     | Address Hold Time after XMC_NOE High                 | $t_{HCLK} + 3$    | —                 | ns   |
| $t_{h(UBLB_NOENOE)}$  | XMC_UB/LB Hold Time after XMC_NOE High               | 0                 | —                 | ns   |
| $t_{v(UBLB_NE)}$      | XMC_NE Low to XMC_UB/LB Valid                        | —                 | 0                 | ns   |
| $t_{su(Data_NE)}$     | Data to XMC_NE High Setup Time                       | $2t_{HCLK} + 24$  | —                 | ns   |
| $t_{su(Data_NOENOE)}$ | Data to XMC_NOE High Setup Time                      | $2t_{HCLK} + 25$  | —                 | ns   |
| $t_{h(Data_NE)}$      | Data Hold Time after XMC_NE High                     | 0                 | —                 | ns   |
| $t_{h(Data_NOENOE)}$  | Data Hold Time after XMC_NOE High                    | 0                 | —                 | ns   |

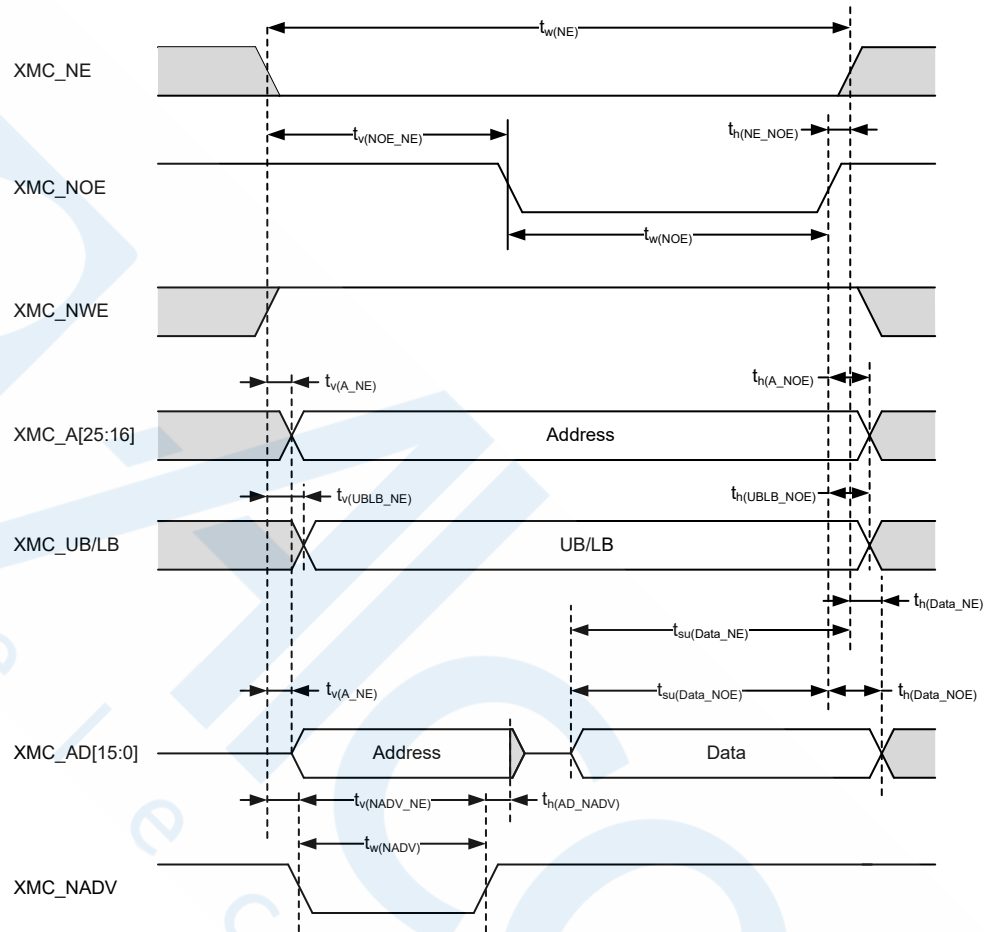
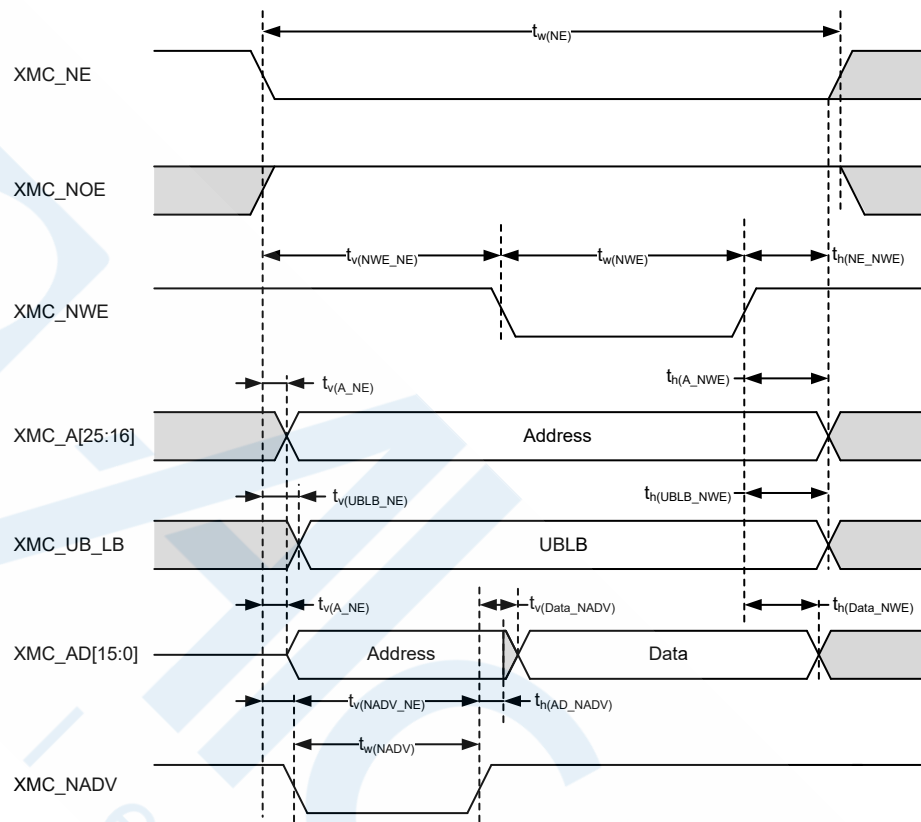


Figure 19. Asynchronous Multiplexed PSRAM / NOR Read Waveforms

Table 39. Asynchronous Multiplexed PSRAM / NOR Write Timings

| Symbol             | Parameter  | Min.              | Max.             | Unit |
|--------------------|--|-------------------|------------------|------|
| $t_{w(NE)}$        | XMC_NE Low Time                                      | $5t_{HCLK} - 1$   | $5t_{HCLK} + 2$  | ns   |
| $t_{v(NWE_NE)}$    | XMC_NE Low to XMC_NWE Low                            | $2t_{HCLK}$       | $2t_{HCLK} + 1$  | ns   |
| $t_{w(NWE)}$       | XMC_NWE Low Time                                     | $2t_{HCLK} - 1$   | $2t_{HCLK} + 2$  | ns   |
| $t_{h(NE_NWE)}$    | XMC_NWE High to XMC_NE High Hold Time                | $t_{HCLK} - 1$    | —                | ns   |
| $t_{v(A_NE)}$      | XMC_NE Low to XMC_A Valid                            | —                 | 7                | ns   |
| $t_{v(NADV_NE)}$   | XMC_NE Low to XMC_NADV Low                           | 3                 | 5                | ns   |
| $t_{w(NADV)}$      | XMC_NADV Low Time                                    | $t_{HCLK} - 1$    | $t_{HCLK} + 1$   | ns   |
| $t_{h(AD_NADV)}$   | XMC_AD (address) Valid Hold Time after XMC_NADV High | $t_{HCLK} - 3$    | —                | ns   |
| $t_{h(A_NWE)}$     | Address Hold Time after XMC_NWE High                 | $4t_{HCLK} + 2.5$ | —                | ns   |
| $t_{h(UBLB_NWE)}$  | XMC_UB/LB Hold Time after XMC_NWE High               | $t_{HCLK} - 1.5$  | —                | ns   |
| $t_{v(UBLB_NE)}$   | XMC_NE Low to XMC_UB/LB Valid                        | —                 | 1.6              | ns   |
| $t_{v(Data_NADV)}$ | XMC_NADV High to Data Valid                          | —                 | $t_{HCLK} + 1.5$ | ns   |
| $t_{h(Data_NWE)}$  | Data Hold Time after XMC_NWE High                    | $t_{HCLK} - 5$    | —                | ns   |



**Figure 20. Asynchronous Multiplexed PSRAM / NOR Write Waveforms**

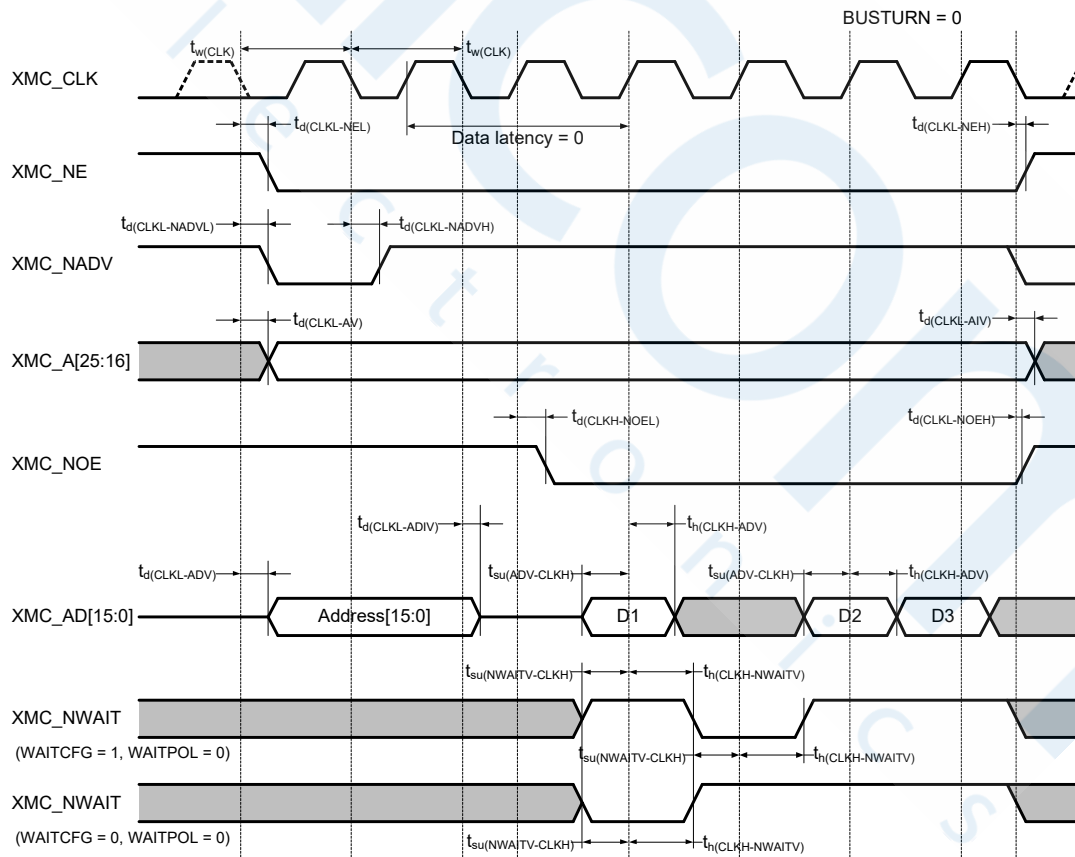
**Synchronous Waveforms and Timings of PSRAM / NOR**

The results shown in these tables are obtained with the following XMC configuration:

- BurstAccessMode = XMC\_BurstAccessMode\_Enable (enable burst transfer mode)
- MemoryType = XMC\_MemoryType\_CRAM (memory type is CRAM)
- WriteBurst = XMC\_WriteBurst\_Enable (enable burst write operation)
- CLKPrescale = 1; (memory cycle = 2 HICK cycles) (Note: CLKPrescale refers to the CLKPSC bit in XMC\_BK1TMGx register. Refer to the HT32F49365/HT32F49395 User Manual.)
- DataLatency = 1 stands for NOR Flash; DataLatency = 0 for PSRAM (Note: DataLatency refers to the DTLAT bit in XMC\_BK1TMGx register. Refer to the HT32F49365/HT32F49395 User Manual.)

**Table 40. Synchronous Multiplexed PSRAM / NOR Read Timings**

| Symbol                       | Parameter                             | Min.                    | Max.                  | Unit |
|------------------------------|---------------------------------------|-------------------------|-----------------------|------|
| $t_{w(\text{CLK})}$          | XMC_CLK Period                        | 20                      | —                     | ns   |
| $t_{d(\text{CLKL-NEL})}$     | XMC_CLK Low to XMC_NE Low             | —                       | 1.5                   | ns   |
| $t_{d(\text{CLKL-NEH})}$     | XMC_CLK Low to XMC_NE High            | $t_{\text{HCLK}} + 2$   | —                     | ns   |
| $t_{d(\text{CLKL-NADVL})}$   | XMC_CLK Low to XMC_NADV Low           | —                       | 4                     | ns   |
| $t_{d(\text{CLKL-NADVH})}$   | XMC_CLK Low to XMC_NADV High          | 5                       | —                     | ns   |
| $t_{d(\text{CLKL-AV})}$      | XMC_CLK Low to XMC_A Valid            | —                       | 0                     | ns   |
| $t_{d(\text{CLKL-AIV})}$     | XMC_CLK Low to XMC_A Invalid          | $t_{\text{HCLK}} + 2$   | —                     | ns   |
| $t_{d(\text{CLKH-NOEL})}$    | XMC_CLK High to XMC_NOE Low           | —                       | $t_{\text{HCLK}} + 1$ | ns   |
| $t_{d(\text{CLKL-NOEH})}$    | XMC_CLK Low to XMC_NOE High           | $t_{\text{HCLK}} + 0.5$ | —                     | ns   |
| $t_{d(\text{CLKL-ADV})}$     | XMC_CLK Low to XMC_AD Valid           | —                       | 12                    | ns   |
| $t_{d(\text{CLKL-ADIV})}$    | XMC_CLK Low to XMC_AD Invalid         | 0                       | —                     | ns   |
| $t_{su(\text{ADV-CLKH})}$    | XMC_AD Valid Data before XMC_CLK High | 6                       | —                     | ns   |
| $t_h(\text{CLKH-ADV})$       | XMC_AD Valid Data after XMC_CLK High  | $t_{\text{HCLK}} - 10$  | —                     | ns   |
| $t_{su(\text{NWAITV-CLKH})}$ | XMC_NWAIT Valid before XMC_CLK High   | 8                       | —                     | ns   |
| $t_h(\text{CLKH-NWAITV})$    | XMC_NWAIT Valid after XMC_CLK High    | 6                       | —                     | ns   |

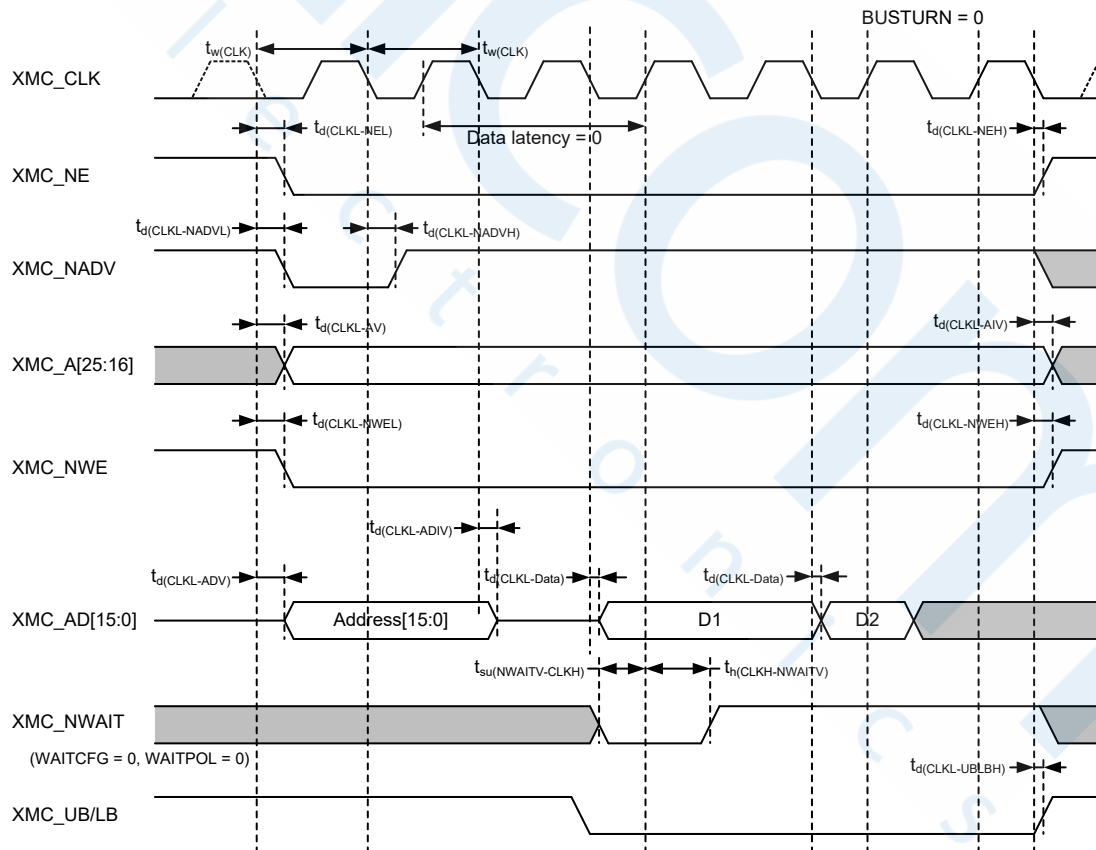


**Figure 21. Synchronous Multiplexed PSRAM / NOR Read Waveforms**



**Table 41. Synchronous Multiplexed PSRAM Write Timings**

| Symbol                       | Parameter                           | Min.                  | Max. | Unit |
|------------------------------|-------------------------------------|-----------------------|------|------|
| $t_{w(\text{CLK})}$          | XMC_CLK Period                      | 20                    | —    | ns   |
| $t_{d(\text{CLKL-NEL})}$     | XMC_CLK Low to XMC_NE Low           | —                     | 2    | ns   |
| $t_{d(\text{CLKL-NEH})}$     | XMC_CLK Low to XMC_NE High          | $t_{\text{HCLK}} + 2$ | —    | ns   |
| $t_{d(\text{CLKL-NADVL})}$   | XMC_CLK Low to XMC_NADV Low         | —                     | 4    | ns   |
| $t_{d(\text{CLKL-NADVH})}$   | XMC_CLK Low to XMC_NADV High        | 5                     | —    | ns   |
| $t_{d(\text{CLKL-AV})}$      | XMC_CLK Low to XMC_A Valid          | —                     | 0    | ns   |
| $t_{d(\text{CLKL-AIV})}$     | XMC_CLK Low to XMC_A Invalid        | $t_{\text{HCLK}} + 2$ | —    | ns   |
| $t_{d(\text{CLKL-NWEL})}$    | XMC_CLK Low to XMC_NWE Low          | —                     | 1    | ns   |
| $t_{d(\text{CLKL-NWEH})}$    | XMC_CLK Low to XMC_NWE High         | $t_{\text{HCLK}} + 1$ | —    | ns   |
| $t_{d(\text{CLKL-ADV})}$     | XMC_CLK Low to XMC_AD Valid         | —                     | 12   | ns   |
| $t_{d(\text{CLKL-ADIV})}$    | XMC_CLK Low to XMC_AD Invalid       | 3                     | —    | ns   |
| $t_{d(\text{CLKL-Data})}$    | XMC_AD Valid after XMC_CLK Low      | —                     | 6    | ns   |
| $t_{d(\text{CLKL-UBLBH})}$   | XMC_CLK Low to XMC_UB/LB High       | $t_{\text{HCLK}} + 1$ | —    | ns   |
| $t_{su(\text{NWAITV-CLKH})}$ | XMC_NWAIT Valid before XMC_CLK High | 7                     | —    | ns   |
| $t_h(\text{CLKH-NWAITV})$    | XMC_NWAIT Valid after XMC_CLK High  | 2                     | —    | ns   |



**Figure 22. Synchronous Multiplexed PSRAM Write Waveforms**

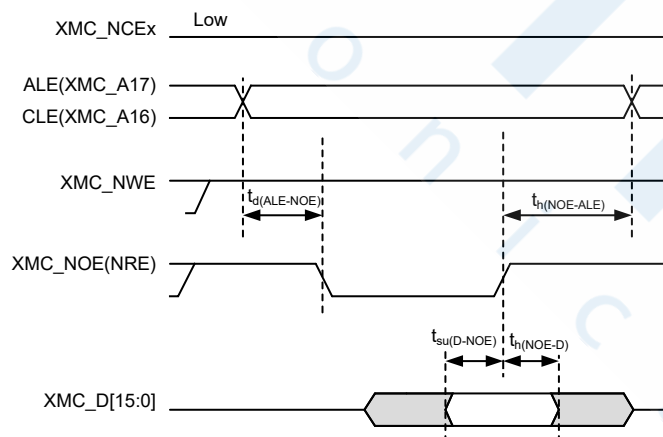
### NAND Controller Waveforms and Timings

The results shown in this table are obtained with the following XMC configuration:

- COM.XMC\_SetupTime = 0x01; (Note: STP in XMC\_BKxTMGMEM)
- COM.XMC\_WaitSetupTime = 0x03; (Note: OP in XMC\_BKxTMGMEM)
- COM.XMC\_HoldSetupTime = 0x02; (Note: HLD in XMC\_BKxTMGMEM)
- COM.XMC\_HiZSetupTime = 0x01; (Note: WRSTP in XMC\_BKxTMGMEM)
- ATT.XMC\_SetupTime = 0x01; (Note: STP in XMC\_BKxTMGATT)
- ATT.XMC\_WaitSetupTime = 0x03; (Note: OP in XMC\_BKxTMGATT)
- ATT.XMC\_HoldSetupTime = 0x02; (Note: HLD in XMC\_BKxTMGATT)
- ATT.XMC\_HiZSetupTime = 0x01; (Note: WRSTP in XMC\_BKxTMGATT)
- Bank = XMC\_Bank\_NAND;
- MemoryDataWidth = XMC\_MemoryDataWidth\_16b; (Note: Memory data width = 16 bits)
- ECC = XMC\_ECC\_Enable; (Note: enable ECC calculation)
- ECCPageSize = XMC\_ECCPageSize\_512Bytes; (Note: ECC page size = 512 Bytes)
- DLYCRSetupTime = 0; (Note: DLYCR in XMC\_BKxCTRL)
- DLYARSetupTime = 0; (Note: DLYAR in XMC\_BKxCTRL)

**Table 42. NAND Flash Read and Write Timings**

| Symbol           | Parameter                            | Min.              | Max.              | Unit |
|------------------|--------------------------------------|-------------------|-------------------|------|
| $t_{w(NOE)}$     | XMC_NWE Low Width                    | $4t_{HCLK} - 1.5$ | $4t_{HCLK} + 1.5$ | ns   |
| $t_{su(D-NOE)}$  | XMC_D Valid Data before XMC_NOE High | 25                | —                 | ns   |
| $t_{h(NOE-D)}$   | XMC_D Valid Data after XMC_NOE High  | 14                | —                 | ns   |
| $t_{d(ALE-NOE)}$ | XMC_ALE Valid before XMC_NOE Low     | —                 | $3t_{HCLK} + 2$   | ns   |
| $t_{h(NOE-ALE)}$ | XMC_NOE High to XMC_ALE Invalid      | $3t_{HCLK} + 4.5$ | —                 | ns   |
| $t_{w(NWE)}$     | XMC_NWE Low Width                    | $4t_{HCLK} - 1$   | $4t_{HCLK} + 2.5$ | ns   |
| $t_{v(NWE-D)}$   | XMC_NWE Low to XMC_D Valid           | —                 | 0                 | ns   |
| $t_{h(NWE-D)}$   | XMC_NWE High to XMC_D Invalid        | $10t_{HCLK} + 4$  | —                 | ns   |
| $t_{d(D-NWE)}$   | XMC_D Valid before XMC_NWE High      | $6t_{HCLK} + 12$  | —                 | ns   |
| $t_{d(ALE-NWE)}$ | XMC_ALE Valid before XMC_NWE Low     | —                 | $3t_{HCLK} + 1.5$ | ns   |
| $t_{h(NWE-ALE)}$ | XMC_NWE High to XMC_ALE Invalid      | $3t_{HCLK} + 4.5$ | —                 | ns   |



**Figure 23. NAND Controller Read Waveforms**

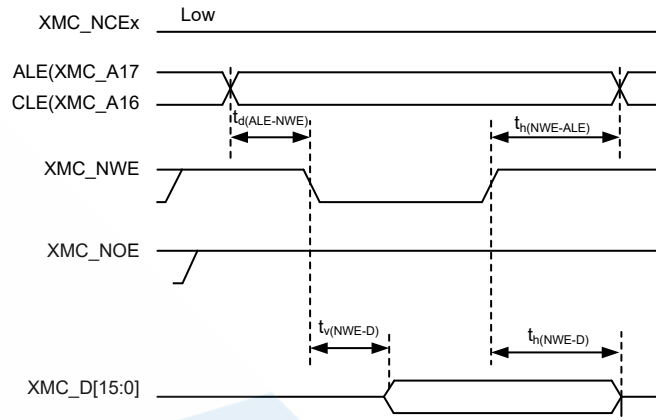


Figure 24. NAND Controller Write Waveforms

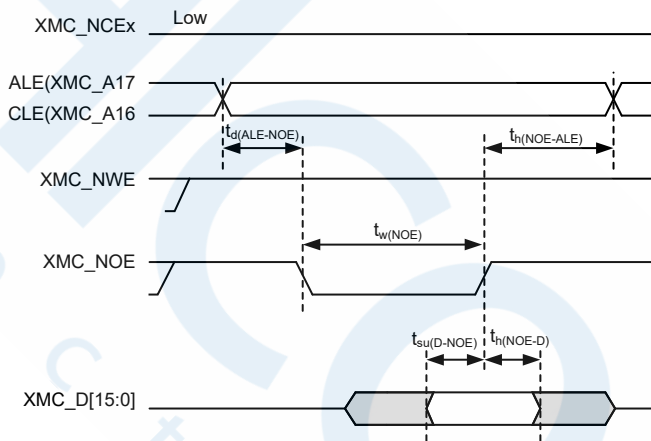


Figure 25. NAND Controller Common Memory Read Waveforms

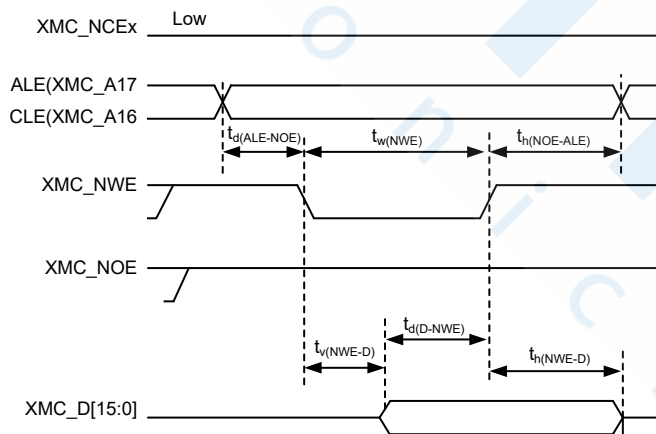


Figure 26. NAND Controller for Common Memory Write Waveforms

## TMR Timer Characteristics

The parameters given in the table below are Data based on characterization results only.

**Table 43. TMR Characteristics**

| Symbol         | Parameter                                    | Conditions                      | Min. | Max.            | Unit          |
|----------------|--|---------------------------------|------|-----------------|---------------|
| $t_{res(TMR)}$ | Timer Resolution Time                        | —                               | 1    | —               | $t_{TMRxCLK}$ |
|                |  | $f_{TMRxCLK} = 240 \text{ MHz}$ | 4.17 | —               | ns            |
| $f_{EXT}$      | Timer External Clock Frequency on CH1 to CH4 | —                               | 0    | $f_{TMRxCLK}/2$ | MHz           |
|                |  |                                 |      | 50              | MHz           |

## SPI / I<sup>2</sup>S Characteristics

The SPI and I<sup>2</sup>S parameters are listed in the following tables.

**Table 44. SPI Characteristics**

| Symbol                                     | Parameter                             | Conditions   | Min.        | Max.        | Unit |
|--|---------------------------------------|--|-------------|-------------|------|
| $f_{SCK} (1/t_{c(SCK)})^{(1)}$             | SPI Clock Frequency <sup>(2)(3)</sup> | $V_{DD} = 3.3 \text{ V}, T_A = 25 \text{ }^\circ\text{C}$    | —           | 50          | MHz  |
|  |                                       | $V_{DD} = 3.3 \text{ V}, T_A = 105 \text{ }^\circ\text{C}$   | —           | 36          |      |
|  |                                       | $V_{DD} = 2.6 \text{ V}, T_A = 105 \text{ }^\circ\text{C}$   | —           | 30          |      |
| $t_{r(SCK)}$<br>$t_{f(SCK)}$               | SPI Clock Rising and Falling Time     | Capacitive load: C = 30 pF                                   | —           | 8           | ns   |
| $t_{su(CS)}^{(1)}$                         | CS Setup Time                         | Slave mode   | $4t_{PCLK}$ | —           | ns   |
| $t_{h(CS)}^{(1)}$                          | CS Hold Time                          | Slave mode   | $2t_{PCLK}$ | —           | ns   |
| $t_{w(SCKH)}^{(1)}$<br>$t_{w(SCKL)}^{(1)}$ | SCK High and Low Time                 | Master mode, $f_{PCLK} = 100 \text{ MHz}$ ,<br>prescaler = 4 | 15          | 25          | ns   |
| $t_{su(MI)}^{(1)}$                         | Data Input Setup Time                 | Master mode  | 5           | —           | ns   |
| $t_{su(SI)}^{(1)}$                         |                                       | Slave mode   | 5           | —           |      |
| $t_{h(MI)}^{(1)}$                          | Data Input Setup Time                 | Master mode  | 5           | —           | ns   |
| $t_{h(SI)}^{(1)}$                          |                                       | Slave mode   | 4           | —           |      |
| $t_{a(SO)}^{(1)(4)}$                       | Data Output Access Time               | Slave mode, $f_{PCLK} = 20 \text{ MHz}$                      | 0           | $3t_{PCLK}$ | ns   |
| $t_{dis(SO)}^{(1)(5)}$                     | Data Output Disable Time              | Slave mode   | 2           | 10          | ns   |
| $t_{v(SO)}^{(1)}$                          | Data Output Valid Time                | Slave mode (after enable edge)                               | —           | 25          | ns   |
| $t_{v(MO)}^{(1)}$                          | Data Output Valid Time                | Master mode (after enable edge)                              | —           | 5           | ns   |
| $t_{h(SO)}^{(1)}$                          | Data Output Hold Time                 | Slave mode (after enable edge)                               | 15          | —           | ns   |
| $t_{h(MO)}^{(1)}$                          |                                       | Master mode (after enable edge)                              | 2           | —           |      |

Note: 1. Data based on characterization results only, not tested in production.

2. The maximum SPI clock frequency should not exceed  $f_{PCLK}/2$ .

3. The maximum SPI clock frequency is highly related with devices and the PCB layout.

4. Min time is for the minimum time to drive the output and the max time is for the maximum time to validate the data.

5. Min time is for the minimum time to invalidate the output and the max time is for the maximum time to put the data in Hi-Z.

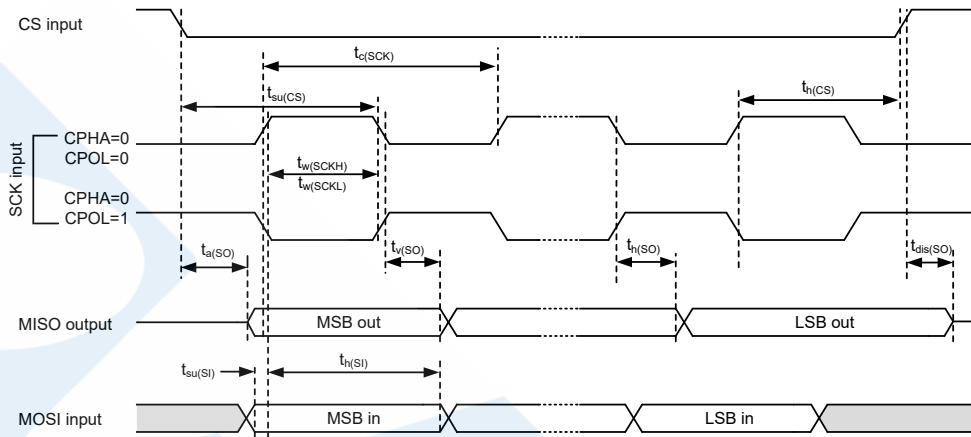


Figure 27. SPI Timing Diagram – Slave Mode and CPHA = 0

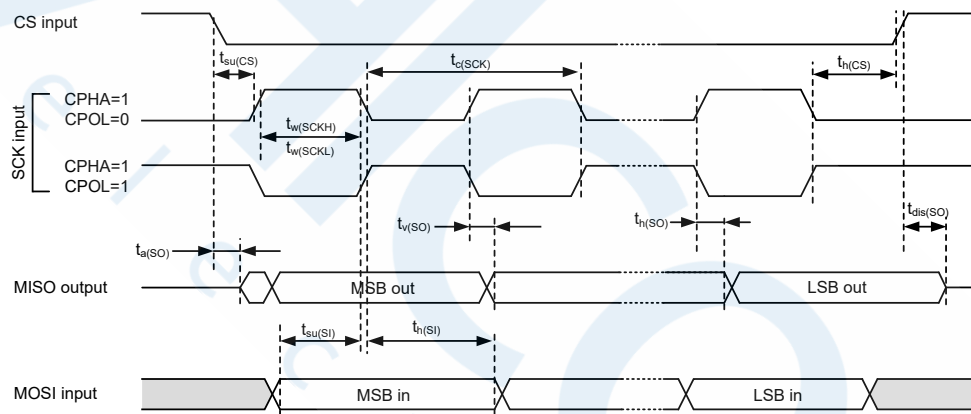


Figure 28. SPI Timing Diagram – Slave Mode and CPHA = 1

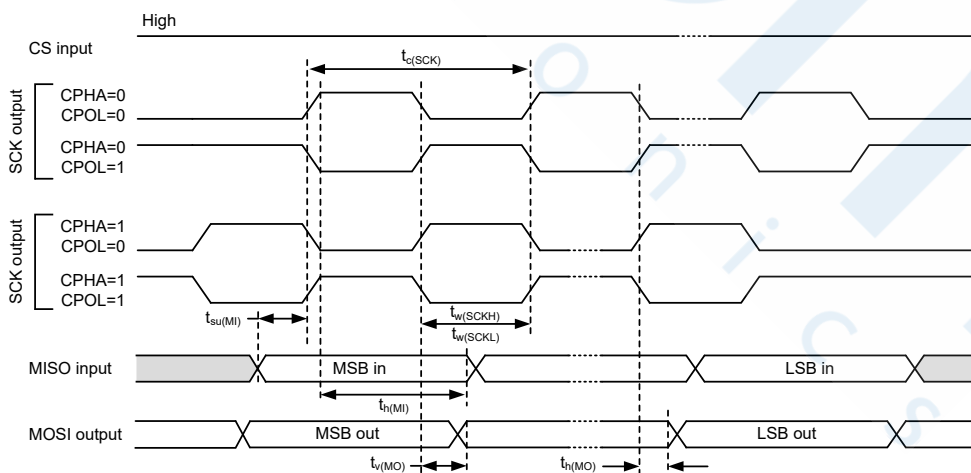
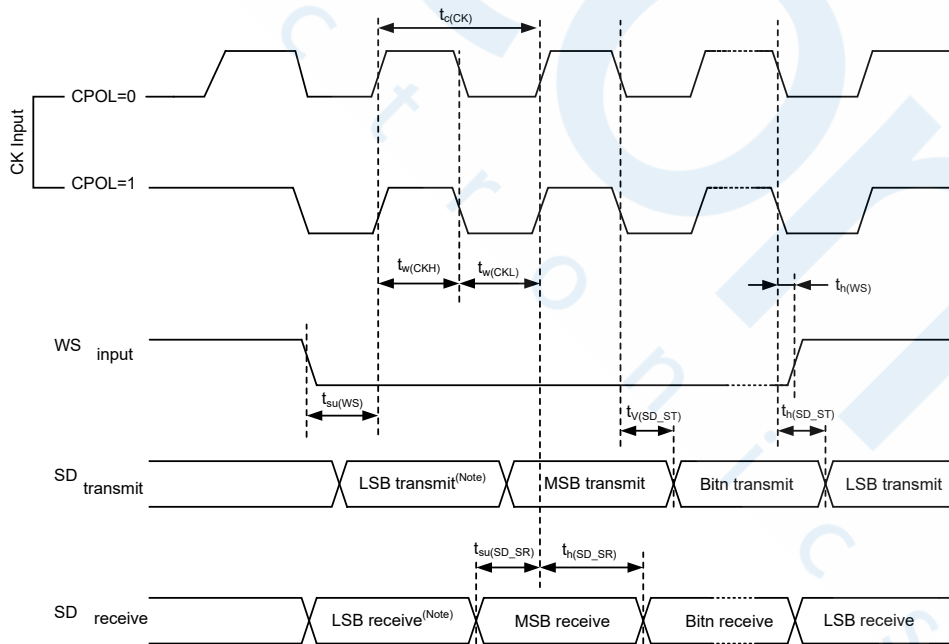


Figure 29. SPI Timing Diagram – Master Mode

**Table 45. I<sup>2</sup>S Characteristics**

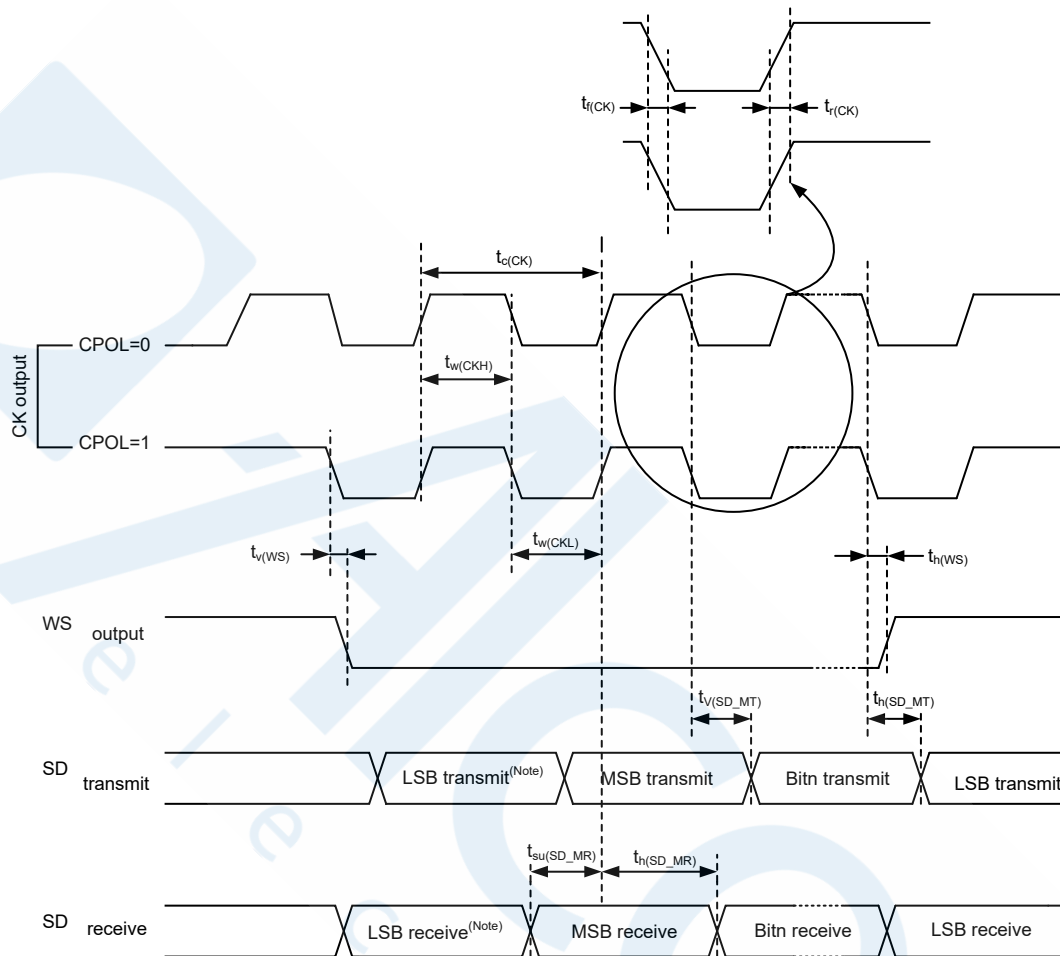
| Symbol   | Parameter                                      | Conditions   | Min.         | Max.  | Unit |
|--|--|--|--------------|-------|------|
| $f_{CK}$<br>$1/t_{c(CK)}$                            | I <sup>2</sup> S Clock Frequency               | Master mode (data: 16 bits,<br>audio frequency = 48 kHz) | 1.522        | 1.525 | MHz  |
|  |  | Slave mode   | 0            | 6.5   |      |
| $t_{r(CK)}$<br>$t_{f(CK)}$                           | I <sup>2</sup> S Clock Rising and Falling Time | Capacitive load: C = 50 pF                               | —            | 8     |      |
| $t_{v(WS)}^{(1)}$                                    | WS Valid Time                                  | Master mode  | 3            | —     |      |
| $t_{h(WS)}^{(1)}$                                    | WS Hold Time                                   | Master mode  | 2            | —     |      |
| $t_{su(WS)}^{(1)}$                                   | WS Setup Time                                  | Slave mode   | 4            | —     |      |
| $t_{h(WS)}^{(1)}$                                    | WS Hold Time                                   | Slave mode   | 0            | —     |      |
| $t_{w(CKH)}^{(1)}$<br>$t_{w(CKL)}^{(1)}$             | CK High and Low Time                           | Master $f_{PCLK} = 16$ MHz,<br>audio frequency = 48 kHz  | 312.5<br>345 | —     |      |
| $t_{su(SD\_MR)}^{(1)}$<br>$t_{su(SD\_SR)}^{(1)}$     | Data Input Setup Time                          | Master receiver<br>Slave receiver                        | 6.5<br>1.5   | —     | ns   |
| $t_{h(SD\_MR)}^{(1)(2)}$<br>$t_{h(SD\_SR)}^{(1)(2)}$ | Data Input Hold Time                           | Master receiver<br>Slave receiver                        | 0<br>0.5     | —     |      |
| $t_{v(SD\_ST)}^{(1)(2)}$                             | Data Output Valid Time                         | Slave transmitter (after enable edge)                    | —            | 18    |      |
| $t_{h(SD\_ST)}^{(1)}$                                | Data Output Hold Time                          | Slave transmitter (after enable edge)                    | 11           | —     |      |
| $t_{v(SD\_MT)}^{(1)(2)}$                             | Data Output Valid Time                         | Master transmitter (after enable edge)                   | —            | 3     |      |
| $t_{h(SD\_MT)}^{(1)}$                                | Data Output Hold Time                          | Master transmitter (after enable edge)                   | 0            | —     |      |

Note: 1. Data based on design and/or characterization results, not tested in production.  
2. Depends on  $f_{PCLK}$ . For example, if  $f_{PCLK}=8$  MHz, then  $t_{PCLK} = 1/f_{PCLK} = 125$  ns.



**Figure 30. I<sup>2</sup>S Slave Timing Diagram (Philips Protocol)**

Note: LSB transmit/receive of the previously transmitted byte. No LSB transmit/receive is sent before the first byte.



**Figure 31. I<sup>2</sup>S Master Timing Diagram (Philips Protocol)**

Note: LSB transmit/receive of the previously transmitted byte. No LSB transmit/receive is sent before the first byte.

## I<sup>2</sup>C Interface Characteristics

GPIO pins SDA and SCL have limitation as follows: they are not “true” open-drain. When configured as open-drain, the PMOS connected between the GPIO pin and V<sub>DD</sub> is disabled, but is still present.

The I<sup>2</sup>C bus interface can support standard mode (max. 100 kHz) and fast mode (max. 400 kHz). The I<sup>2</sup>C bus frequency can be increased up to 1 MHz.

## SDIO Characteristics

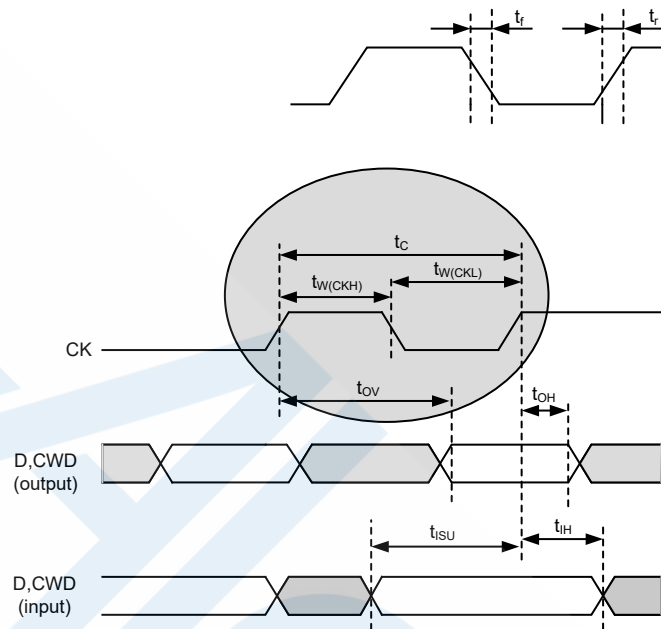


Figure 32. SDIO High-Speed Mode

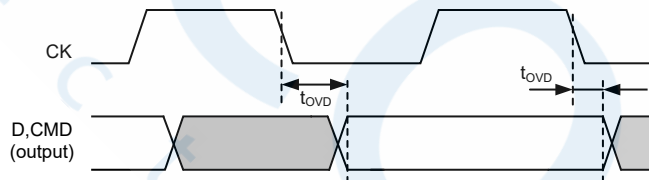


Figure 33. SD Default Mode



**Table 46. SD / MMC Characteristics**

| Symbol   | Parameter                             | Conditions        | Min. | Max. | Unit |
|--|---------------------------------------|-------------------|------|------|------|
| $f_{PP}$   | Clock Frequency in Data Transfer Mode | —                 | 0    | 48   | MHz  |
| $t_{W(CKL)}$   | Clock Low Time                        | $f_{PP} = 16$ MHz | 32   | —    | ns   |
| $t_{W(CKH)}$   | Clock High Time                       | $f_{PP} = 16$ MHz | 30   | —    |      |
| $t_r$  | Clock Rise Time                       | —                 | —    | 4    |      |
| $t_f$  | Clock Fall Time                       | —                 | —    | 5    |      |
| <b>CMD, D Inputs (Referenced to CK)</b>                                      |                                       |                   |      |      |      |
| $t_{ISU}$  | Input Setup Time                      | —                 | 2    | —    | ns   |
| $t_{IH}$   | Input Hold Time                       | —                 | 0    | —    |      |
| <b>CMD, D Outputs (Referenced to CK) in MMC and SD HS Mode</b>               |                                       |                   |      |      |      |
| $t_{OV}$   | Output Valid Time                     | —                 | —    | 6    | ns   |
| $t_{OH}$   | Output Hold Time                      | —                 | 0    | —    |      |
| <b>CMD, D Outputs (Referenced to CK) in SD Default Mode<sup>(Note)</sup></b> |                                       |                   |      |      |      |
| $t_{OVD}$  | Output Valid Default Time             | —                 | —    | 7    | ns   |
| $t_{OHD}$  | Output Hold Default Time              | —                 | 0.5  | —    |      |

Note: Refer to SDIO\_CLKCTRL, the SDIO clock control register to control the CK output.

## USBFS Characteristics

**Table 47. USBFS Startup Time**

| Symbol                 | Parameter                      | Max. | Unit    |
|------------------------|--------------------------------|------|---------|
| $t_{STARTUP}^{(Note)}$ | USBFS Transceiver Startup Time | 1    | $\mu$ s |

Note: Data based on characterization results only, not tested in production.

**Table 48. USBFS DC Electrical Characteristics**

| Symbol        | Parameter                 | Conditions                      | Min. <sup>(1)</sup>                              | Typ.               | Max. <sup>(1)</sup> | Unit       |   |
|---------------|---------------------------|---------------------------------|--|--------------------|---------------------|------------|---|
| Input levels  | $V_{DD}$                  | USBFS Operating Voltage         | —  | 3.0 <sup>(2)</sup> | —                   | 3.6        | V |
|               | $V_{DI}^{(3)}$            | Differential Input Sensitivity  | I (USBFS_D+, USBFS_D-)                           | 0.2                | —                   | —          | V |
|               | $V_{CM}^{(3)}$            | Differential Common Mode Range  | Includes $V_{DI}$ range                          | 0.8                | —                   | 2.5        |   |
|               | $V_{SE}^{(3)}$            | Single Ended Receiver Threshold | —  | 1.3                | —                   | 2.0        |   |
| Output levels | $V_{OL}$                  | Static Output Level Low         | $R_L$ of 1.24 k $\Omega$ to 3.6 V <sup>(4)</sup> | —                  | —                   | 0.3        | V |
|               | $V_{OH}$                  | Static Output Level High        | $R_L$ of 15 k $\Omega$ to $V_{SS}^{(4)}$         | 2.8                | —                   | 3.6        |   |
| $R_{PU}$      | USBFS_D+ Internal Pull-up | $V_{IN} = V_{SS}$               | 0.97   | 1.24               | 1.58                | k $\Omega$ |   |

Note: 1. All the voltages are measured from the local ground potential.

2. The HT32F49365/HT32F49395 USB functionality is ensured down to 2.7 V but not the full USB electrical characteristics which are degraded in the 2.7 to 3.0 V  $V_{DD}$  voltage range.

3. Data based on characterization results only, not tested in production.

4.  $R_L$  is the load connected on the USB drivers.

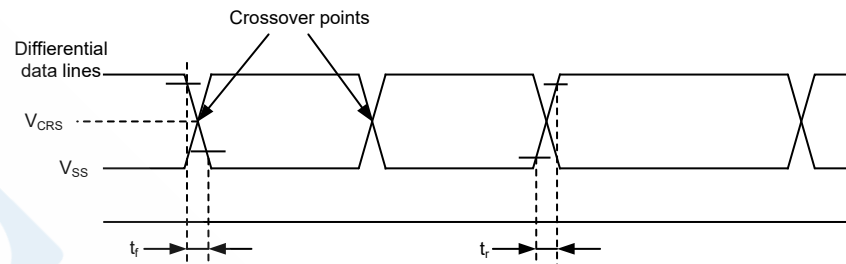


Figure 34. USBFS Timings: Definition of Data Signal Rising and Falling Time

Table 49. USBFS Electrical Characteristics

| Symbol    | Parameter                       | Conditions       | Min. <sup>(1)</sup> | Max. <sup>(1)</sup> | Unit |
|-----------|---------------------------------|------------------|---------------------|---------------------|------|
| $t_r$     | Rising Time <sup>(2)</sup>      | $C_L \leq 50$ pF | 4                   | 20                  | ns   |
| $t_f$     | Falling Time <sup>(2)</sup>     | $C_L \leq 50$ pF | 4                   | 20                  | ns   |
| $t_{rfm}$ | Rising/Falling Time Matching    | $t_r/t_f$        | 90                  | 110                 | %    |
| $V_{CRS}$ | Output Signal Crossover Voltage | —                | 1.3                 | 2.0                 | V    |

Note: 1. Data based on characterization results only, not tested in production.

2. Measured from 10% to 90% of the data signal. For more detailed information, please refer to USB Specification - Chapter 7 (version 2.0).

## 12-bit ADC Characteristics

Unless otherwise specified, the parameters given in the table below are preliminary values derived from tests performed under ambient temperature,  $f_{PCLK2}$  frequency and  $V_{DDA}$  supply voltage conditions summarized in Table 13.

Note: It is recommended to perform a calibration after each power-up.

Table 50. ADC Characteristics

| Symbol                    | Parameter  | Conditions         | Min.                                       | Typ.               | Max.       | Unit        |
|---------------------------|--|--------------------|--|--------------------|------------|-------------|
| $V_{DDA}$                 | Power Supply                                       | —                  | 2.6  | —                  | 3.6        | V           |
| $V_{REF+}$                | Positive Reference Voltage <sup>(3)</sup>          | —                  | 2.0  | —                  | $V_{DDA}$  | V           |
| $I_{DDA}$                 | Current on the $V_{DDA}$ Input Pin                 | —                  | —  | 380 <sup>(1)</sup> | 445        | $\mu$ A     |
| $I_{VREF}$                | Current on the $V_{REF+}$ Input Pin <sup>(3)</sup> | —                  | —  | 200 <sup>(1)</sup> | 220        | $\mu$ A     |
| $f_{ADC}$                 | ADC Clock Frequency                                | —                  | 0.6  | —                  | 28         | MHz         |
| $f_S$ <sup>(2)</sup>      | Sampling Rate                                      | —                  | 0.05                                       | —                  | 2          | MHz         |
| $f_{TRIG}$ <sup>(2)</sup> | External Trigger Frequency                         | $f_{ADC} = 28$ MHz | —  | —                  | 1.65       | MHz         |
|                           |  | —                  | —  | —                  | 17         | $1/f_{ADC}$ |
| $V_{AIN}$                 | Conversion Voltage Range <sup>(3)</sup>            | —                  | 0 ( $V_{SSA}$ or $V_{REF}$ tied to ground) |                    | $V_{REF+}$ | V           |
| $R_{AIN}$ <sup>(2)</sup>  | External Input Impedance                           | —                  | See Table 51 and Table 52 for details      |                    |            | $\Omega$    |
| $C_{ADC}$ <sup>(2)</sup>  | Internal Sample and Hold Capacitor                 | —                  | —  | 10                 | —          | pF          |
| $t_{CAL}$ <sup>(2)</sup>  | Calibration Time                                   | $f_{ADC} = 28$ MHz | 6.61                                       |                    |            | $\mu$ s     |
|                           |  | —                  | 185  |                    |            | $1/f_{ADC}$ |

| Symbol           | Parameter  | Conditions                 | Min.  | Typ. | Max.             | Unit          |
|------------------|--|----------------------------|---|------|------------------|---------------|
| $t_{lat}^{(2)}$  | Injection Trigger Conversion Latency               | $f_{ADC} = 28 \text{ MHz}$ | —   | —    | 107              | ns            |
|                  |  | —                          | —   | —    | 3 <sup>(4)</sup> | $1/f_{ADC}$   |
| $t_{latr}^{(2)}$ | Regular Trigger Conversion Latency                 | $f_{ADC} = 28 \text{ MHz}$ | —   | —    | 71.4             | $\mu\text{s}$ |
|                  |  | —                          | —   | —    | 2 <sup>(4)</sup> | $1/f_{ADC}$   |
| $t_s^{(2)}$      | Sampling Time                                      | $f_{ADC} = 28 \text{ MHz}$ | 0.053   | —    | 8.55             | $\mu\text{s}$ |
|                  |  | —                          | 1.5   | —    | 239.5            | $1/f_{ADC}$   |
| $t_{STAB}^{(2)}$ | Power-up Time                                      | —                          | 42  |      |                  | $1/f_{ADC}$   |
| $t_{CONV}^{(2)}$ | Total Conversion Time<br>(including Sampling Time) | $f_{ADC} = 28 \text{ MHz}$ | 0.5   | —    | 9                | $\mu\text{s}$ |
|                  |  | —                          | 14 to 252 ( $t_s$ for sampling + 12.5 for successive approximation) |      |                  | $1/f_{ADC}$   |

Note: 1. Data based on design only, not tested in production.

2. Data based on characterization results only, not tested in production.

3.  $V_{REF+}$  can be internally connected to  $V_{DDA}$  and  $V_{REF-}$  can be internally connected to  $V_{SSA}$ , depending on the package.

4. For external triggers, a delay of  $1/f_{PCLK2}$  must be added to the latency specified in Table 50.

The following two tables are used to determine the maximum external impedance allowed for an error below 1/4 of LSB.

**Table 51. Max.  $R_{AIN}$  for  $f_{ADC} = 14 \text{ MHz}$**

| $T_s$ (Cycle) | $t_s$ ( $\mu\text{s}$ ) | Max. $R_{AIN}$ ( $k\Omega$ ) <sup>(Note)</sup> |
|---------------|-------------------------|--|
| 1.5           | 0.11                    | 0.25   |
| 7.5           | 0.54                    | 1.3  |
| 13.5          | 0.96                    | 2.5  |
| 28.5          | 2.04                    | 5.0  |
| 41.5          | 2.96                    | 8.0  |
| 55.5          | 3.96                    | 10.5   |
| 71.5          | 5.11                    | 13.5   |
| 239.5         | 17.11                   | 40   |

Note: Data based on characterization results only.

**Table 52. Max.  $R_{AIN}$  for  $f_{ADC} = 28 \text{ MHz}$**

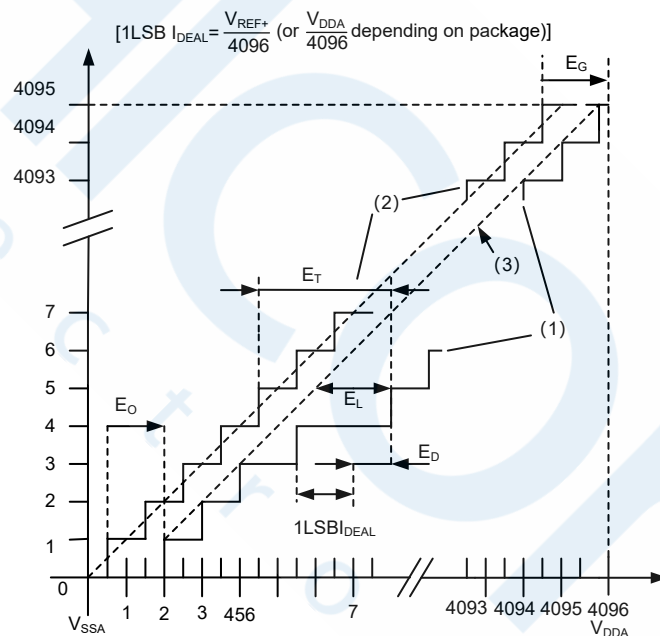
| $T_s$ (Cycle) | $t_s$ ( $\mu\text{s}$ ) | Max. $R_{AIN}$ ( $k\Omega$ ) <sup>(Note)</sup> |
|---------------|-------------------------|--|
| 1.5           | 0.05                    | 0.1  |
| 7.5           | 0.27                    | 0.6  |
| 13.5          | 0.48                    | 1.2  |
| 28.5          | 1.02                    | 2.5  |
| 41.5          | 1.48                    | 4.0  |
| 55.5          | 1.98                    | 5.2  |
| 71.5          | 2.55                    | 7.0  |
| 239.5         | 8.55                    | 20   |

Note: Data based on characterization results only.

**Table 53. ADC Accuracy<sup>(1)</sup>**

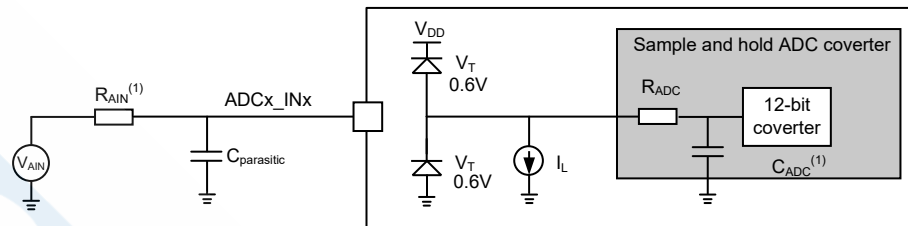
| Symbol         | Parameter                    | Test Conditions  | Typ. <sup>(2)</sup> | Max. <sup>(2)</sup> | Unit |
|----------------|------------------------------|--|---------------------|---------------------|------|
| E <sub>T</sub> | Total Unadjusted Error       | f <sub>PCLK2</sub> = 56 MHz, f <sub>ADC</sub> = 28 MHz,<br>R <sub>AIN</sub> < 10 kΩ, V <sub>DDA</sub> = 3.0 to 3.6 V,<br>T <sub>A</sub> = 25 °C, Measurements made after<br>ADC calibration V <sub>REF+</sub> = V <sub>DDA</sub> | ±1.5                | ±2.5                | LSB  |
| E <sub>O</sub> | Offset Error                 |  | +0.5                | ±1.5                |      |
| E <sub>G</sub> | Gain Error                   |  | +1                  | +2/-0.5             |      |
| E <sub>D</sub> | Differential Linearity Error |  | ±0.6                | ±0.9                |      |
| E <sub>L</sub> | Integral Linearity Error     |  | ±0.8                | ±1.5                |      |
| E <sub>T</sub> | Total Unadjusted Error       | f <sub>PCLK2</sub> = 56 MHz, f <sub>ADC</sub> = 28 MHz,<br>R <sub>AIN</sub> < 10 kΩ, V <sub>DDA</sub> = 2.6 to 3.6 V,<br>Measurements made after ADC<br>calibration  | ±2                  | ±4                  | LSB  |
| E <sub>O</sub> | Offset Error                 |  | +0.5                | ±2                  |      |
| E <sub>G</sub> | Gain Error                   |  | +1                  | +2.5/<br>-1.5       |      |
| E <sub>D</sub> | Differential Linearity Error |  | ±0.6                | ±1.2                |      |
| E <sub>L</sub> | Integral Linearity Error     |  | ±1                  | ±2                  |      |

Note: 1. ADC DC accuracy values are measured after internal calibration.  
2. Data based on characterization results only, not tested in production.



**Figure 35. ADC Accuracy Characteristics**

- Note: 1. Example of an actual transfer curve.  
2. Ideal transfer curve.  
3. End point correlation line.  
4. E<sub>T</sub> = Maximum deviation between the actual and the ideal transfer curves.  
E<sub>O</sub> = Deviation between the first actual transition and the first ideal one.  
E<sub>G</sub> = Deviation between the last ideal transition and the last actual one.  
E<sub>D</sub> = Maximum deviation between actual steps and the ideal one.  
E<sub>L</sub> = Maximum deviation between any actual transition and the end point correlation line.



**Figure 36. Typical Connection Diagram Using the ADC**

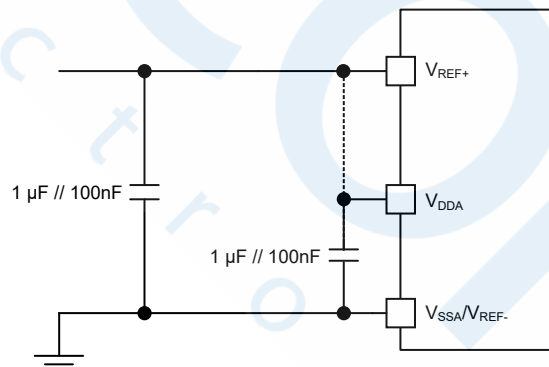
- Note: 1. Refer to Table 50 for the values of  $R_{AIN}$  and  $C_{ADC}$ .  
2.  $C_{parasitic}$  represents the capacitance of the PCB (dependent on soldering and PCB layout quality) plus the pad capacitance (roughly 7 pF). A high  $C_{parasitic}$  value will downgrade conversion accuracy. To remedy this,  $f_{ADC}$  should be reduced.

### General PCB Design Guidelines

Power supply decoupling should be performed as shown in Figure 37 and Figure 38 depending on whether  $V_{REF+}$  is connected to  $V_{DDA}$  or not. The 100 nF capacitors should be ceramic (good quality). They should be placed them as close as possible to the chip.

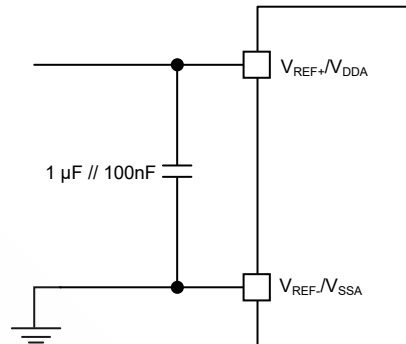
If HEXT is enabled while ADC uses any input channel of ADC123\_IN10~13, following PCB layout guide line below benefits to isolate the high frequency interference from HEXT emitting to ADC input signals nearby.

- Use different PCB layers to route ADC\_IN signal apart from HEXT path
- Do not route ADC\_IN signals and HEXT path parallel



**Figure 37. Power Supply and Reference Decoupling ( $V_{REF+}$  Not Connected to  $V_{DDA}$ )**

Note:  $V_{REF+}$  and  $V_{REF-}$  inputs are available only on 100-pin package.



**Figure 38. Power Supply and Reference Decoupling (V<sub>REF+</sub> Connected to V<sub>DDA</sub>)**

Note: V<sub>REF+</sub> and V<sub>REF-</sub> inputs are available only on 100-pin package.

## Internal Reference Voltage (V<sub>INTRV</sub>) Characteristics

**Table 54. Internal Reference Voltage Characteristics**

| Symbol                               | Parameter   | Conditions | Min. | Typ. | Max. | Unit   |
|--------------------------------------|---|------------|------|------|------|--------|
| V <sub>INTRV</sub>                   | Internal Reference Voltage                                    | —          | 1.16 | 1.20 | 1.24 | V      |
| T <sub>Coeff</sub> <sup>(Note)</sup> | Temperature Coefficient                                       | —          | —    | —    | 120  | ppm/°C |
| T <sub>S_VINTRV</sub>                | ADC Sampling Time when Reading the Internal Reference Voltage | —          | —    | 5.1  | 17.1 | µs     |

Note: Data based on characterization results only, not tested in production.

## Temperature Sensor (V<sub>TS</sub>) Characteristics

**Table 55. Temperature Sensor Characteristics**

| Symbol                             | Parameter                                      | Min.  | Typ.  | Max.  | Unit  |
|------------------------------------|--|-------|-------|-------|-------|
| T <sub>L</sub> <sup>(1)</sup>      | V <sub>TS</sub> Linearity with Temperature     | —     | ±2    | ±4    | °C    |
| Avg_Slope <sup>(1)(2)</sup>        | Average Slope                                  | -4.11 | -4.26 | -4.41 | mV/°C |
| V <sub>25</sub> <sup>(1)(2)</sup>  | Voltage at 25 °C                               | 1.19  | 1.28  | 1.37  | V     |
| t <sub>START</sub> <sup>(3)</sup>  | Startup Time                                   | —     | —     | 100   | µs    |
| T <sub>S_temp</sub> <sup>(3)</sup> | ADC Sampling Time when Reading the Temperature | —     | 8.6   | 17.1  | µs    |

Note: 1. Data based on design, not tested in production.

2. The temperature sensor output voltage changes linearly with temperature. The offset of this line varies from chip to chip due to process variation (up to 50 °C from one chip to another). The internal temperature sensor is more suited to applications that detect temperature variations instead of absolute temperatures. If accurate temperature readings are needed, an external temperature sensor part should be used.

3. Data based on characterization results only, not tested in production.

Obtain the temperature using the following formula:

$$\text{Temperature (in } ^\circ\text{C)} = \{(V_{25} - V_{TS}) / \text{Avg\_Slope}\} + 25.$$

Where,

V<sub>25</sub> = V<sub>TS</sub> value for 25° C and

Avg\_Slope = Average Slope for curve between Temperature vs. V<sub>TS</sub> (given in mV/°C).

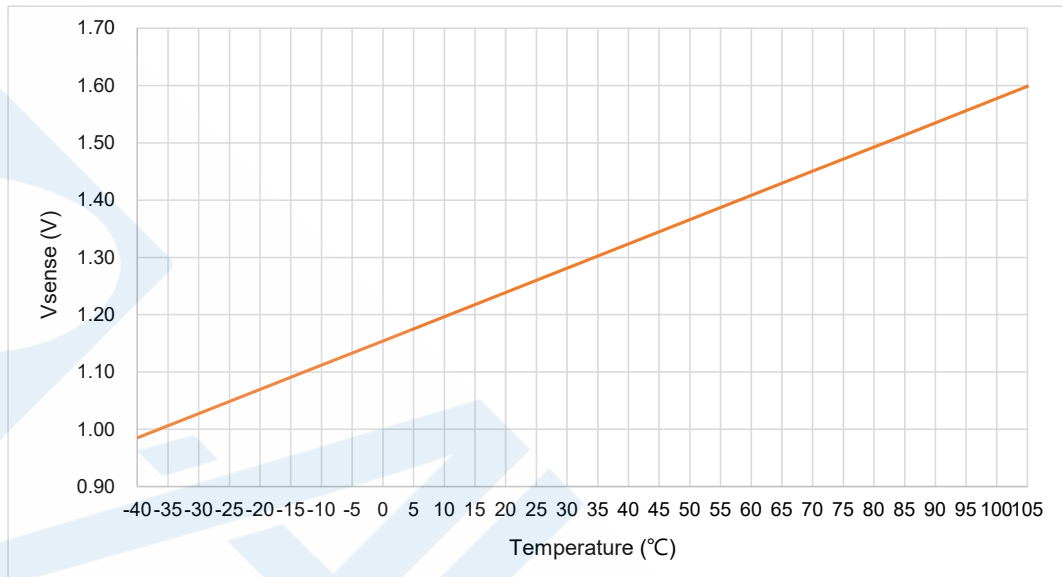


Figure 39. V<sub>TS</sub> vs. Temperature

## 12-bit DAC Characteristics

Table 56. DAC Characteristics

| Symbol                           | Parameter   | Comments                                | Min. | Typ. | Max.                       | Unit |
|----------------------------------|---|---|------|------|----------------------------|------|
| V <sub>DDA</sub>                 | Analog Supply Voltage   | —                                       | 2.6  | —    | 3.6                        | V    |
| V <sub>REF+</sub> <sup>(3)</sup> | Reference Supply Voltage  | —                                       | 2.0  | —    | 3.6                        | V    |
| V <sub>SSA</sub>                 | Ground  | —                                       | 0    | —    | 0                          | V    |
| R <sub>LOAD</sub> <sup>(1)</sup> | Resistive Load with Buffer ON   | —                                       | 5    | —    | —                          | kΩ   |
| R <sub>O</sub> <sup>(2)</sup>    | Impedance Output with Buffer OFF  | —                                       | —    | 13.2 | 16                         | kΩ   |
| C <sub>LOAD</sub> <sup>(1)</sup> | Capacitive Load   | —                                       | —    | —    | 50                         | pF   |
| DAC_OUT <sup>(1)</sup>           | Lower DAC_OUT Voltage with Buffer ON  | —                                       | 0.15 | —    | —                          | V    |
|                                  | Higher DAC_OUT Voltage with Buffer ON   | —                                       | —    | —    | V <sub>REF+</sub> - 0.2    | V    |
|                                  | Lower DAC_OUT Voltage with Buffer OFF   | —                                       | —    | 0.5  | 3.5                        | mV   |
|                                  | Higher DAC_OUT Voltage with Buffer OFF  | —                                       | —    | —    | V <sub>REF+</sub> - 1.5 mV | V    |
| I <sub>DDA</sub>                 | DC Current Consumption in Quiescent Mode  | With no load, V <sub>REF+</sub> = 3.6 V | —    | 480  | 625                        | μA   |
| I <sub>VREF</sub> <sup>(3)</sup> | DC Current Consumption in Quiescent Mode  | With no load, V <sub>REF+</sub> = 3.6 V | —    | 330  | 340                        | μA   |
| DNL <sup>(2)</sup>               | Differential Non Linearity  | —                                       | —    | ±0.4 | ±0.8                       | LSB  |
| INL <sup>(2)</sup>               | Integral Non Linearity (difference between measured value at Code (i) and a line drawn between DAC_OUT min. and DAC_OUT max.) | —                                       | —    | ±0.8 | ±1.5                       | LSB  |

| Symbol                    | Parameter   | Comments   | Min. | Typ. | Max. | Unit          |
|---------------------------|---|--|------|------|------|---------------|
| Offset <sup>(2)</sup>     | Offset Error (difference between measured value at Code (0x800) and the ideal value = $V_{REF+}/2$ )        | —  | —    | 15   | 30   | mV            |
|                           |   |  | —    | 20   | 35   | LSB           |
| Gain error <sup>(2)</sup> | Gain Error  | —  | —    | 0.1  | 0.25 | %             |
| $t_{SETTLING}$            | Settling Time   | $C_{LOAD} \leq 50 \text{ pF}$ ,<br>$R_{LOAD} \geq 5 \text{ k}\Omega$ | —    | 1    | 4    | $\mu\text{s}$ |
| Update rate               | Max. Frequency for a Correct DAC_OUT Change when Small Variation in the Input code (from code i to i+1 LSB) | $C_{LOAD} \leq 50 \text{ pF}$ ,<br>$R_{LOAD} \geq 5 \text{ k}\Omega$ | —    | —    | 1    | MSPS          |
| $t_{WAKEUP}$              | Wakeup Time from Off State (setting the EN bit in the DAC Control Register)                                 | $C_{LOAD} \leq 50 \text{ pF}$ ,<br>$R_{LOAD} \geq 5 \text{ k}\Omega$ | —    | 1.2  | 4    | $\mu\text{s}$ |

Note: 1. Data based on design only, not tested in production.

2. Data based on characterization results only, not tested in production.

3.  $V_{REF+}$  can be internally connected to  $V_{DDA}$  and  $V_{REF-}$  can be internally connected to  $V_{SSA}$ , depending on the package.



## 6 Package Information

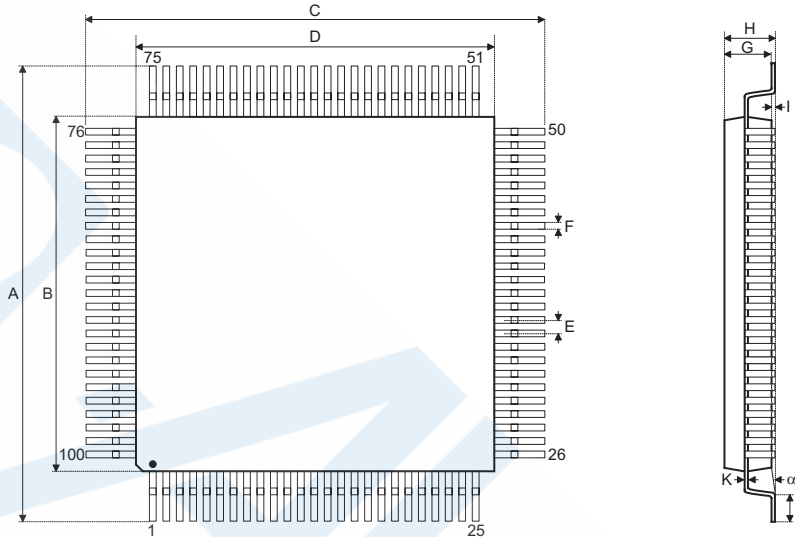
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Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the [Holtek website](#) for the latest version of the [Package Information](#).

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- The Operation Instruction of Packing Materials
- Carton information

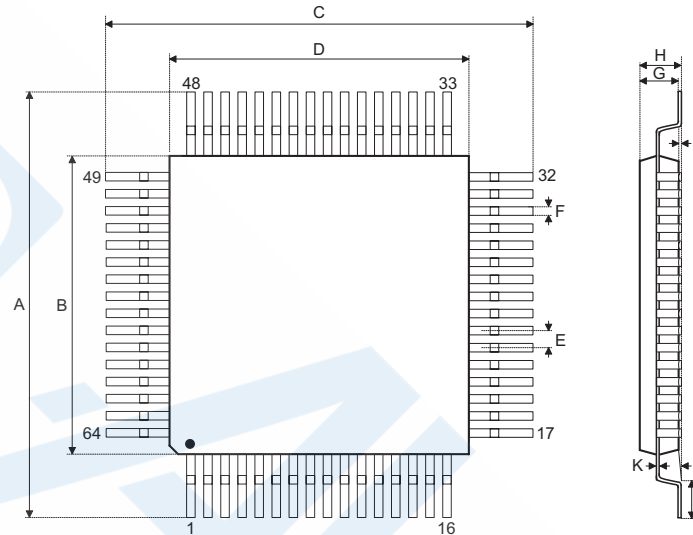
## 100-pin LQFP (14 mm × 14 mm) Outline Dimensions



| Symbol | Dimensions in inch |           |       |
|--------|--------------------|-----------|-------|
|        | Min.               | Nom.      | Max.  |
| A      | —                  | 0.630 BSC | —     |
| B      | —                  | 0.551 BSC | —     |
| C      | —                  | 0.630 BSC | —     |
| D      | —                  | 0.551 BSC | —     |
| E      | —                  | 0.020 BSC | —     |
| F      | 0.007              | 0.009     | 0.011 |
| G      | 0.053              | 0.055     | 0.057 |
| H      | —                  | —         | 0.063 |
| I      | 0.002              | —         | 0.006 |
| J      | 0.018              | 0.024     | 0.030 |
| K      | 0.004              | —         | 0.008 |
| α      | 0°                 | —         | 7°    |

| Symbol | Dimensions in mm |           |      |
|--------|------------------|-----------|------|
|        | Min.             | Nom.      | Max. |
| A      | —                | 16.00 BSC | —    |
| B      | —                | 14.00 BSC | —    |
| C      | —                | 16.00 BSC | —    |
| D      | —                | 14.00 BSC | —    |
| E      | —                | 0.50 BSC  | —    |
| F      | 0.17             | 0.22      | 0.27 |
| G      | 1.35             | 1.40      | 1.45 |
| H      | —                | —         | 1.60 |
| I      | 0.05             | —         | 0.15 |
| J      | 0.45             | 0.60      | 0.75 |
| K      | 0.09             | —         | 0.20 |
| α      | 0°               | —         | 7°   |

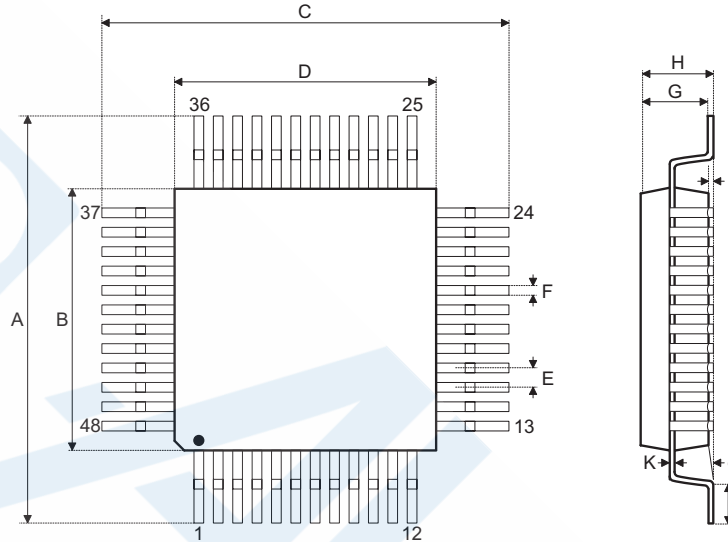
## 64-pin LQFP (10 mm × 10 mm) Outline Dimensions



| Symbol | Dimensions in inch |           |       |
|--------|--------------------|-----------|-------|
|        | Min.               | Nom.      | Max.  |
| A      | —                  | 0.472 BSC | —     |
| B      | —                  | 0.394 BSC | —     |
| C      | —                  | 0.472 BSC | —     |
| D      | —                  | 0.394 BSC | —     |
| E      | —                  | 0.020 BSC | —     |
| F      | 0.007              | 0.009     | 0.011 |
| G      | 0.053              | 0.055     | 0.057 |
| H      | —                  | —         | 0.063 |
| I      | 0.002              | —         | 0.006 |
| J      | 0.018              | 0.024     | 0.030 |
| K      | 0.004              | —         | 0.008 |
| α      | 0°                 | —         | 7°    |

| Symbol | Dimensions in mm |           |      |
|--------|------------------|-----------|------|
|        | Min.             | Nom.      | Max. |
| A      | —                | 12.00 BSC | —    |
| B      | —                | 10.00 BSC | —    |
| C      | —                | 12.00 BSC | —    |
| D      | —                | 10.00 BSC | —    |
| E      | —                | 0.50 BSC  | —    |
| F      | 0.17             | 0.22      | 0.27 |
| G      | 1.35             | 1.40      | 1.45 |
| H      | —                | —         | 1.60 |
| I      | 0.05             | —         | 0.15 |
| J      | 0.45             | 0.60      | 0.75 |
| K      | 0.09             | —         | 0.20 |
| α      | 0°               | —         | 7°   |

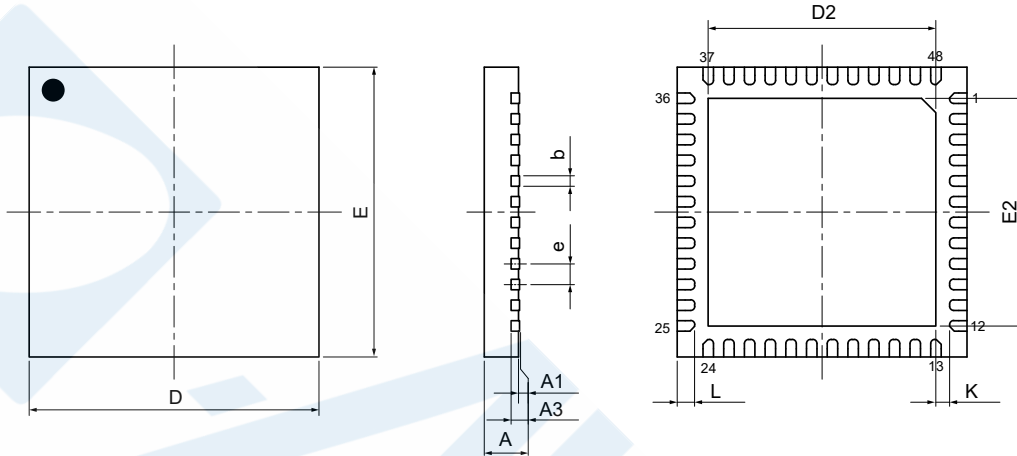
### 48-pin LQFP (7 mm × 7 mm) Outline Dimensions



| Symbol | Dimensions in inch |           |       |
|--------|--------------------|-----------|-------|
|        | Min.               | Nom.      | Max.  |
| A      | —                  | 0.354 BSC | —     |
| B      | —                  | 0.276 BSC | —     |
| C      | —                  | 0.354 BSC | —     |
| D      | —                  | 0.276 BSC | —     |
| E      | —                  | 0.020 BSC | —     |
| F      | 0.007              | 0.009     | 0.011 |
| G      | 0.053              | 0.055     | 0.057 |
| H      | —                  | —         | 0.063 |
| I      | 0.002              | —         | 0.006 |
| J      | 0.018              | 0.024     | 0.030 |
| K      | 0.004              | —         | 0.008 |
| α      | 0°                 | —         | 7°    |

| Symbol | Dimensions in mm |          |      |
|--------|------------------|----------|------|
|        | Min.             | Nom.     | Max. |
| A      | —                | 9.00 BSC | —    |
| B      | —                | 7.00 BSC | —    |
| C      | —                | 9.00 BSC | —    |
| D      | —                | 7.00 BSC | —    |
| E      | —                | 0.50 BSC | —    |
| F      | 0.17             | 0.22     | 0.27 |
| G      | 1.35             | 1.40     | 1.45 |
| H      | —                | —        | 1.60 |
| I      | 0.05             | —        | 0.15 |
| J      | 0.45             | 0.60     | 0.75 |
| K      | 0.09             | —        | 0.20 |
| α      | 0°               | —        | 7°   |

## SAW Type 48-pin QFN (6 mm × 6 mm × 0.85 mm) Outline Dimensions



| Symbol | Dimensions in inch |           |       |
|--------|--------------------|-----------|-------|
|        | Min.               | Nom.      | Max.  |
| A      | 0.031              | 0.033     | 0.035 |
| A1     | 0.000              | 0.001     | 0.002 |
| A3     | —                  | 0.008 REF | —     |
| b      | 0.006              | 0.008     | 0.010 |
| D      | —                  | 0.236 BSC | —     |
| E      | —                  | 0.236 BSC | —     |
| e      | —                  | 0.016 BSC | —     |
| D2     | 0.173              | —         | 0.181 |
| E2     | 0.173              | —         | 0.181 |
| L      | 0.014              | 0.016     | 0.018 |
| K      | 0.008              | —         | —     |

| Symbol | Dimensions in mm |           |      |
|--------|------------------|-----------|------|
|        | Min.             | Nom.      | Max. |
| A      | 0.80             | 0.85      | 0.90 |
| A1     | 0.00             | 0.02      | 0.05 |
| A3     | —                | 0.203 REF | —    |
| b      | 0.15             | 0.20      | 0.25 |
| D      | —                | 6.00 BSC  | —    |
| E      | —                | 6.00 BSC  | —    |
| e      | —                | 0.40 BSC  | —    |
| D2     | 4.40             | —         | 4.60 |
| E2     | 4.40             | —         | 4.60 |
| L      | 0.35             | 0.40      | 0.45 |
| K      | 0.20             | —         | —    |

## Package Thermal Characteristics

| Symbol        | Parameter   | Value | Unit |
|---------------|---|-------|------|
| $\Theta_{JA}$ | Thermal Resistance Junction-Ambient<br>100LQFP – 14 mm × 14 mm / 0.5 mm pitch | 61.2  | °C/W |
|               | Thermal Resistance Junction-Ambient<br>64LQFP – 10 mm × 10 mm / 0.5 mm pitch  | 64.6  |      |
|               | Thermal Resistance Junction-Ambient<br>48LQFP – 7 mm × 7 mm / 0.5 mm pitch    | 68.8  |      |
|               | Thermal Resistance Junction-Ambient<br>48QFN – 6 mm × 6 mm / 0.4 mm pitch     | 30.2  |      |



Singel 3 | B-2550 Kontich | Belgium | Tel. +32 (0)3 458 30 33  
info@alcom.be | www.alcom.be  
Rivium 1e straat 52 | 2909 LE Capelle aan den IJssel | The Netherlands  
Tel. +31 (0)10 288 25 00 | info@alcom.nl | www.alcom.nl

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